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**PRELIMINARY**

**CYW4373E**

## Single-Chip Dual Band WiFi IEEE 802.11ac a/b/g/n MAC/ Baseband/Radio with Bluetooth 5.0 for Industrial Applications

CYW4373E single-chip device provides the highest level of integration for Industrial IoT wireless systems with integrated single-stream IEEE 802.11a/b/g/n/ac MAC/baseband/radio and Bluetooth 5.0 (Basic Rate, Enhanced Data Rate and Bluetooth Low Energy).

CYW4373E supports all rates specified in the IEEE 802.11 a/b/g/n/ac specifications. IEEE 802.11ac's 256 QAM is supported for MCS8 in 20 MHz channels and MCS8/MCS9 in 40 MHz & 80 MHz channels to enable data rates of up to 433.3 Mbps. Included on-chip are 2.4 GHz and 5 GHz power amplifiers and low-noise amplifiers. Optional external PAs and LNAs are also supported.

The CYW4373E brings the latest mobile connectivity technology for Industrial applications. It also offers Industrial/Extended (–40°C to +85°C) temperature performance.

The WLAN section supports the following host interface options: an SDIO v3.0 interface that can operate in 4b or 1b mode, PCIe Gen1 (3.0 compliant) interface, or USB2.0 hub interface which provides a shared single USB connection to both WLAN and Bluetooth target devices. When WLAN is operating in either SDIO or PCIe modes, the Bluetooth section supports a high-speed 4-wire UART interface. An on-chip USB 2.0 hub provides a shared single USB connection to both WLAN and Bluetooth target devices. In addition, coexistence support for external radios (such as ZigBee) is provided via an external interface.

The CYW4373E implements highly sophisticated enhanced collaborative coexistence hardware mechanisms and algorithms, which ensure that WLAN and Bluetooth collaboration is optimized for maximum performance. In addition, coexistence support for external radios (such as LTE cellular) is provided via an external interface.

### Features

#### IEEE 802.11x Key Features

- IEEE 802.11ac compliant.
- Support for MCS8 VHT20 in 20 MHz channels for up to 86.7 Mbps data.
- Single-stream spatial multiplexing up to 433.3 Mbps data rate.
- Supports 20, 40, and 80 MHz channels with optional SGI (256 QAM modulation).
- Full IEEE 802.11a/b/g/n legacy compatibility with enhanced performance.
- TX and RX low-density parity check (LDPC) support for improved range and power efficiency.
- On-chip power amplifiers and low-noise amplifiers for both bands.
- Support for optional front-end modules (FEM) with external PAs and LNAs.
- Supports integrated T/R switch for 2.4 GHz band.
- Supports RF front-end architecture with a single dual-band antenna shared between Bluetooth and WLAN for lowest system cost.
- Shared Bluetooth and WLAN receive signal path eliminates the need for an external power splitter while maintaining excellent sensitivity for both Bluetooth and WLAN.
- Supports IEEE 802.15.2 external coexistence interface to optimize bandwidth utilization with other co-located wireless technologies such as ZigBee.

- Supports standard SDIO v3.0 (including DDR50 mode at 50 MHz and SDR104 mode at 208 MHz, 4-bit and 1-bit) interfaces.
- Backward compatible with SDIO v2.0 host interfaces.
- USB 2.0 Hub shared between WLAN and Bluetooth.
- PCIe Gen1 (3.0 compliant) interface.
- Integrated Arm<sup>®</sup> Cortex<sup>®</sup>-R4 processor and with tightly coupled memory for complete WLAN subsystem functionality and minimizing the need to wake-up the applications processor for standard WLAN functions. This allows for further minimization of power consumption, while maintaining the ability to field upgrade with future features. On-chip memory for WLAN core includes 896 KB RAM and 896 KB ROM.
- Integrated Arm Cortex M3 processor that runs software from the Link Control (LC) to the Host Controller Interface (HCI) layer for Bluetooth. The Arm core is paired with a memory unit that contains 1088 KB of ROM and 384 KB of RAM.

#### Bluetooth Key Features

- Qualified for Bluetooth Core Specification 5.0 with all Bluetooth 4.2 optional features
  - QDID: [102901](#)
  - Declaration ID: [D035922](#)
- Bluetooth Class 1 or Class 2 transmitter operation.
- Supports extended synchronous connections (eSCO), for enhanced voice quality by allowing for retransmission of dropped packets.

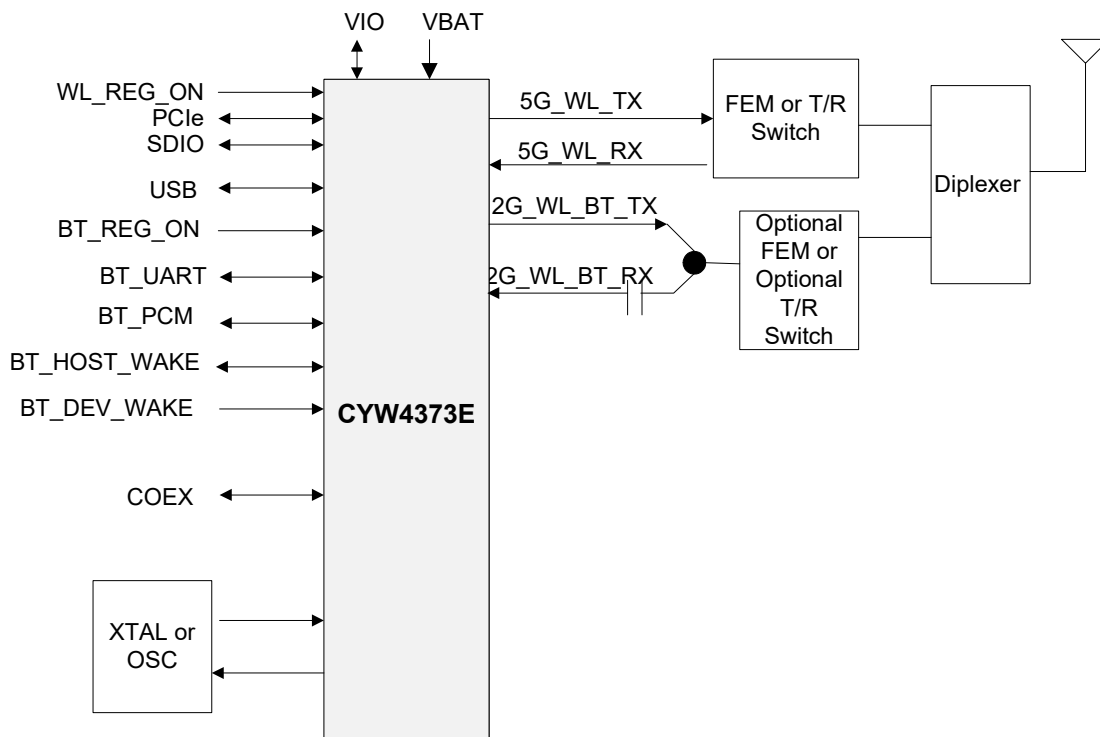
- Adaptive frequency hopping (AFH) for reducing radio frequency interference.
- Interface support, host controller interface (HCI) using a high-speed UART interface and PCM for audio data.
- Low power consumption improves battery life of IoT and embedded devices.
- Supports multiple simultaneous Advanced Audio Distribution Profiles (A2DP) for stereo sound.
- Automatic frequency detection for standard crystal and TCXO values.

**General Features**

- Supports battery voltage range from 3.2 V to 4.8 V supplies with internal switching regulator.

- Programmable dynamic power management
- 6 Kbit OTP for storing board parameters.
- GPIOs: 10.
- 128-ball WLBGA package (4.51 mm × 5.43 mm, 0.4 mm pitch).
- Security:
  - WPA, WPA2 (Personal), and WPA3 (Personal) support for powerful encryption and authentication.
  - AES and TKIP in hardware for faster data encryption and IEEE 802.11i compatibility.
  - Reference WLAN subsystem provides Wi-Fi Protected Setup (WPS).
- Worldwide regulatory support: Global products supported with worldwide homologated design.

**Figure 1. Functional Block Diagram**



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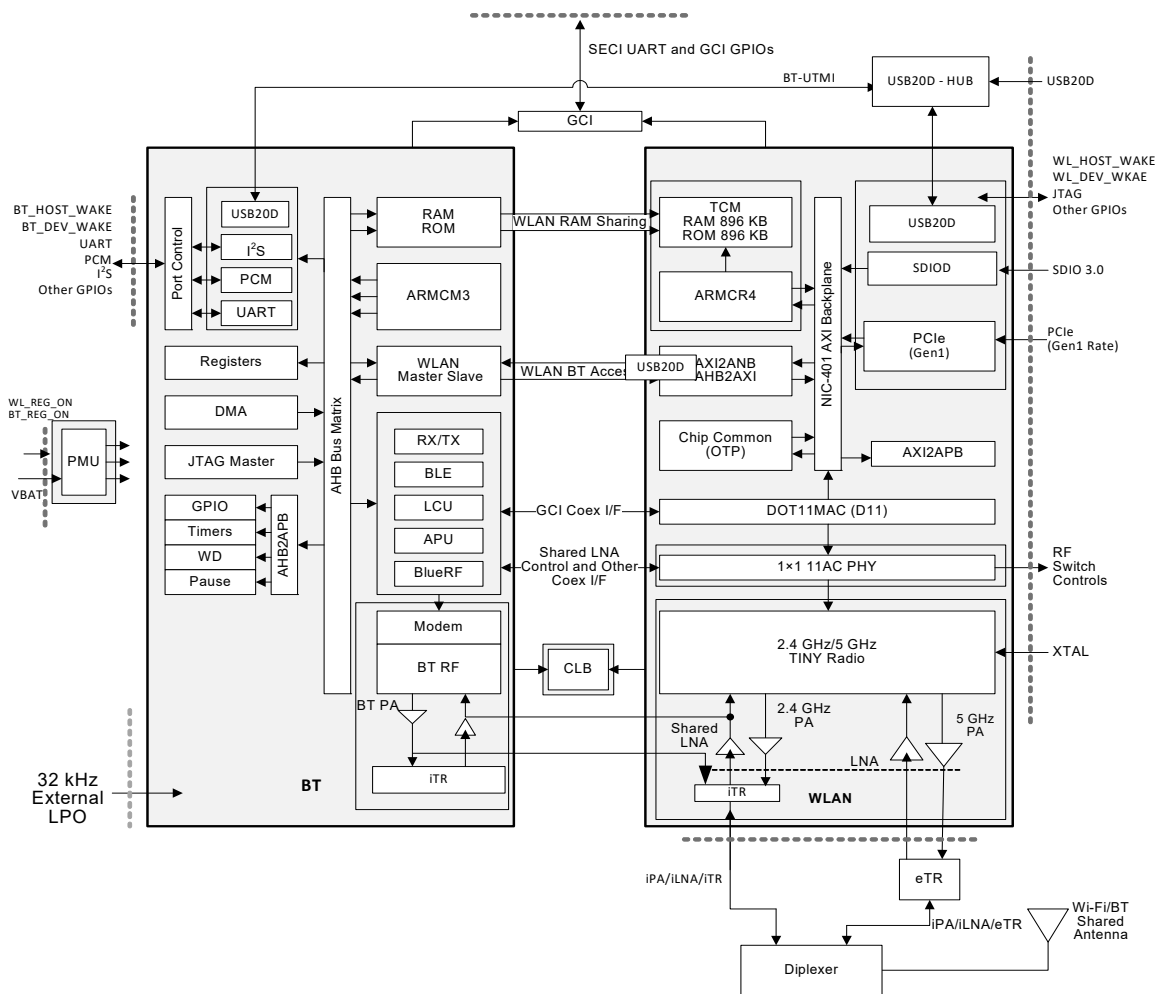
# 1. CYW4373E Overview

## 1.1 Overview

The Cypress CYW4373E single-chip device provides the highest level of integration for an Industrial Connectivity wireless system, with integrated IEEE 802.11 a/b/g/n/ac MAC/baseband radio and Bluetooth 5.0. It provides a small form-factor solution with minimal external components to provide flexibility in size, form, and function. Comprehensive power management circuitry and software ensure the system can meet the needs of highly mobile devices that require minimal power consumption and reliable operation.

Figure 2 shows interconnect of all the major physical blocks in the CYW4373E and their associated external interfaces, which are described in greater detail in the following sections.

Figure 2. CYW4373E Block Diagram



## 1.2 Standards Compliance

The CYW4373E supports the following standards:

- Bluetooth
  - Bluetooth 2.1 + EDR
  - Bluetooth 3.0
  - Bluetooth 4.2 Bluetooth Low Energy
  - Bluetooth 5.0
- IEEE 802.11 WLAN
  - IEEE 802.11ac Enhancements for Very High Throughput for Operation in Bands below 6 GHz
  - IEEE 802.11n Enhancements for Higher Throughput
  - IEEE 802.11a High-speed Physical Layer in the 5 GHz Band
  - IEEE 802.11b Higher-Speed Physical Layer Extension in the 2.4 GHz Band
  - IEEE 802.11g Further Higher Data Rate Extension in the 2.4 GHz Band
  - IEEE 802.11d Specification for operation in additional regulatory domains
  - IEEE 802.11r Fast Basic Service Set (BSS) Transition
  - IEEE 802.11w Protected Management Frames
  - IEEE 802.11e Medium Access Control (MAC) Quality of Service Enhancements
  - IEEE 802.11h Spectrum and Transmit Power Management Extensions in the 5 GHz band
  - IEEE 802.11i Medium Access Control (MAC) Security Enhancements
  - IEEE 802.11k Radio Resource Measurement of Wireless LANs
- IEEE 802.15.2 Coexistence Compliance (on-silicon solution compliant with IEEE 3-wire requirements)
- WLAN Security:
  - WEP
  - WPA-Personal
  - WPA2-Personal
  - WPA3-Personal
  - AES (hardware accelerator)
  - TKIP (hardware accelerator)
- Wi-Fi Multimedia:
  - WMM
  - Wi-Fi Multimedia - PowerSave (WMM-PS with U-APSD)
  - WMM-Sequential Access (WMM-SA with PCF)

## 2. Power Supplies and Power Management

### 2.1 Power Supply Topology

One Buck regulator, multiple LDO regulators, and a power management unit (PMU) are integrated into the CYW4373E. All regulators are programmable via the PMU. These blocks simplify power supply design for Bluetooth, and WLAN functions in embedded designs.

A single VBAT (3.2 up to 4.8V DC max.) and VIO supply (1.8V to 3.3V) can be used, with all additional voltages being provided by the regulators in the CYW4373E.

**Note:** RF performance in this datasheet is guaranteed for VBAT = 3.6~4.8V at room temperature.

Two control signals, BT\_REG\_ON and WL\_REG\_ON, are used to power-up the regulators and take the respective section out of reset. The CBUCK CLDO and LNLDO power-up when any of the reset signals are de-asserted. All regulators are powered down only when both BT\_REG\_ON and WL\_REG\_ON are de-asserted. The CLDO and LNLDO may be turned off/on based on the dynamic demands of the digital baseband.

The CYW4373E allows for an extremely low power-consumption mode by completely shutting down the CBUCK, CLDO, and LNLDO regulators. When in this state, the LPLDO1 (which is the low-power linear regulator that is supplied by the system VIO supply) provides the CYW4373E with all required voltage, further reducing leakage currents.

### 2.2 CYW4373E PMU Features

- VBAT to 1.35Vout (170 mA nominal, 600 mA maximum) Core-Buck (CBUCK) switching regulator
- VBAT to 3.3Vout (200 mA nominal, 450 mA–850 mA maximum) LDO3P3
- VBAT to 2.5Vout (15 mA nominal, 70 mA maximum) BTLDO2P5
- 1.35V to 1.2Vout (50 mA nominal, 150 mA maximum) LNLDO
- 1.35V to 1.2Vout (80 mA nominal, 200 mA maximum) CLDO with bypass mode for deep-sleep
- 1.35V to 1.2Vout (35 mA nominal, 55 mA maximum) HLDO
- Additional internal LDOs (not externally accessible)
- PMU internal timer auto-calibration by the crystal clock for precise wake-up timing from extremely low power-consumption mode.

Figure 3 and Figure 4 show the regulators and a typical power topology.



Figure 3. Typical Power Topology (Page 1 of 2)

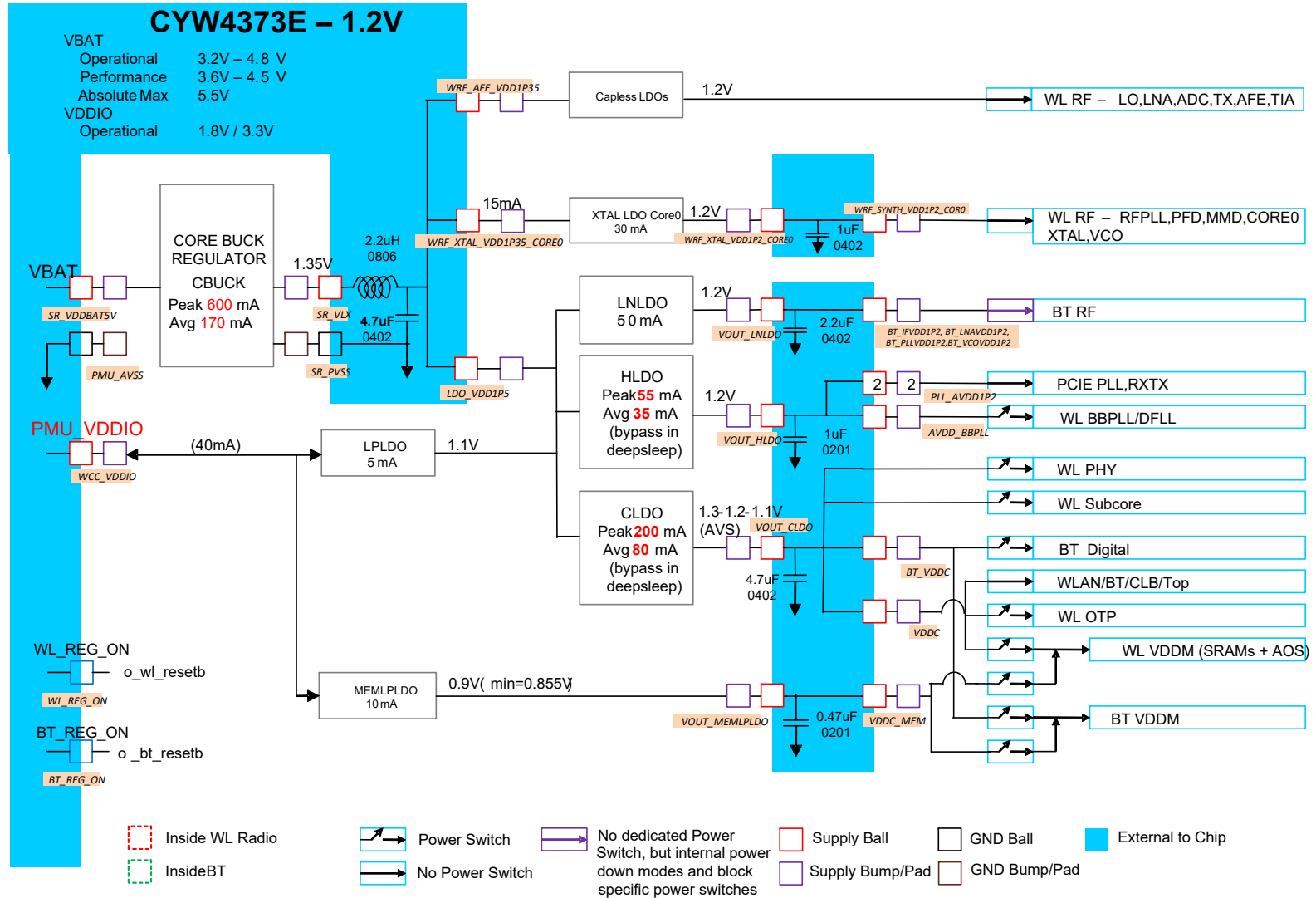
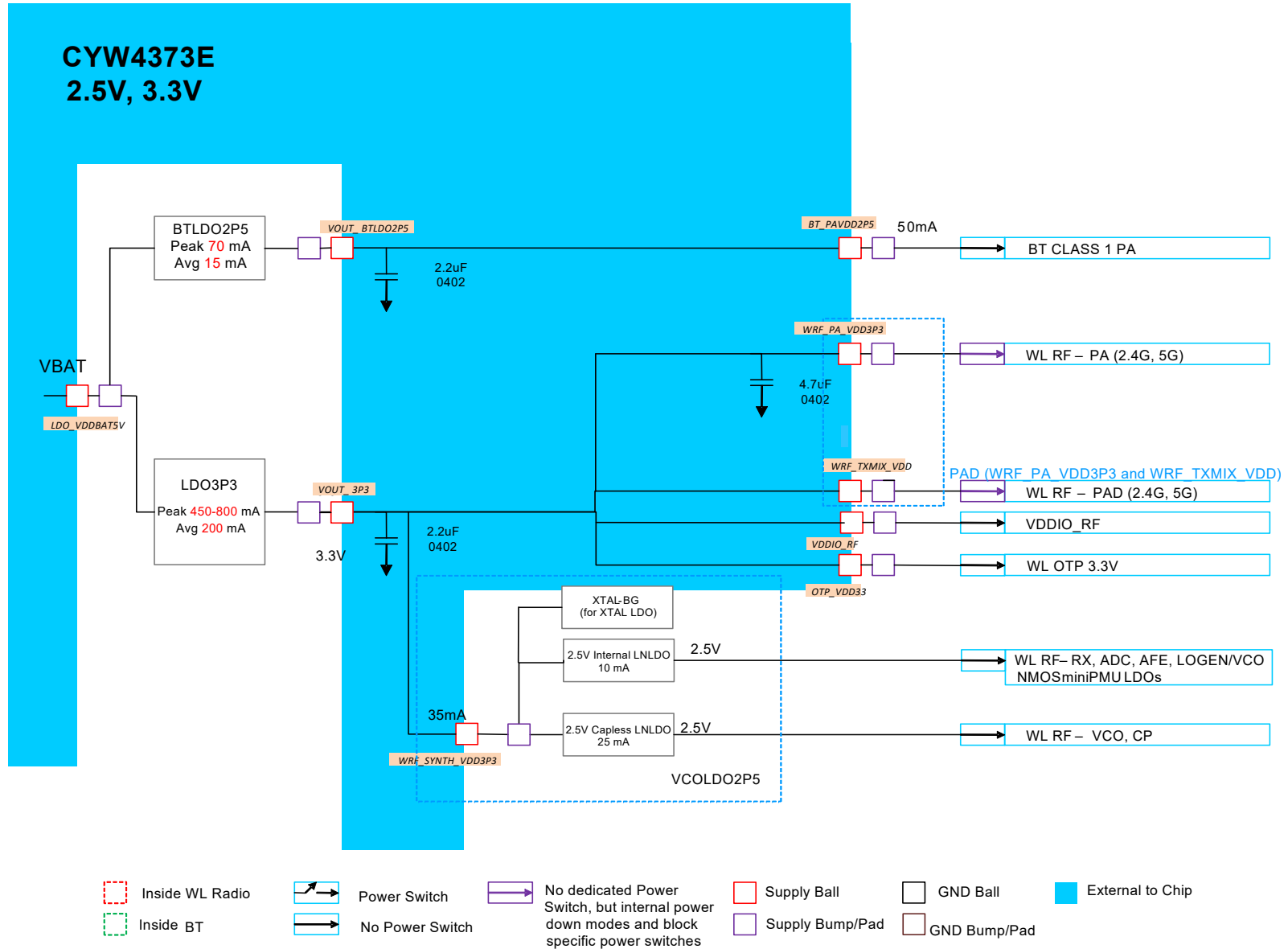


Figure 4. Typical Power Topology (Page 2 of 2)



### 2.3 WLAN Power Management

The CYW4373E has been designed with the stringent Power consumption requirements of Industrial IoT devices in mind. All areas of the chip design are optimized to minimize power consumption. Silicon processes and cell libraries were chosen to reduce leakage current and supply voltages. Additionally, the CYW4373E integrated RAM is a high Vt memory with dynamic clock control. The dominant supply current consumed by the RAM is leakage current only. Additionally, the CYW4373E includes an advanced WLAN power management unit (PMU) sequencer. The PMU sequencer provides significant power savings by putting the CYW4373E into various power management states appropriate to the current environment and activities that are being performed. The power management unit enables and disables internal regulators, switches, and other blocks based on a computation of the required resources and a table that describes the relationship between resources and the time needed to enable and disable them. Power-up sequences are fully programmable. Configurable, free-running counters (running at 32.768 kHz LPO clock) in the PMU sequencer are used to turn on/turn off individual regulators and power switches. Clock speeds are dynamically changed (or gated altogether) for the current mode. Slower clock speeds are used wherever possible.

The CYW4373E WLAN power states are described as follows:

- **Active mode**—All WLAN blocks in the CYW4373E are powered up and fully functional with active carrier sensing and frame transmission and receiving. All required regulators are enabled and put in the most efficient mode based on the load current. Clock speeds are dynamically adjusted by the PMU sequencer.
- **Doze mode**—The radio, analog domains, and most of the linear regulators are powered down. The rest of the CYW4373E remains powered up in an IDLE state. All main clocks (PLL, crystal oscillator or TCXO) are shut down to reduce active power to the minimum. The 32.768 kHz LPO clock is available only for the PMU sequencer. This condition is necessary to allow the PMU sequencer to wake-up the chip and transition to Active mode. In Doze mode, the primary power consumed is due to leakage current.
- **Deep sleep mode**—Most of the chip including both analog and digital domains and most of the regulators are powered off. Logic states in the digital core are saved and preserved into a retention memory in the always-ON domain before the digital core is powered off. Upon a wake-up event triggered by the PMU timers, an external interrupt or host resume through the PCIe bus, logic states in the digital core are restored to the pre-deep sleep settings to avoid lengthy HW re-initialization.
- **Power-down mode**—The CYW4373E is effectively powered off by shutting down all internal regulators. The chip is brought out of this mode by external logic re-enabling the internal regulators.

## 2.4 PMU Sequencing

The PMU sequencer is used to minimize system power consumption. It enables and disables various system resources based on a computation of required resources and a table that describes the relationship between resources and the time required to enable and disable them.

Resource requests may derive from several sources: clock requests from cores, the minimum resources defined in the *ResourceMin* register, and the resources requested by any active resource request timers. The PMU sequencer maps clock requests into a set of resources required to produce the requested clocks.

Each resource is in one of four states:

- enabled
- disabled
- transition\_on
- transition\_off

The timer contains 0 when the resource is enabled or disabled and a non-zero value in the transition states. The timer is loaded with the time\_on or time\_off value of the resource when the PMU determines that the resource must be enabled or disabled. That timer decrements on each 32.768 kHz PMU clock. When it reaches 0, the state changes from transition\_off to disabled or transition\_on to enabled. If the time\_on value is 0, the resource can transition immediately from disabled to enabled. Similarly, a time\_off value of 0 indicates that the resource can transition immediately from enabled to disabled. The terms *enable sequence* and *disable sequence* refer to either the immediate transition or the timer load-decrement sequence.

During each clock cycle, the PMU sequencer performs the following actions:

- Computes the required resource set based on requests and the resource dependency table.
- Decrements all timers whose values are non zero. If a timer reaches 0, the PMU clears the ResourcePending bit for the resource and inverts the ResourceState bit.
- Compares the request with the current resource status and determines which resources must be enabled or disabled.
- Initiates a disable sequence for each resource that is enabled, no longer being requested, and has no powered up dependents.
- Initiates an enable sequence for each resource that is disabled, is being requested, and has all of its dependencies enabled.

## 2.5 Power-Off Shutdown

The CYW4373E provides a low-power shutdown feature that allows the device to be turned off while the host, and any other devices in the system, remain operational. When the CYW4373E is not needed in the system, VDDIO\_RF and VDDC are shut down while VDDIO remains powered. This allows the CYW4373E to be effectively off while keeping the I/O pins powered so that they do not draw extra current from any other devices connected to the I/O.

During a low-power shutdown state, provided VDDIO remains applied to the CYW4373E, all outputs are tristate, and most inputs signals are disabled. Input voltages must remain within the limits defined for normal operation. This is done to prevent current paths or create loading on any digital signals in the system, and enables the CYW4373E to be fully integrated in an embedded device and take full advantage of the lowest power-savings modes.

When the CYW4373E is powered on from this state, it is the same as a normal power-up and the device does not retain any information about its state from before it was powered down.

## 2.6 Power-Up/Power-Down/Reset Circuits

The CYW4373E has two signals (see [Table 1](#)) that enable or disable the Bluetooth and WLAN circuits and the internal regulator blocks, allowing the host to control power consumption. For timing diagrams of these signals and the required power-up sequences, see [Section 20. "Power-Up Sequence and Timing"](#).

**Table 1. Power-Up/Power-Down/Reset Control Signals**

| Signal    | Description  |
|-----------|--|
| WL_REG_ON | This signal is used by the PMU (with BT_REG_ON) to power-up the WLAN section. It is also OR-gated with the BT_REG_ON input to control the internal CYW4373E regulators. When this pin is high, the regulators are enabled and the WLAN section is out of reset. When this pin is low, the WLAN section is in reset. If BT_REG_ON and WL_REG_ON are both low, the regulators are disabled. This pin has an internal 200 kΩ pull-down resistor that is enabled by default. It can be disabled through programming. |
| BT_REG_ON | This signal is used by the PMU (with WL_REG_ON) to decide whether or not to power down the internal CYW4373E regulators. If BT_REG_ON and WL_REG_ON are low, the regulators will be disabled. This pin has an internal 200 kΩ pull-down resistor that is enabled by default. It can be disabled through programming.   |

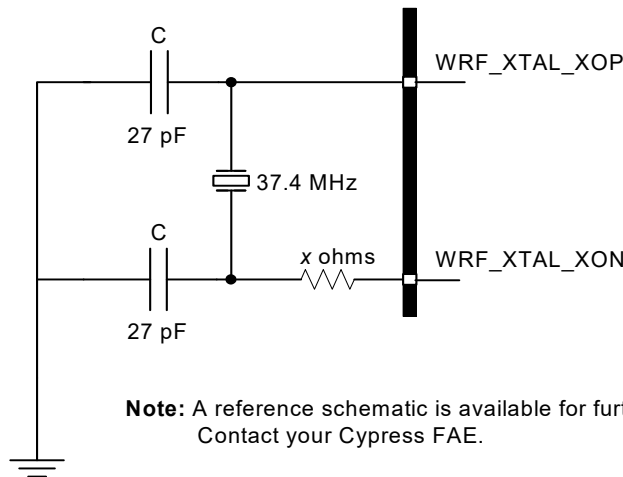
### 3. Frequency References

An external crystal is used for generating all radio frequencies and normal operation clocking. As an alternative, an external frequency reference may be used. In addition, a low-power oscillator (LPO) is provided for lower power mode timing.

#### 3.1 Crystal Interface and Clock Generation

The CYW4373E can use an external crystal to provide a frequency reference. The recommended configuration for the crystal oscillator including all external components is shown in [Figure 5](#). Consult the reference schematics for the latest configuration.

**Figure 5. Recommended Oscillator Configuration**



A fractional-N synthesizer in the CYW4373E generates the radio frequencies, clocks, and data/packet timing, enabling it to operate using a wide selection of frequency references.

The recommended default frequency reference is a 37.4 MHz crystal. The signal characteristics for the crystal interface are listed in [Table 2](#).

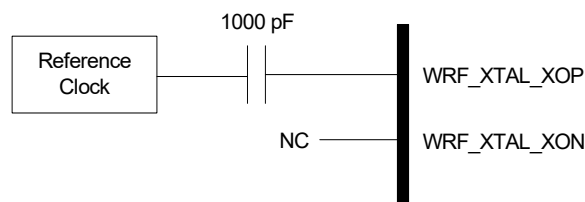
**Note:** Although the fractional-N synthesizer can support alternative reference frequencies, frequencies other than the default require support to be added in the driver, plus additional extensive system testing. Contact Cypress for further details.

#### 3.2 External Frequency Reference

As an alternative to a crystal, an external precision frequency reference can be used, provided that it meets the Phase Noise requirements listed in [Table 2](#).

If used, the external clock should be connected to the WRF\_XTAL\_XOP pin through an external 1000 pF coupling capacitor, as shown in [Figure 6](#). The internal clock buffer connected to this pin will be turned OFF when the CYW4373E goes into sleep mode. When the clock buffer turns ON and OFF there will be a small impedance variation. Power must be supplied to the WRF\_XTAL\_VDD1P35 pin.

**Figure 6. Recommended Circuit to Use With an External Reference Clock**



**Table 2. Crystal Oscillator and External Clock—Requirements and Performance**

| Parameter  | Conditions/Notes  | Crystal <sup>[1]</sup> |      |     | External Frequency Reference <sup>[2]</sup> |      |      | Unit              |
|--|---|------------------------|------|-----|---|------|------|-------------------|
|  |   | Min                    | Typ  | Max | Min   | Typ  | Max  |                   |
| Frequency  | SDIO 3.0, and PCIe WLAN interfaces                          | –                      | 37.4 | –   | –   | 37.4 | –    | MHz               |
| Frequency tolerance over the lifetime of the equipment, including temperature <sup>[3]</sup> | Without trimming  | –20                    | –    | 20  | –20   | –    | 20   | ppm               |
| Crystal load capacitance   | –   | –                      | 16   | –   | –   | –    | –    | pF                |
| ESR  | –   | –                      | –    | 60  | –   | –    | –    | Ω                 |
| Drive level  | External crystal must be able to tolerate this drive level. | 200                    | –    | –   | –   | –    | –    | μW                |
| Input impedance (WRF_XTAL_XOP)   | Resistive   | –                      | –    | –   | 30k   | 100k | –    | Ω                 |
|  | Capacitive  | –                      | –    | 7.5 | –   | –    | 7.5  | pF                |
| WRF_XTAL_XOP Input low level   | DC-coupled digital signal                                   | –                      | –    | –   | 0   | –    | 0.2  | V                 |
| WRF_XTAL_XOP Input high level  | DC-coupled digital signal                                   | –                      | –    | –   | 1.0   | –    | 1.26 | V                 |
| WRF_XTAL_XOP input voltage(see Figure 6)   | IEEE 802.11a/b/g operation only                             | –                      | –    | –   | 400   | –    | 1200 | mV <sub>p-p</sub> |
| WRF_XTAL_XOP input voltage(see Figure 6)   | IEEE 802.11n/ac AC-coupled analog input                     | –                      | –    | –   | 1   | –    | –    | V <sub>p-p</sub>  |
| Duty cycle   | 37.4 MHz clock  | –                      | –    | –   | 40  | 50   | 60   | %                 |
| Phase Noise <sup>[4]</sup> (IEEE 802.11b/g)  | 37.4 MHz clock at 10 kHz offset                             | –                      | –    | –   | –   | –    | –129 | dBc/Hz            |
|  | 37.4 MHz clock at 100 kHz offset                            | –                      | –    | –   | –   | –    | –136 | dBc/Hz            |
| Phase Noise <sup>[4]</sup> (IEEE 802.11a)  | 37.4 MHz clock at 10 kHz offset                             | –                      | –    | –   | –   | –    | –137 | dBc/Hz            |
|  | 37.4 MHz clock at 100 kHz offset                            | –                      | –    | –   | –   | –    | –144 | dBc/Hz            |
| Phase Noise <sup>[4]</sup> (IEEE 802.11n, 2.4 GHz)   | 37.4 MHz clock at 10 kHz offset                             | –                      | –    | –   | –   | –    | –134 | dBc/Hz            |
|  | 37.4 MHz clock at 100 kHz offset                            | –                      | –    | –   | –   | –    | –141 | dBc/Hz            |
| Phase Noise <sup>[4]</sup> (IEEE 802.11n, 5 GHz)   | 37.4 MHz clock at 10 kHz offset                             | –                      | –    | –   | –   | –    | –142 | dBc/Hz            |
|  | 37.4 MHz clock at 100 kHz offset                            | –                      | –    | –   | –   | –    | –149 | dBc/Hz            |
| Phase Noise <sup>[4]</sup> (IEEE 802.11ac, 5 GHz)  | 37.4 MHz clock at 10 kHz offset                             | –                      | –    | –   | –   | –    | –148 | dBc/Hz            |
|  | 37.4 MHz clock at 100 kHz offset                            | –                      | –    | –   | –   | –    | –155 | dBc/Hz            |

**Notes**

1. (Crystal) Use WRF\_XTAL\_XON and WRF\_XTAL\_XOP.
2. See “External Frequency Reference” for alternative connection methods.
3. It is the responsibility of the equipment designer to select oscillator components that comply with these specifications.
4. Assumes that external clock has a flat phase noise response above 100 kHz.

### 3.3 External 32.768 kHz Low-Power Oscillator

The CYW4373E requires an external low-frequency clock for low-power mode timing. An external 32.768kHz precision oscillator which meets the requirements listed in [Table 3](#) must be used.

**Table 3. External 32.768 kHz Sleep Clock Specifications**

| Parameter                              | LPO Clock                | Unit    |
|--|--------------------------|---------|
| Nominal input frequency                | 32.768                   | kHz     |
| Frequency accuracy                     | ±200                     | ppm     |
| Duty cycle                             | 30–70                    | %       |
| Input signal amplitude                 | 200–3300                 | mV, p-p |
| Signal type                            | Square-wave or sine-wave | –       |
| Input impedance <sup>[5]</sup>         | >100k<br><5              | Ω<br>pF |
| Clock jitter (during initial start-up) | <10,000                  | ppm     |

**Note**

5. When power is applied or switched off.



## 4. Bluetooth Overview

The CYW4373E is a Bluetooth 5.0 compliant, baseband processor with 2.4 GHz transceiver. It features the highest level of integration and eliminates all critical external components, thus minimizing the footprint, power consumption, and system cost of a Bluetooth radio solution.

The CYW4373 is the optimal solution for any Bluetooth voice and/or data application. The Bluetooth subsystem presents a standard host controller interface (HCI) via a high-speed UART or shared USB 2.0 and I2S/PCM for audio. The CYW4373E incorporates all Bluetooth 5.0 features including secure simple pairing, sniff subrating, and encryption pause and resume.

The CYW4373E Bluetooth radio transceiver provides enhanced radio performance to meet the most stringent temperature applications and the tightest integration into IoT and embedded applications. It provides full radio compatibility to operate simultaneously with GPS, WLAN, and cellular radios.

The Bluetooth transmitter also features a Class 1 power amplifier with Class 2 capability.

### 4.1 Features

Primary CYW4373E Bluetooth features include:

- Bluetooth 5.0 qualified with all errata (applicable to v4.2 and earlier) fixed as well as all support for all optional Bluetooth 4.2 features
- Fully supports Bluetooth Core Specification version 5.0 + EDR features:
  - Adaptive frequency hopping (AFH)
  - Quality of service (QoS)
  - Extended synchronous connections (eSCO)—voice connections
  - Fast connect (interlaced page and inquiry scans)
  - Secure simple pairing (SSP)
  - Sniff subrating (SSR)
  - Encryption pause resume (EPR)
  - Extended inquiry response (EIR)
  - Link supervision timeout (LST)
- UART baud rates up to 4 Mbps
- Supports all Bluetooth 5.0 + HS packet types
- Supports maximum Bluetooth data rates over HCI UART
- Multipoint operation with up to seven active slaves
  - Maximum of seven simultaneous active ACL links
  - Maximum of three simultaneous active SCO and eSCO connections with scatternet support
- Trigger Cypress fast connect (TCFC)
- Narrow band and wide band packet loss concealment
- Scatternet operation with up to four active piconets with background scan and support for scatter mode
- High-speed HCI UART transport support with low-power out-of-band BT\_DEV\_WAKE and BT\_HOST\_WAKE signaling (see [“Host Controller Power Management”](#))
- Channel quality driven data rate and packet type selection
- Standard Bluetooth test modes
- Extended radio and production test mode features
- Full support for power savings modes
  - Bluetooth clock request
  - Bluetooth standard sniff
  - Deep-sleep modes and software regulator shutdown
- Supports a low-power crystal, which can be used during power save mode for better timing accuracy.
- USB wake up from L2 deep sleep state through LINESTATE of HUB

- Host interface with USB 1.1 with Full Speed data rate
- Host Interface with Shared USB 2.0 with High Speed data rate
- USB 2.0 hub for a shared single USB connection to both Bluetooth and WLAN

## 4.2 Bluetooth Radio

The CYW4373E has an integrated radio transceiver that has been optimized for use in 2.4 GHz Bluetooth wireless systems. It has been designed to provide low-power, low-cost, robust communications for applications operating in the globally available 2.4 GHz unlicensed ISM band. It is fully compliant with the Bluetooth Radio Specification, EDR specification and Bluetooth Low Energy specification and meets or exceeds the requirements to provide the highest communication link quality of service.

### 4.2.1 Transmit

The CYW4373E features a fully integrated zero-IF transmitter. The baseband transmit data is GFSK-modulated in the modem block and upconverted to the 2.4 GHz ISM band in the transmitter path. The transmitter path consists of signal filtering, I/Q upconversion, output power amplifier, and RF filtering. The transmitter path also incorporates  $\pi/4$ -DQPSK for 2 Mbps and 8-DPSK for 3 Mbps to support EDR. The transmitter section is compatible to the Bluetooth Low Energy specification. The transmitter PA bias can also be adjusted to provide Bluetooth class 1 or class 2 operation.

### 4.2.2 Digital Modulator

The digital modulator performs the data modulation and filtering required for the GFSK,  $\pi/4$ -DQPSK, and 8-DPSK signal. The fully digital modulator minimizes any frequency drift or anomalies in the modulation characteristics of the transmitted signal and is much more stable than direct VCO modulation schemes.

### 4.2.3 Digital Demodulator and Bit Synchronizer

The digital demodulator and bit synchronizer take the low-IF received signal and perform an optimal frequency tracking and bit-synchronization algorithm.

### 4.2.4 Power Amplifier

The fully integrated PA supports Class 1 or Class 2 output using a highly linearized, temperature-compensated design. This provides greater flexibility in front-end matching and filtering. Due to the linear nature of the PA combined with some integrated filtering, external filtering is required to meet the Bluetooth and regulatory harmonic and spurious requirements. For IoT and embedded applications in which Bluetooth is next to the other radios, external filtering can be applied to achieve near thermal noise levels for spurious and radiated noise emissions. The transmitter features a sophisticated on-chip transmit signal strength indicator (TSSI) block to keep the absolute output power variation within a tight range across process, voltage, and temperature.

### 4.2.5 Receiver

The receiver path uses a low-IF scheme to downconvert the received signal for demodulation in the digital demodulator and bit synchronizer. The receiver path provides a high degree of linearity, an extended dynamic range, and high-order on-chip channel filtering to ensure reliable operation in the noisy 2.4 GHz ISM band. The front-end topology with built-in out-of-band attenuation enables the CYW4373E to be used in most applications with minimal off-chip filtering. For IoT and embedded applications, in which the Bluetooth function is integrated close to the other radio transmitters, external filtering is required to eliminate the desensitization of the receiver.

### 4.2.6 Digital Demodulator and Bit Synchronizer

The digital demodulator and bit synchronizer take the low-IF received signal and perform an optimal frequency tracking and bit synchronization algorithm.

### 4.2.7 Receiver Signal Strength Indicator

The radio portion of the CYW4373E provides a receiver signal strength indicator (RSSI) signal to the baseband, so that the controller can take part in a Bluetooth power-controlled link by providing a metric of its own receiver signal strength to determine whether the transmitter should increase or decrease its output power.

#### *4.2.8 Local Oscillator Generation*

A local oscillator (LO) generation provides fast frequency hopping (1600 hops/second) across the 79 maximum available channels. The LO generation subblock employs an architecture for high immunity to LO pulling during PA operation. The CYW4373E uses an internal RF and IF loop filter.

#### *4.2.9 Calibration*

The CYW4373E radio transceiver features an automated calibration scheme that is fully self contained in the radio. No user interaction is required during normal operation or during manufacturing to provide the optimal performance. Calibration optimizes the performance of all the major blocks within the radio to within 2% of optimal conditions, including gain and phase characteristics of filters, matching between key components, and key gain blocks. This takes into account process variation and temperature variation. Calibration occurs transparently during normal operation during the settling time of the hops and calibrates for temperature variations as the device cools and heats during normal operation in its environment.

## 5. Bluetooth Baseband Core

The Bluetooth Baseband Core (BBC) implements all of the time critical functions required for high-performance Bluetooth operation. The BBC manages the buffering, segmentation, and routing of data for all connections. It also buffers data that passes through it, handles data flow control, schedules SCO/ACL TX/RX transactions, monitors Bluetooth slot usage, optimally segments and packages data into baseband packets, manages connection status indicators, and composes and decodes HCI packets. In addition to these functions, it independently handles HCI event types, and HCI command types.

The following transmit and receive functions are also implemented in the BBC hardware to increase reliability and security of the TX/RX data before sending over the air:

- Symbol timing recovery, data deframing, forward error correction (FEC), header error control (HEC), cyclic redundancy check (CRC), data decryption, and data dewatering in the receiver.
- Data framing, FEC generation, HEC generation, CRC generation, key generation, data encryption, and data whitening in the transmitter.

### 5.1 Bluetooth 4.0 Features

The BBC supports all Bluetooth 4.0 features, with the following benefits:

- Dual-mode Bluetooth Low Energy (BT and BLE operation)
- Extended Inquiry Response (EIR): Shortens the time to retrieve the device name, specific profile, and operating mode.
- Encryption Pause Resume (EPR): Enables the use of Bluetooth technology in a much more secure environment.
- Sniff Subrating (SSR): Optimizes power consumption for low duty cycle asymmetric data flow, which subsequently extends battery life.
- Secure Simple Pairing (SSP): Reduces the number of steps for connecting two devices, with minimal or no user interaction required.
- Link Supervision Time Out (LSTO): Additional commands added to HCI and Link Management Protocol (LMP) for improved link time-out supervision.
- QoS enhancements: Changes to data traffic control, which results in better link performance. Audio, human interface device (HID), bulk traffic, SCO, and enhanced SCO (eSCO) are improved with the erroneous data (ED) and packet boundary flag (PBF) enhancements.

### 5.2 Bluetooth 5.0 Features

The BBC supports all Bluetooth 5.0 features, with the following benefits:

- LE Secure Connections to enable secure connection establishment using the Elliptic-Curve Diffie-Hellman algorithm
- LE Privacy 1.2 to enable low-power private address resolution
- LE Data Length Extension to support longer Bluetooth Low Energy packets

**Note:** The CYW4373E is compatible with the Bluetooth Low Energy operating mode, which provides a dramatic reduction in the power consumption of the Bluetooth radio and baseband. The primary application for this mode is to provide support for low data rate devices, such as sensors and remote controls.

### 5.3 Bluetooth Low Energy

The CYW4373E supports the Bluetooth Low Energy operating mode.

## 5.4 Link Control Layer

The link control layer is part of the Bluetooth link control functions that are implemented in dedicated logic in the link control unit (LCU). This layer consists of the command controller that takes commands from the software, and other controllers that are activated or configured by the command controller, to perform the link control tasks. Each task performs a different state in the Bluetooth Link Controller.

- Major states:
  - Standby
  - Connection
- Substates:
  - Page
  - Page Scan
  - Inquiry
  - Inquiry Scan
  - Sniff

## 5.5 Test Mode Support

The CYW4373E fully supports Bluetooth Test mode. This includes the transmitter tests, normal and delayed loopback tests, and reduced hopping sequence.

In addition to the standard Bluetooth Test Mode, the CYW4373E also supports enhanced testing features to simplify RF debugging and qualification and type-approval testing. These features include:

- Fixed frequency carrier wave (unmodulated) transmission
  - Simplifies some type-approval measurements (Japan)
  - Aids in transmitter performance analysis
- Fixed frequency constant receiver mode
  - Receiver output directed to I/O pin
  - Allows for direct BER measurements using standard RF test equipment
  - Facilitates spurious emissions testing for receive mode
- Fixed frequency constant transmission
  - 8-bit fixed pattern or PRBS-9
  - Enables modulated signal measurements with standard RF test equipment

## 5.6 Bluetooth Power Management Unit

The Bluetooth Power Management Unit (PMU) provides power management features that can be invoked by either software through power management registers or packet handling in the baseband core.

The power management functions provided by the CYW4373E are:

- [RF Power Management](#)
- [Host Controller Power Management](#)
- [BBC Power Management](#)

### 5.6.1 RF Power Management

The BBC generates power-down control signals for the transmit path, receive path, PLL, and power amplifier to the 2.4 GHz transceiver. The transceiver then processes the power-down functions accordingly.

### 5.6.2 Host Controller Power Management

When running in UART mode, the CYW4373E may be configured so that dedicated signals are used for power management hand-shaking between the CYW4373E and the host. The basic power saving functions supported by those hand-shaking signals include the standard Bluetooth defined power savings modes and standby modes of operation. [Table 4](#) describes the power-control handshake signals used with the UART interface.

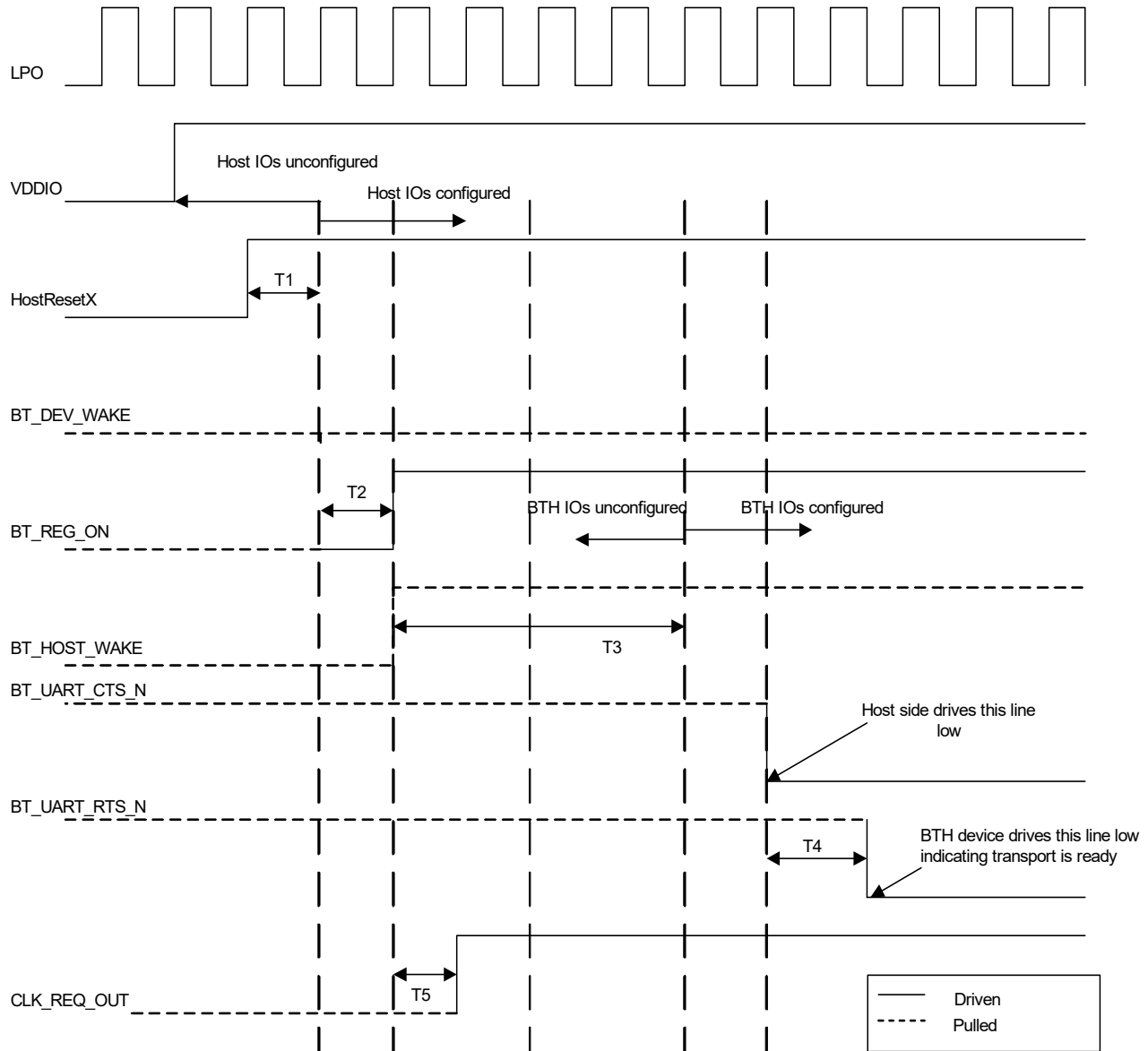
**Note** Pad function Control Register is set to 0 for these pins. See [“DC Characteristics”](#) for more details.

**Table 4. Power Control Pin Description**

| Signal       | Mapped to Pin                    | Type | Description   |
|--------------|----------------------------------|------|---|
| BT_DEV_WAKE  | BT_GPIO_0                        | I    | Bluetooth device wake-up: Signal from the host to the CYW4373E indicating that the host requires attention. <ul style="list-style-type: none"> <li>■ Asserted: The Bluetooth device must wake-up or remain awake.</li> <li>■ Deasserted: The Bluetooth device may sleep when sleep criteria are met.</li> </ul> The polarity of this signal is software configurable and can be asserted high or low. |
| BT_HOST_WAKE | BT_GPIO_1                        | O    | Host wake-up. Signal from the CYW4373E to the host indicating that the CYW4373E requires attention. <ul style="list-style-type: none"> <li>■ Asserted: host device must wake-up or remain awake.</li> <li>■ Deasserted: host device may sleep when sleep criteria are met.</li> </ul> The polarity of this signal is software configurable and can be asserted high or low.                           |
| CLK_REQ      | BT_CLK_REQ_OUT<br>WL_CLK_REQ_OUT | O    | The CYW4373E asserts CLK_REQ when Bluetooth or WLAN wants the host to turn on the reference clock. The CLK_REQ polarity is active-high. Add an external 100 kΩ pull-down resistor to ensure the signal is deasserted when the CYW4373E powers up or resets when VDDIO is present.   |

Figure 7 shows the startup signaling sequence prior to software download.

Figure 7. Startup Signaling Sequence Prior to Software Download



Notes :

- T1 is the time for Host to settle its IOs after a reset.
  - T2 is the time for Host to drive BT\_REG\_ON high after the Host IOs are configured.
  - T3 is the time for BTH (Bluetooth) device to settle its IOs after a reset and reference clock settling time has elapsed.
  - T4 is the time for BTH device to drive BT\_UART\_RTS\_N low after the Host drives BT\_UART\_CTS\_N low. This assumes the BTH device has already completed initialization.
  - T5 is the time for BTH device to drive CLK\_REQ\_OUT high after BT\_REG\_ON goes high. Note this pin is used for designs that use an external reference clock source from the Host. This pin is irrelevant for Crystal reference clock based designs where the BTH device generates its own reference clock from an external crystal connected to its oscillator circuit.
- Timing diagram assumes VBAT is present.

### 5.6.3 BBC Power Management

The following are low-power operations for the BBC:

- Physical layer packet-handling turns the RF on and off dynamically within transmit/receive packets.
- Bluetooth-specified low-power connection modes: sniff, hold, and park. While in these modes, the CYW4373E runs on the low-power oscillator and wakes up after a predefined time period.
- A low-power shutdown feature allows the device to be turned off while the host and any other devices in the system remain operational. When the CYW4373E is not needed in the system, the RF and core supplies are shut down while the I/O remains powered. This allows the CYW4373E to effectively be off while keeping the I/O pins powered so they do not draw extra current from any other devices connected to the I/O.

During the low-power shutdown state, provided VDDIO remains applied to the CYW4373E, all outputs are tristated, and most input signals are disabled. Input voltages must remain within the limits defined for normal operation. This is done to prevent current paths or create loading on any digital signals in the system and enables the CYW4373E to be fully integrated in an embedded device to take full advantage of the lowest power-saving modes.

Two CYW4373E input signals are designed to be high-impedance inputs that do not load the driving signal even if the chip does not have VDDIO power supplied to it: the frequency reference input (WRF\_TCXO\_IN) and the 32.768 kHz input (LPO). When the CYW4373E is powered on from this state, it is the same as a normal power-up, and the device does not contain any information about its state from the time before it was powered down.

### Wideband Speech

The CYW4373E provides support for wideband speech (WBS) using on-chip Cypress SmartAudio® technology. The CYW4373E can perform subband-codec (SBC), as well as mSBC, encoding and decoding of linear 16 bits at 16 kHz (256 Kbps rate) transferred over the PCM bus.

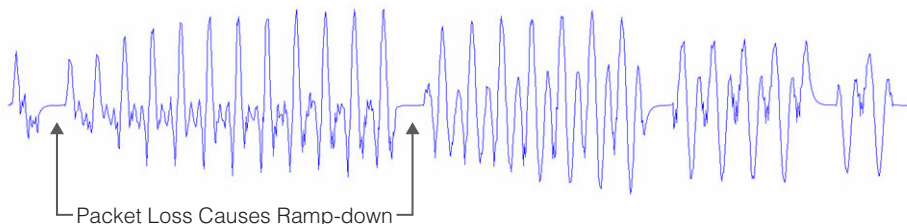
### Packet Loss Concealment

Packet Loss Concealment (PLC) improves apparent audio quality for systems with marginal link performance. Bluetooth messages are sent in packets. When a packet is lost, it creates a gap in the received audio bit-stream. Packet loss can be mitigated in several ways:

- Fill in zeros.
- Ramp down the output audio signal toward zero (this is the method used in current Bluetooth headsets).
- Repeat the last frame (or packet) of the received bit-stream and decode it as usual (frame repeat).

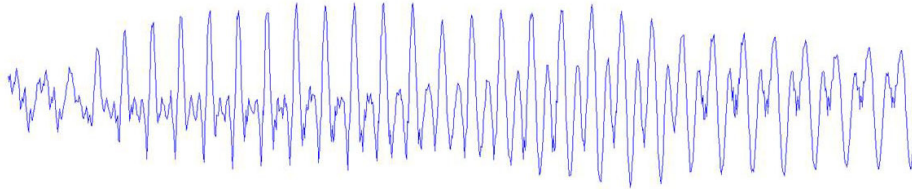
These techniques cause distortion and popping in the audio stream. The CYW4373E uses a proprietary waveform extension algorithm to provide dramatic improvement in the audio quality. [Figure 8](#) and [Figure 9](#) show audio waveforms with and without Packet Loss Concealment. Cypress PLC/BEC algorithms also support wideband speech.

**Figure 8. CVSD Decoder Output Waveform Without PLC**





**Figure 9. CVSD Decoder Output Waveform After Applying PLC**



#### **Audio Rate-Matching Algorithms**

The CYW4373E has an enhanced rate-matching algorithm that uses interpolation algorithms to reduce audio stream jitter that may be present when the rate of audio data coming from the host is not the same as the Bluetooth audio data rates.

#### **Codec Encoding**

The CYW4373E can support SBC and mSBC encoding and decoding for wideband speech.

#### **Multiple Simultaneous A2DP Audio Stream**

The CYW4373E has the ability to take a single audio stream and output it to multiple Bluetooth devices simultaneously. This allows a user to share his or her music (or any audio stream) with a friend.

#### **Burst Buffer Operation**

The CYW4373E has a data buffer that can buffer data being sent over the HCI and audio transports, then send the data at an increased rate. This mode of operation allows the host to sleep for the maximum amount of time, dramatically reducing system current consumption.

### **5.7 Adaptive Frequency Hopping**

The CYW4373E gathers link quality statistics on a channel by channel basis to facilitate channel assessment and channel map selection. The link quality is determined using both RF and baseband signal processing to provide a more accurate frequency-hop map.

## 5.8 Advanced Bluetooth/WLAN Coexistence

The CYW4373E includes advanced coexistence technologies that are only possible with a Bluetooth/WLAN integrated die solution. These coexistence technologies are targeted at small form-factor platforms and high performance platforms such as Industrial systems and media players, including applications such as VoWLAN + eSCO and Video-over-WLAN + High Fidelity BT Stereo.

Support is provided for platforms that share a single antenna between Bluetooth and WLAN. Dual-antenna applications are also supported. Dual antenna applications can be made use of advanced coexistence modes giving superior coexistence performance compared to single antenna applications.

The CYW4373E integrated solution enables MAC-layer signaling (firmware) and a greater degree of sharing via an enhanced coexistence interface. Information is exchanged between the Bluetooth and WLAN cores without host processor involvement.

The CYW4373E also supports Transmit Power Control on the STA together with standard Bluetooth TPC to limit mutual interference and receiver desensitization. Preemption mechanisms are utilized to prevent AP transmissions from colliding with Bluetooth frames. Improved channel classification techniques have been implemented in Bluetooth for faster and more accurate detection and elimination of interferers (including non-WLAN 2.4 GHz interference).

The Bluetooth AFH classification is also enhanced by the WLAN core's channel information.

## 5.9 Fast Connection (Interlaced Page and Inquiry Scans)

The CYW4373E supports page scan and inquiry scan modes that significantly reduce the average inquiry response and connection times. These scanning modes are compatible with the Bluetooth version 2.1 page and inquiry procedures.

## **6. Microprocessor and Memory Unit for Bluetooth**

The Bluetooth microprocessor core is based on the Arm Cortex-M3 32-bit RISC processor with embedded ICE-RT debug and JTAG interface units. It runs software from the link control (LC) layer, up to the host controller interface (HCI).

The Arm core is paired with a memory unit that contains 1088 KB of ROM memory for program storage and boot ROM, 384 KB of RAM for data scratchpad and patch RAM code. The internal ROM allows for flexibility during power-on reset to enable the same device to be used in various configurations. At power-up, the lower-layer protocol stack is executed from the internal ROM memory.

External patches may be applied to the ROM-based firmware to provide flexibility for bug fixes or features additions. These patches may be downloaded from the host to the CYW4373E through UART.

### **6.1 RAM, ROM, and Patch Memory**

The CYW4373E Bluetooth core has 384 KB of internal RAM which is mapped between general purpose scratch pad memory and patch memory and 1088 KB of ROM used for the lower-layer protocol stack, test mode software, and boot ROM. The patch memory capability enables the addition of code changes for purposes of feature additions and bug fixes to the ROM memory.

### **6.2 Reset**

The CYW4373E has an integrated power-on reset circuit that resets all circuits to a known power-on state. The BT power-on reset (POR) circuit is out of reset after BT\_REG\_ON goes High. If BT\_REG\_ON is low, then the POR circuit is held in reset.

## 7. Bluetooth Peripheral Transport Unit

### 7.1 PCM Interface

The CYW4373E has an independent PCM interface. The PCM Interface on the CYW4373E can connect to linear PCM Codec devices in master or slave mode. In master mode, the CYW4373E generates the PCM\_CLK and PCM\_SYNC signals, and in slave mode, these signals are provided by another master on the PCM interface and are inputs to the CYW4373E.

The configuration of the PCM interface may be adjusted by the host through the use of vendor-specific HCI commands.

#### 7.1.1 Slot Mapping

The CYW4373E supports up to three simultaneous full-duplex SCO or eSCO channels through the PCM interface. These three channels are time-multiplexed onto the single PCM interface by using a time-slotting scheme where the 8 kHz or 16 kHz audio sample interval is divided into as many as 16 slots. The number of slots is dependent on the selected interface rate of 128 kHz, 512 kHz, or 1024 kHz. The corresponding number of slots for these interface rate is 1, 2, 4, 8, and 16, respectively. Transmit and receive PCM data from an SCO channel is always mapped to the same slot. The PCM data output driver tristates its output on unused slots to allow other devices to share the same PCM interface signals. The data output driver tristates its output after the falling edge of the PCM clock during the last bit of the slot.

#### 7.1.2 Frame Synchronization

The CYW4373E supports both short- and long-frame synchronization in both master and slave modes. In short-frame synchronization mode, the frame synchronization signal is an active-high pulse at the audio frame rate that is a single-bit period in width and is synchronized to the rising edge of the bit clock. The PCM slave looks for a high on the falling edge of the bit clock and expects the first bit of the first slot to start at the next rising edge of the clock. In long-frame synchronization mode, the frame synchronization signal is again an active-high pulse at the audio frame rate; however, the duration is three bit periods and the pulse starts coincident with the first bit of the first slot.

#### 7.1.3 Data Formatting

The CYW4373E may be configured to generate and accept several different data formats. For conventional narrowband speech mode, the CYW4373E uses 13 of the 16 bits in each PCM frame. The location and order of these 13 bits can be configured to support various data formats on the PCM interface. The remaining three bits are ignored on the input and may be filled with 0s, 1s, a sign bit, or a programmed value on the output. The default format is 13-bit 2's complement data, left justified, and clocked MSB first.

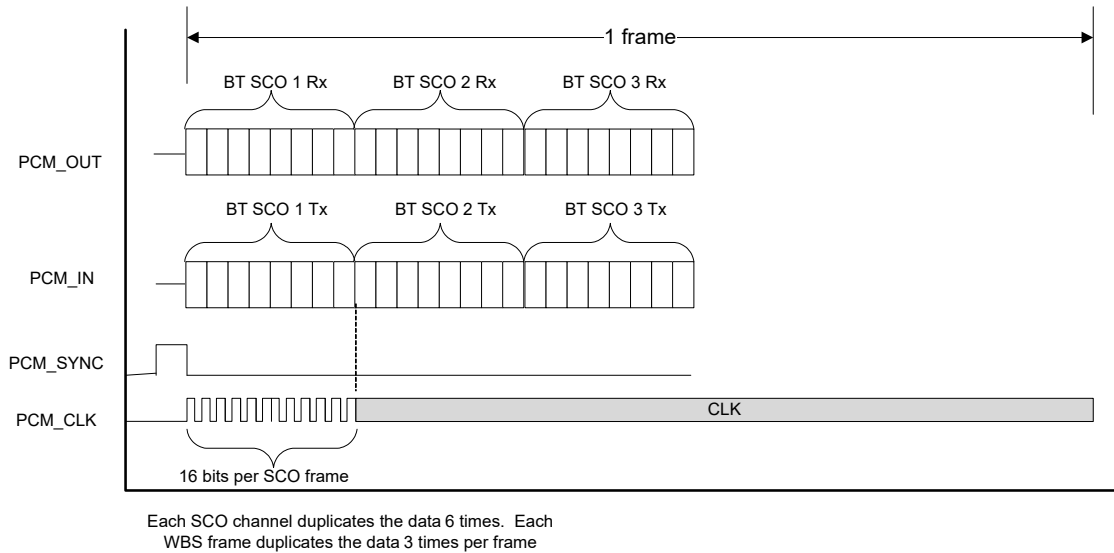
#### 7.1.4 Wideband Speech Support

When the host encodes Wideband Speech (WBS) packets in transparent mode, the encoded packets are transferred over the PCM bus for an eSCO voice connection. In this mode, the PCM bus is typically configured in master mode for a 4 kHz sync rate with 16-bit samples, resulting in a 64 Kbps bit rate. The CYW4373E also supports slave transparent mode using a proprietary rate-matching scheme. In SBC-code mode, linear 16-bit data at 16 kHz (256 Kbps rate) is transferred over the PCM bus.

**7.1.5 Multiplexed Bluetooth Over PCM**

Bluetooth supports multiple audio streams within the Bluetooth channel and both 16 kHz and 8 kHz streams can be multiplexed. This mode of operation is only supported when the Bluetooth host is the master. Figure 10 shows the operation of the multiplexed transport with three simultaneous SCO connections. To accommodate additional SCO channels, the transport clock speed is increased. To change between modes of operation, the transport must be halted and restarted in the new configuration.

**Figure 10. Functional Multiplex Data Diagram**



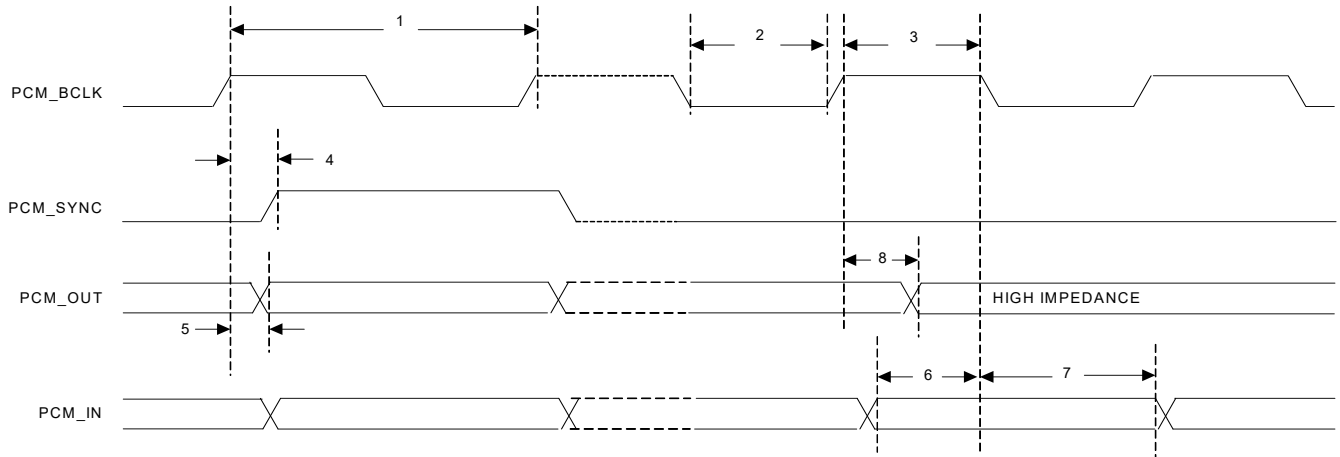
**7.1.6 Burst PCM Mode**

In this mode of operation, the PCM bus runs at a significantly higher rate of operation to allow the host to duty cycle its operation and save current. In this mode of operation, the PCM bus can operate at a rate of up to 24 MHz. This mode of operation is initiated with an HCI command from the host.

7.1.7 PCM Interface Timing

**Short Frame Sync, Master Mode**

**Figure 11. PCM Timing Diagram (Short Frame Sync, Master Mode)**

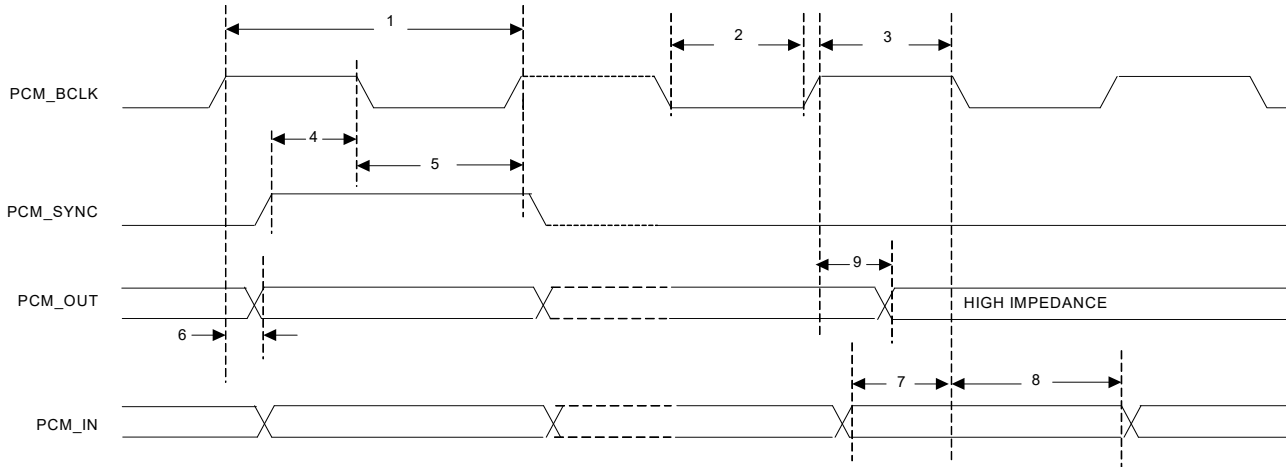


**Table 5. PCM Interface Timing Specifications (Short Frame Sync, Master Mode)**

| Reference | Characteristics  | Min | Typ | Max | Unit |
|-----------|--|-----|-----|-----|------|
| 1         | PCM bit clock frequency  | –   | –   | 12  | MHz  |
| 2         | PCM bit clock LOW  | 41  | –   | –   | ns   |
| 3         | PCM bit clock HIGH   | 41  | –   | –   | ns   |
| 4         | PCM_SYNC delay   | 0   | –   | 25  | ns   |
| 5         | PCM_OUT delay  | 0   | –   | 25  | ns   |
| 6         | PCM_IN setup   | 8   | –   | –   | ns   |
| 7         | PCM_IN hold  | 8   | –   | –   | ns   |
| 8         | Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance | 0   | –   | 25  | ns   |

**Short Frame Sync, Slave Mode**

**Figure 12. PCM Timing Diagram (Short Frame Sync, Slave Mode)**

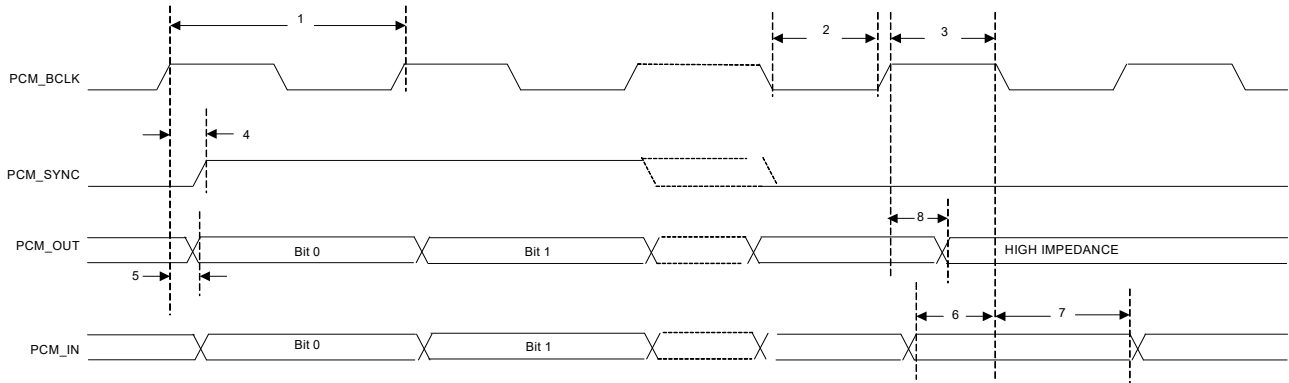


**Table 6. PCM Interface Timing Specifications (Short Frame Sync, Slave Mode)**

| Reference | Characteristics  | Min | Typ | Max | Unit |
|-----------|--|-----|-----|-----|------|
| 1         | PCM bit clock frequency  | –   | –   | 12  | MHz  |
| 2         | PCM bit clock LOW  | 41  | –   | –   | ns   |
| 3         | PCM bit clock HIGH   | 41  | –   | –   | ns   |
| 4         | PCM_SYNC setup   | 8   | –   | –   | ns   |
| 5         | PCM_SYNC hold  | 8   | –   | –   | ns   |
| 6         | PCM_OUT delay  | 0   | –   | 25  | ns   |
| 7         | PCM_IN setup   | 8   | –   | –   | ns   |
| 8         | PCM_IN hold  | 8   | –   | –   | ns   |
| 9         | Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance | 0   | –   | 25  | ns   |

**Long Frame Sync, Master Mode**

**Figure 13. PCM Timing Diagram (Long Frame Sync, Master Mode)**



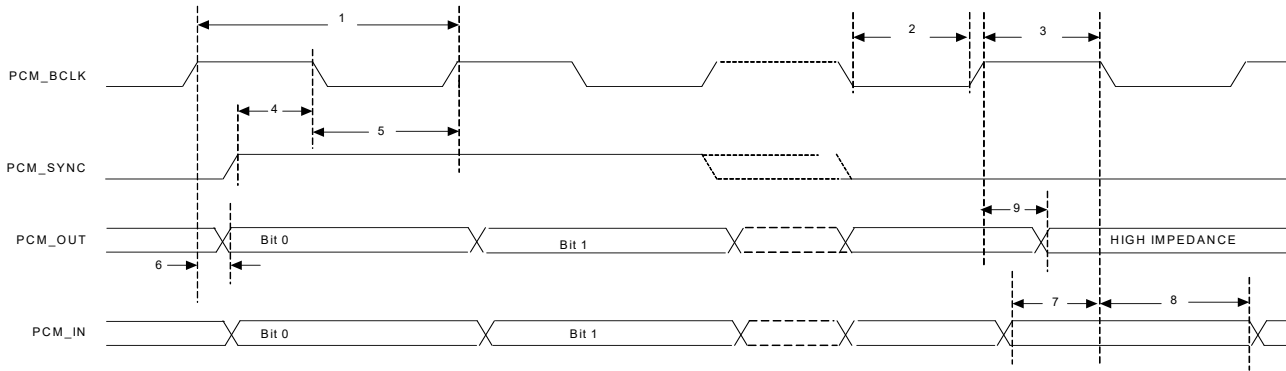
**Table 7. PCM Interface Timing Specifications (Long Frame Sync, Master Mode)**

| Reference | Characteristics  | Min | Typ | Max | Unit |
|-----------|--|-----|-----|-----|------|
| 1         | PCM bit clock frequency  | –   | –   | 12  | MHz  |
| 2         | PCM bit clock LOW  | 41  | –   | –   | ns   |
| 3         | PCM bit clock HIGH   | 41  | –   | –   | ns   |
| 4         | PCM_SYNC delay   | 0   | –   | 25  | ns   |
| 5         | PCM_OUT delay  | 0   | –   | 25  | ns   |
| 6         | PCM_IN setup   | 8   | –   | –   | ns   |
| 7         | PCM_IN hold  | 8   | –   | –   | ns   |
| 8         | Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance | 0   | –   | 25  | ns   |



**Long Frame Sync, Slave Mode**

**Figure 14. PCM Timing Diagram (Long Frame Sync, Slave Mode)**

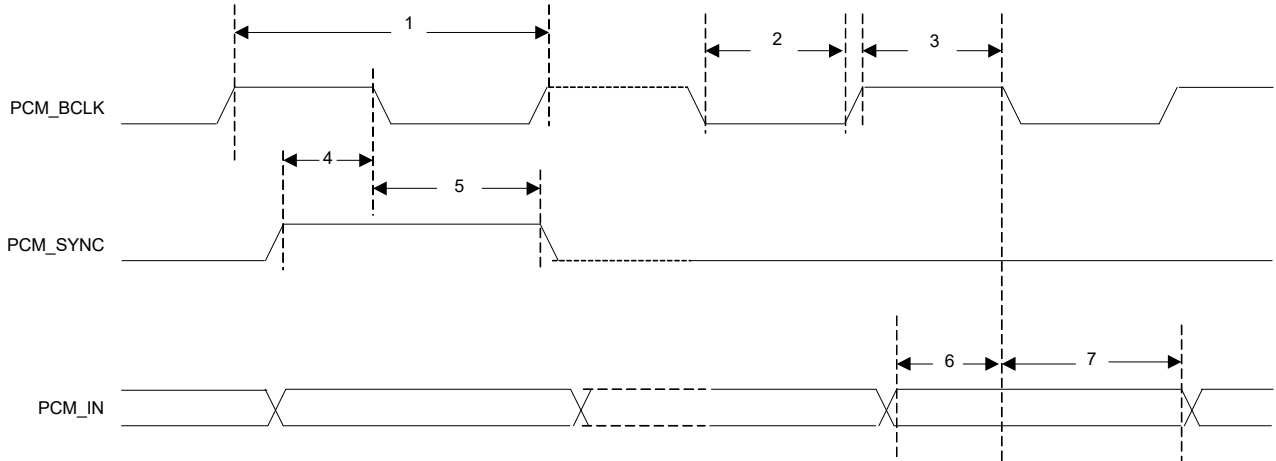


**Table 8. PCM Interface Timing Specifications (Long Frame Sync, Slave Mode)**

| Reference | Characteristics  | Min | Typ | Max | Unit |
|-----------|--|-----|-----|-----|------|
| 1         | PCM bit clock frequency  | –   | –   | 12  | MHz  |
| 2         | PCM bit clock LOW  | 41  | –   | –   | ns   |
| 3         | PCM bit clock HIGH   | 41  | –   | –   | ns   |
| 4         | PCM_SYNC setup   | 8   | –   | –   | ns   |
| 5         | PCM_SYNC hold  | 8   | –   | –   | ns   |
| 6         | PCM_OUT delay  | 0   | –   | 25  | ns   |
| 7         | PCM_IN setup   | 8   | –   | –   | ns   |
| 8         | PCM_IN hold  | 8   | –   | –   | ns   |
| 9         | Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance | 0   | –   | 25  | ns   |

**Short Frame Sync, Burst Mode**

**Figure 15. PCM Burst Mode Timing (Receive Only, Short Frame Sync)**

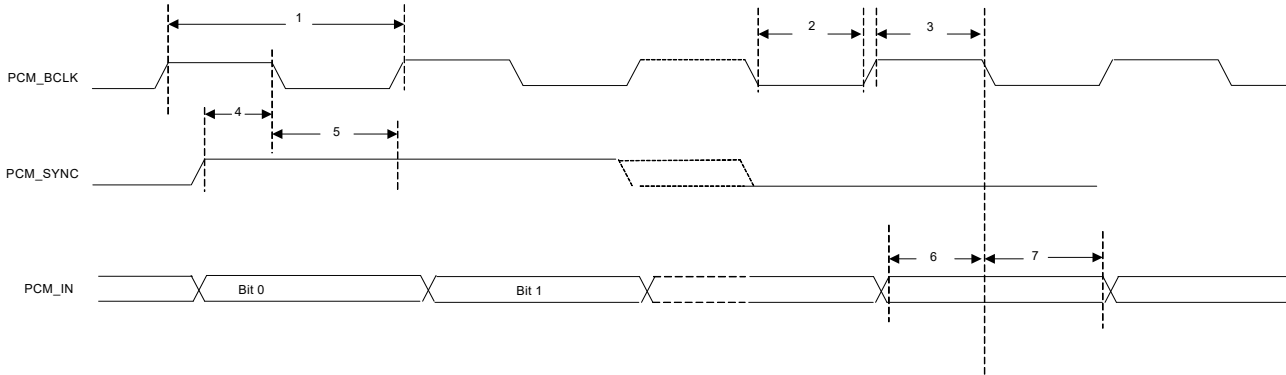


**Table 9. PCM Burst Mode (Receive Only, Short Frame Sync)**

| Reference | Characteristics         | Min  | Typ | Max | Unit |
|-----------|-------------------------|------|-----|-----|------|
| 1         | PCM bit clock frequency | –    | –   | 24  | MHz  |
| 2         | PCM bit clock LOW       | 20.8 | –   | –   | ns   |
| 3         | PCM bit clock HIGH      | 20.8 | –   | –   | ns   |
| 4         | PCM_SYNC setup          | 8    | –   | –   | ns   |
| 5         | PCM_SYNC hold           | 8    | –   | –   | ns   |
| 6         | PCM_IN setup            | 8    | –   | –   | ns   |
| 7         | PCM_IN hold             | 8    | –   | –   | ns   |

**Long Frame Sync, Burst Mode**

**Figure 16. PCM Burst Mode Timing (Receive Only, Long Frame Sync)**



**Table 10. PCM Burst Mode (Receive Only, Long Frame Sync)**

| Reference | Characteristics         | Min  | Typ | Max | Unit |
|-----------|-------------------------|------|-----|-----|------|
| 1         | PCM bit clock frequency | –    | –   | 24  | MHz  |
| 2         | PCM bit clock LOW       | 20.8 | –   | –   | ns   |
| 3         | PCM bit clock HIGH      | 20.8 | –   | –   | ns   |
| 4         | PCM_SYNC setup          | 8    | –   | –   | ns   |
| 5         | PCM_SYNC hold           | 8    | –   | –   | ns   |
| 6         | PCM_IN setup            | 8    | –   | –   | ns   |
| 7         | PCM_IN hold             | 8    | –   | –   | ns   |

**7.2 UART Interface**

The UART is a standard 4-wire interface (RX, TX, RTS, and CTS) with adjustable baud rates from 9600 bps to 4.0 Mbps. The interface features an automatic baud rate detection capability that returns a baud rate selection. Alternatively, the baud rate may be selected through a vendor-specific UART HCI command.

UART has a 1040-byte receive FIFO and a 1040-byte transmit FIFO to support EDR. Access to the FIFOs is conducted through the AHB interface through either DMA or the CPU. The UART supports the Bluetooth UART HCI specification: H4 and a custom Extended H4. The default baud rate is 115.2 Kbaud.

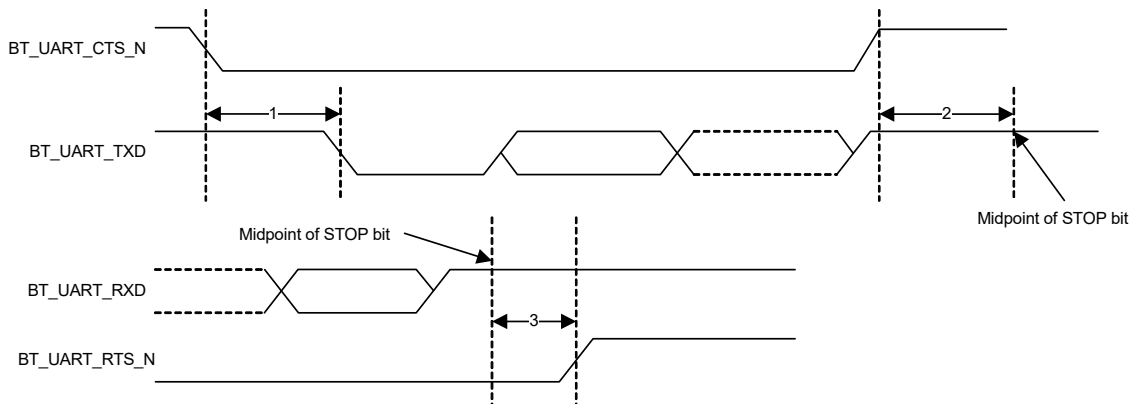
The CYW4373E UART can perform XON/XOFF flow control and includes hardware support for the Serial Line Input Protocol (SLIP). It can also perform wake-on activity. For example, activity on the RX or CTS inputs can wake the chip from a sleep state.

Normally, the UART baud rate is set by a configuration record downloaded after device reset, or by automatic baud rate detection, and the host does not need to adjust the baud rate. Support for changing the baud rate during normal HCI UART operation is included through a vendor-specific command that allows the host to adjust the contents of the baud rate registers. The CYW4373E UARTs operate correctly with the host UART as long as the combined baud rate error of the two devices is within  $\pm 2\%$ .

**Table 11. Example of Common Baud Rates**

| Desired Rate | Actual Rate | Error (%) |
|--------------|-------------|-----------|
| 4000000      | 4000000     | 0.00      |
| 3692000      | 3692308     | 0.01      |
| 3000000      | 3000000     | 0.00      |
| 2000000      | 2000000     | 0.00      |
| 1500000      | 1500000     | 0.00      |
| 1444444      | 1454544     | 0.70      |
| 921600       | 923077      | 0.16      |
| 460800       | 461538      | 0.16      |
| 230400       | 230796      | 0.17      |
| 115200       | 115385      | 0.16      |
| 57600        | 57692       | 0.16      |
| 38400        | 38400       | 0.00      |
| 28800        | 28846       | 0.16      |
| 19200        | 19200       | 0.00      |
| 14400        | 14423       | 0.16      |
| 9600         | 9600        | 0.00      |

**Figure 17. UART Timing**



**Table 12. UART Timing Specifications**

| Ref | Characteristics  | Min | Typ | Max | Unit        |
|-----|--|-----|-----|-----|-------------|
| 1   | Delay time, BT_UART_CTS_N low to BT_UART_TXD valid         | –   | –   | 1.5 | Bit periods |
| 2   | Setup time, BT_UART_CTS_N high before midpoint of stop bit | –   | –   | 0.5 | Bit periods |
| 3   | Delay time, midpoint of stop bit to BT_UART_RTS_N high     | –   | –   | 0.5 | Bit periods |

### 7.3 I<sup>2</sup>S Interface

The CYW4373E supports an I<sup>2</sup>S digital audio port for Bluetooth audio. The I<sup>2</sup>S signals are:

- I<sup>2</sup>S clock: I<sup>2</sup>S SCK
- I<sup>2</sup>S Word Select: I<sup>2</sup>S WS
- I<sup>2</sup>S Data Out: I<sup>2</sup>S SDO
- I<sup>2</sup>S Data In: I<sup>2</sup>S SDI

The I<sup>2</sup>S signals are multiplexed behind the PCM signals. The table below provides the signal mapping.

**Table 13. I<sup>2</sup>S Signal Mapping**

| PCM Signals | I <sup>2</sup> S Signals |
|-------------|--------------------------|
| BT_PCM_CLK  | I <sup>2</sup> S_SCK     |
| BT_PCM_IN   | I <sup>2</sup> S_SDI     |
| BT_PCM_OUT  | I <sup>2</sup> S_SDO     |
| BT_PCM_SYNC | I <sup>2</sup> S_WS      |

I<sup>2</sup>S SCK and I<sup>2</sup>S WS become outputs in master mode and inputs in slave mode, while I<sup>2</sup>S SDO always stays as an output. The channel word length is 16 bits and the data is justified so that the MSB of the left-channel data is aligned with the MSB of the I<sup>2</sup>S bus, per the I<sup>2</sup>S specification. The MSB of each data word is transmitted one bit clock cycle after the I<sup>2</sup>S WS transition, synchronous with the falling edge of bit clock. Left-channel data is transmitted when I<sup>2</sup>S WS is low, and right-channel data is transmitted when I<sup>2</sup>S WS is high. Data bits sent by the CYW4373E are synchronized with the falling edge of I<sup>2</sup>S\_SCK and should be sampled by the receiver on the rising edge of I<sup>2</sup>S\_SCK.

The clock rate in master mode is either of the following:

- 48 kHz x 32 bits per frame = 1.536 MHz
- 48 kHz x 50 bits per frame = 2.400 MHz

The master clock is generated from the input reference clock using a N/M clock divider. In the slave mode, any clock rate is supported to a maximum of 3.072 MHz.

7.3.1 I<sup>2</sup>S Timing

**Note:** Timing values specified in Table 14 are relative to high and low threshold levels.

**Table 14. Timing for I<sup>2</sup>S Transmitters and Receivers**

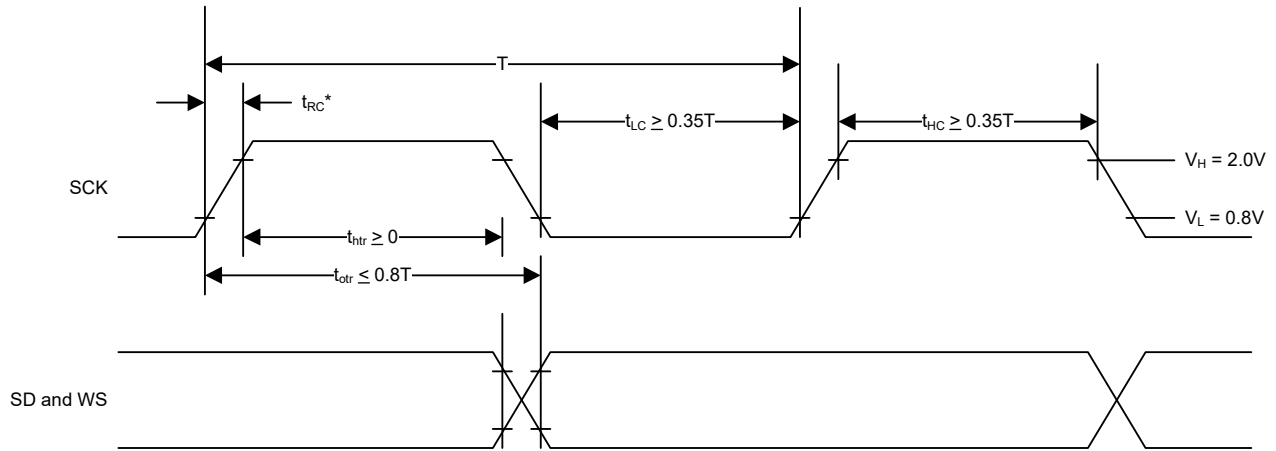
|   | Transmitter         |                     |                     |      | Receiver            |                     |             |      | Notes |
|---|---------------------|---------------------|---------------------|------|---------------------|---------------------|-------------|------|-------|
|   | Lower Limit         |                     | Upper Limit         |      | Lower Limit         |                     | Upper Limit |      |       |
|   | Min.                | Max.                | Min.                | Max. | Min.                | Max.                | Min.        | Max. |       |
| Clock Period T  | T <sub>tr</sub>     | –                   | –                   | –    | T <sub>r</sub>      | –                   | –           | –    | [6]   |
| Master Mode: Clock generated by transmitter or receiver |                     |                     |                     |      |                     |                     |             |      |       |
| HIGH t <sub>HC</sub>                                    | 0.35T <sub>tr</sub> | –                   | –                   | –    | 0.35T <sub>tr</sub> | –                   | –           | –    | [7]   |
| LOW t <sub>LC</sub>                                     | 0.35T <sub>tr</sub> | –                   | –                   | –    | 0.35T <sub>tr</sub> | –                   | –           | –    | [7]   |
| Slave Mode: Clock accepted by transmitter or receiver   |                     |                     |                     |      |                     |                     |             |      |       |
| HIGH t <sub>HC</sub>                                    | –                   | 0.35T <sub>tr</sub> | –                   | –    | –                   | 0.35T <sub>tr</sub> | –           | –    | [8]   |
| LOW t <sub>LC</sub>                                     | –                   | 0.35T <sub>tr</sub> | –                   | –    | –                   | 0.35T <sub>tr</sub> | –           | –    | [8]   |
| Rise time t <sub>RC</sub>                               | –                   | –                   | 0.15T <sub>tr</sub> | –    | –                   | –                   | –           | –    | [9]   |
| Transmitter   |                     |                     |                     |      |                     |                     |             |      |       |
| Delay t <sub>dtr</sub>                                  | –                   | –                   | –                   | 0.8T | –                   | –                   | –           | –    | [10]  |
| Hold time t <sub>htr</sub>                              | 0                   | –                   | –                   | –    | –                   | –                   | –           | –    | [9]   |
| Receiver  |                     |                     |                     |      |                     |                     |             |      |       |
| Setup time t <sub>sr</sub>                              | –                   | –                   | –                   | –    | –                   | 0.2T <sub>r</sub>   | –           | –    | [11]  |
| Hold time t <sub>hr</sub>                               | –                   | –                   | –                   | –    | –                   | 0                   | –           | –    | [11]  |

**Notes**

6. The system clock period T must be greater than T<sub>tr</sub> and T<sub>r</sub> because both the transmitter and receiver have to be able to handle the data transfer rate.
7. At all data rates in master mode, the transmitter or receiver generates a clock signal with a fixed mark/space ratio. For this reason, t<sub>HC</sub> and t<sub>LC</sub> are specified with respect to T.
8. In slave mode, the transmitter and receiver need a clock signal with minimum HIGH and LOW periods so that they can detect the signal. So long as the minimum periods are greater than 0.35T<sub>r</sub>, any clock that meets the requirements can be used.
9. Because the delay (t<sub>dtr</sub>) and the maximum transmitter speed (defined by T<sub>r</sub>) are related, a fast transmitter driven by a slow clock edge can result in t<sub>dtr</sub> not exceeding t<sub>RC</sub> which means t<sub>htr</sub> becomes zero or negative. Therefore, the transmitter has to guarantee that t<sub>htr</sub> is greater than or equal to zero, so long as the clock rise-time t<sub>RC</sub> is not more than t<sub>RCmax</sub>, where t<sub>RCmax</sub> is not less than 0.15T<sub>tr</sub>.
10. To allow data to be clocked out on a falling edge, the delay is specified with respect to the rising edge of the clock signal and T, always giving the receiver sufficient setup time.
11. The data setup and hold time must not be less than the specified receiver setup and hold time.

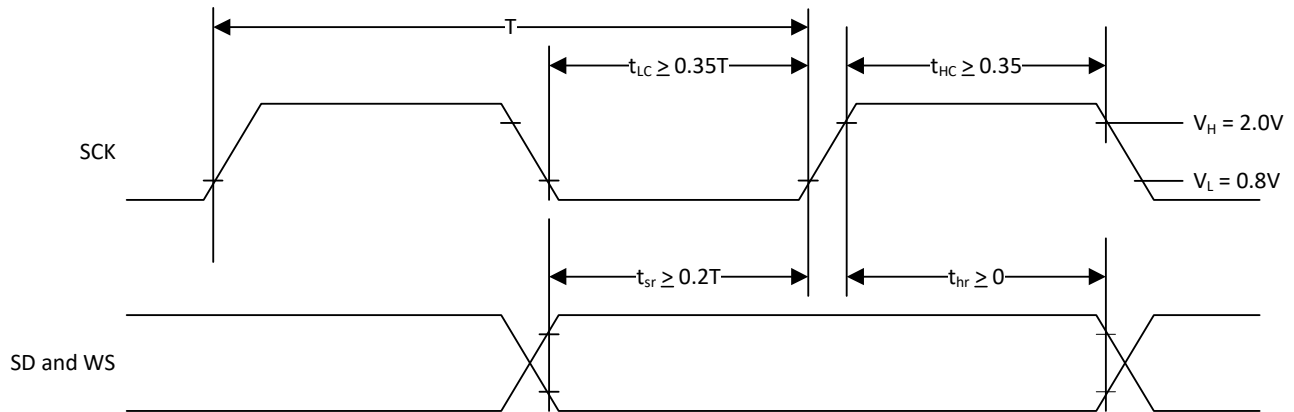
**Note:** The time periods specified in Figure 18 and Figure 19 are defined by the transmitter speed. The receiver specifications must match transmitter performance.

**Figure 18. I<sup>2</sup>S Transmitter Timing**



$T$  = Clock period  
 $T_r$  = Minimum allowed clock period for transmitter  
 $T = T_r$   
 \*  $t_{RC}$  is only relevant for transmitters in slave mode.

**Figure 19. I<sup>2</sup>S Receiver Timing**

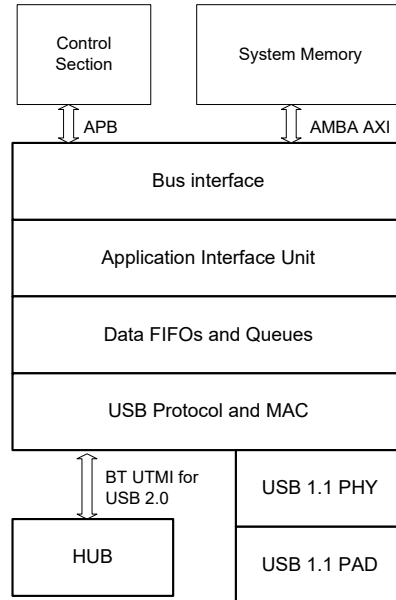


$T$  = Clock period  
 $T_r$  = Minimum allowed clock period for transmitter  
 $T > T_r$

**7.4 BT USB Interface**

Host Interface block diagram of the shared USB for BT is shown in below.

**Figure 20. BT USB Interface**



The CYW4373 has an USB 2.0 protocol engine that supports the following hardware interface:

- Advanced microcontroller bus architecture (AMBA) advanced extensible interface (AXI) for an AXI interconnect
- AMBA advanced peripheral bus (APB) for device controller (BDC) certificate signing request (CSR) access
- Interrupts
- BT UTMI interface connected to HS HUB

The device properties and endpoint (0 to 6) are stored inside the CYW4373 system memory, in which each endpoint consists of transfer ring and is linked to data buffers.



## 8. WLAN Global Functions

### 8.1 WLAN CPU and Memory Subsystem

The CYW4373E WLAN section includes an integrated Arm Cortex-R4 32-bit processor with internal RAM and ROM. The Arm Cortex-R4 is a low-power processor that features low gate count, low interrupt latency, and low-cost debug capabilities.

At 0.19  $\mu\text{W}/\text{MHz}$ , the Cortex-R4 is the most power efficient general-purpose microprocessor available, outperforming 8- and 16-bit devices on MIPS/ $\mu\text{W}$ . It supports integrated sleep modes.

Using multiple technologies to reduce cost, the Arm Cortex-R4 offers improved memory utilization, reduced pin overhead, and reduced silicon area. It supports independent buses for Code and Data access (ICode/DCode and System buses), and extensive debug features including real time trace of program execution.

On-chip memory for the CPU includes 896 KB SRAM and 896 KB ROM.

### 8.2 One-Time Programmable Memory

Various hardware configuration parameters may be stored in an internal 6144-bit (768 bytes) One-Time Programmable (OTP) memory, which is read by the system software after device reset. In addition, customer-specific parameters, including the system vendor ID and the MAC address can be stored, depending on the specific board design.

The initial state of all bits in an unprogrammed OTP device is 0. After any bit is programmed to a 1, it cannot be reprogrammed to 0. The entire OTP array can be programmed in a single write cycle using a utility provided with the Cypress WLAN manufacturing test tools. Alternatively, multiple write cycles can be used to selectively program specific bytes, but only bits which are still in the 0 state can be altered during each programming cycle.

Prior to OTP programming, all values should be verified using the appropriate editable nvram.txt file, which is provided with the reference board design package.

### 8.3 GPIO Interface

The following number of general-purpose I/O (GPIO) pins are available on the WLAN section of the CYW4373E that can be used to connect to various external devices:

- WLBGA package – 10 GPIOs

Upon power-up and reset, these pins become tristated. Subsequently, they can be programmed to be either input or output pins via the GPIO control register. In addition, the GPIO pins can be assigned to various other functions.

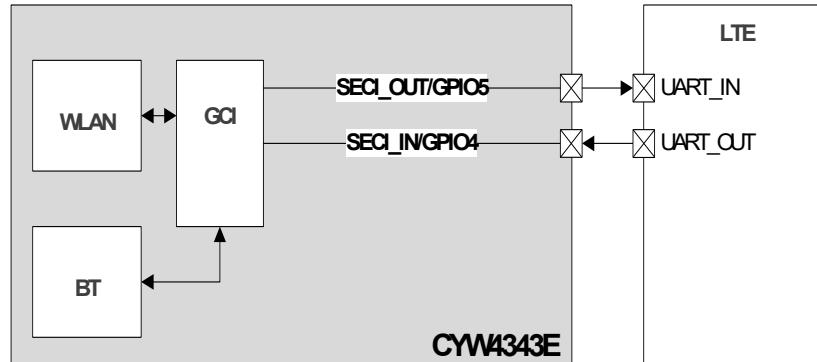
## 8.4 External Coexistence Interface

External handshake interface is available to enable signaling between the device and an external co-located wireless device or LTE to manage wireless medium sharing for optimum performance.

### 8.4.1 LTE Coexistence Interface

Figure 21 shows the WCI-2 LTE coexistence interface<sub>b</sub>. See Table 12 “UART Timing Specifications” for UART baud rate.

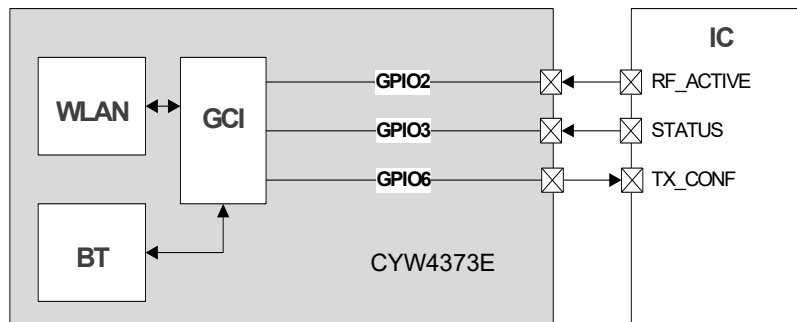
**Figure 21. Cypress GCI or BT-SIG WCI-2 Coexistence Interface for Cypress BT Radios or LTE Radios**



### 8.4.2 3-Wire Coexistence Interface

Figure 22, Figure 23, and Table 15 define external 3-wire interface<sub>b</sub>.

**Figure 22. 3-Wire Coexistence Interface for 3rd Party BT Radios**



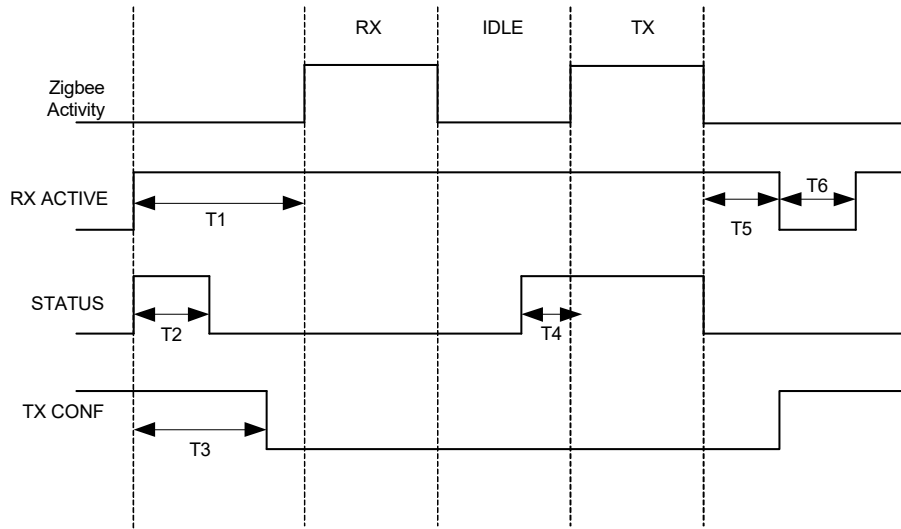
**Table 15. 3-Wire External Coexistence Interface**

| GPIO Name | Coexistence Signal | Type   | Comment   |
|-----------|--------------------|--------|---|
| GPIO_2    | RF_ACTIVE          | Input  | Request indication from external device for access  |
| GPIO_3    | STATUS             | Input  | Indicates priority (within T2) and TX/RX (after T2) |
| GPIO_6    | TX_CONF            | Output | Grant of access indication to external device       |

**Notes:**

- a. GPIO\_2, GPIO\_3, GPIO\_4, GPIO\_5 and GPIO\_6 are multiplexed with the JTAG interface using the JTAG\_SEL pin.
- b. The 2- and 3-wire coexistence interfaces are not supported by default on the CYW94343EWLPSD reference design. Please contact the Cypress support team to understand how to use these interfaces.

**Figure 23. 3-Wire External Coexistence Interface Timing Diagram**



**Notes on Timing Diagram**

- T1: Advance assertion time of RF Active from actual TX or RX
  - Minimum 100  $\mu$ s
- T2: Priority indication on Status Line
  - Expected to start at the same time as RF Active
  - Minimum 30  $\mu$ s
  - Maximum 50  $\mu$ s
  - 1 – High Priority, 0 – Low Priority
- After 50 us, the Status line is used to indicate TX/RX
  - 1 – TX, 0 – RX
- T3 – TX CONF assertion delay from RF ACTIVE
  - Maximum 90  $\mu$ s
- T4 – Advance assertion time of TX/RX indication on status line for subsequent frames without RF ACTIVE toggling
  - Minimum 30  $\mu$ s
- T5 – RF ACTIVE de-assertion delay after end of frame exchange
  - Expected to be as low as possible (~0  $\mu$ s) to improve overall efficiency
- T6 – RF ACTIVE de-assertion
  - Minimum 16  $\mu$ s

3-wire Coexistence interface protocol details:

- External device asserts RF ACTIVE (in advance) when it wants access to the wireless medium
  - 1 – Access Requested
  - 0 – Access not requested
- It indicates priority of the access requested in a specified window (50  $\mu$ s counted from assertion of RF ACTIVE) on STATUS line
  - 1 – High Priority
  - 0 – Low Priority
- After indicating priority on STATUS line it indicates TX/RX indication on the same STATUS line (after 50  $\mu$ s window)
  - 1 – TX
  - 0 – RX
- Arbitrating device (WiFi) will decide based on the relative priority of the different requests (WiFi internal and external) and either grant or reject the request. This is indicated using the TX CONF signal
  - 1 – Access Denied
  - 0 – Access Granted

## 8.5 UART Interface

A high-speed 4-wire CTS/RTS UART interface can be enabled by software as an alternate function on GPIO pins. Provided primarily for debugging during development, this UART enables the CYW4373E to operate as RS-232 data termination equipment (DTE) for exchanging and managing data with other serial devices. It is compatible with the industry standard 16550 UART, and provides a FIFO size of 64  $\times$  8 in each direction.

## 8.6 JTAG Interface

The CYW4373E supports IEEE 1149.1 JTAG boundary scan to access the chip's internal blocks and backplane for system bring-up and debugging. This interface allows Cypress engineers to assist customers with proprietary debug and characterization test tools.

The debug access port (DAP) embedded in the Arm processor supports both SWD and JTAG interfaces and can be switched from one to the other through a specific sequence on the TMS lines. In addition to the Arm debug interface, an internal JTAG master on the DAP allows access to test access points (TAPs) in the CYW4373E for hardware debugging.

## 9. WLAN Host Interfaces

### 9.1 SDIO v3.0

CYW4373E WLAN section provides support for SDIO version 3.0, including the new UHS-I modes:

- DS: Default speed (DS) up to 25 MHz, including 1- and 4-bit modes (3.3V signaling).
- HS: High speed up to 50 MHz (3.3V signaling).
- SDR12: SDR up to 25 MHz (1.8V signaling).
- SDR25: SDR up to 50 MHz (1.8V signaling).
- SDR50: SDR up to 100 MHz (1.8V signaling).
- SDR104: SDR up to 208 MHz (1.8V signaling)
- DDR50: DDR up to 50 MHz (1.8V signaling).

**Note:** The CYW4373E is backward compatible with SDIO v2.0 host interfaces.

The SDIO interface also has the ability to map the interrupt signal on to a GPIO pin for applications requiring an interrupt different from the one provided by the SDIO interface. The ability to force control of the gated clocks from within the device is also provided. SDIO mode is enabled by strapping options. See [Table 19](#) for strapping options.

The following three functions are supported:

- Function 0 Standard SDIO function (Max BlockSize/ByteCount = 32B)
- Function 1 Backplane Function to access the internal system-on-chip (SoC) address space (Max BlockSize/ByteCount = 64B)
- Function 2 WLAN Function for efficient WLAN packet transfer through DMA (Max BlockSize/ByteCount = 512B).
- Function 3 BT Function for efficient WLAN packet transfer through DMA

#### 9.1.1 SDIO Pins

**Table 16. SDIO Pin Description**

| SD 4-Bit Mode |                          | SD 1-Bit Mode |              |
|---------------|--------------------------|---------------|--------------|
| DATA0         | Data line 0              | DATA          | Data line    |
| DATA1         | Data line 1 or Interrupt | IRQ           | Interrupt    |
| DATA2         | Data line 2 or Read Wait | RW            | Read Wait    |
| DATA3         | Data line 3              | N/C           | Not used     |
| CLK           | Clock                    | CLK           | Clock        |
| CMD           | Command line             | CMD           | Command line |

**Figure 24. Signal Connections to SDIO Host (SD 4-Bit Mode)**

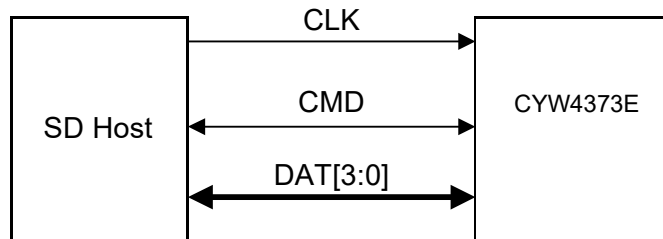
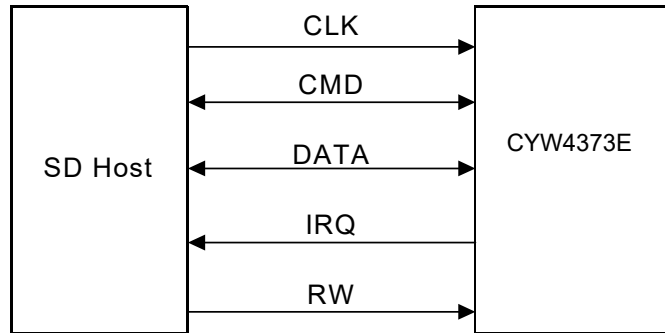


Figure 25. Signal Connections to SDIO Host (SD 1-Bit Mode)



**Note:** Per Section 6 of the SDIO specification, pull-ups in the 10 kΩ to 100 kΩ range are required on the four DATA lines and the CMD line. This requirement must be met during all operating states either through the use of external pull-up resistors or through proper programming of the SDIO host's internal pull-ups.

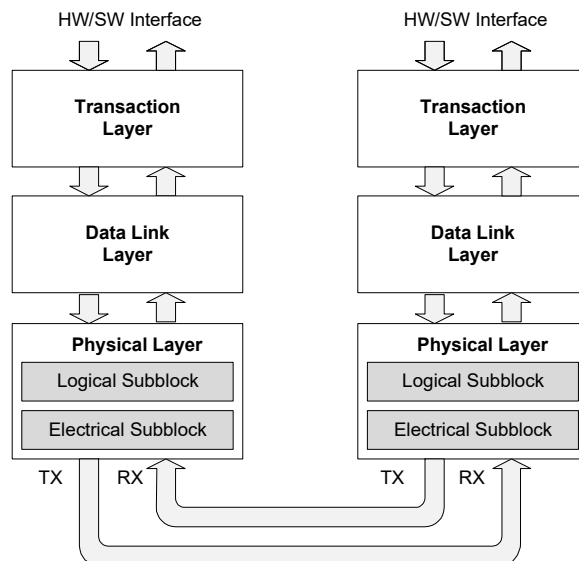
### 9.2 PCI Express Interface

The PCI Express (PCIe) core on the CYW4373E is a high-performance serial I/O interconnect that is protocol compliant and electrically compatible with the *PCI Express Base Specification v2.0*. This core contains all the necessary blocks, including logical and electrical functional subblocks to perform PCIe functionality and maintain high-speed links, using existing PCI system configuration software implementations without modification.

Organization of the PCIe core is in logical layers: Transaction Layer, Data Link Layer, and Physical Layer, as shown in Figure 26. A configuration or link management block is provided for enumerating the PCIe configuration space and supporting generation and reception of System Management Messages by communicating with PCIe layers.

Each layer is partitioned into dedicated transmit and receive units that allow point-to-point communication between the host and CYW4373E device. The transmit side processes outbound packets while the receive side processes inbound packets. Packets are formed and generated in the Transaction and Data Link Layer for transmission onto the high-speed links and onto the receiving device. A header is added at the beginning to indicate the packet type and any other optional fields.

Figure 26. PCI Express Layer Model



### 9.2.1 Transaction Layer Interface

The PCIe core employs a packet-based protocol to transfer data between the host and CYW4373E device, delivering new levels of performance and features. The upper layer of the PCIe is the Transaction Layer. The Transaction layer is primarily responsible for assembly and disassembly of Transaction Layer Packets (TLPs). TLP structure contains header, data payload, and End-to-End CRC (ECRC) fields, which are used to communicate transactions, such as read and write requests and other events.

A pipelined full split-transaction protocol is implemented in this layer to maximize efficient communication between devices with credit-based flow control of TLP, which eliminates wasted link bandwidth due to retries.

### 9.2.2 Data Link Layer

The data link layer serves as an intermediate stage between the transaction layer and the physical layer. Its primary responsibility is to provide reliable, efficient mechanism for the exchange of TLPs between two directly connected components on the link. Services provided by the data link layer include data exchange, initialization, error detection and correction, and retry services.

Data Link Layer Packets (DLLPs) are generated and consumed by the data link layer. DLLPs are the mechanism used to transfer link management information between data link layers of the two directly connected components on the link, including TLP acknowledgment, power management, and flow control.

### 9.2.3 Physical Layer

The physical layer of the PCIe provides a handshake mechanism between the data link layer and the high-speed signaling used for Link data interchange. This layer is divided into the logical and electrical functional subblocks. Both subblocks have dedicated transmit and receive units that allow for point-to-point communication between the host and CYW4373E device. The transmit section prepares outgoing information passed from the data link layer for transmission, and the receiver section identifies and prepares received information before passing it to the data link layer. This process involves link initialization, configuration, scrambler, and data conversion into a specific format.

### 9.2.4 Logical Subblock

The logical sub block primary functions are to prepare outgoing data from the data link layer for transmission and identify received data before passing it to the data link layer.

### 9.2.5 Scrambler/Descrambler

This PCIe PHY component generates pseudo-random sequence for scrambling of data bytes and the idle sequence. On the transmit side, scrambling is applied to characters prior to the 8b/10b encoding. On the receive side, descrambling is applied to characters after 8b/10b decoding. Scrambling may be disabled in polling and recovery for testing and debugging purposes.

### 9.2.6 8B/10B Encoder/Decoder

The PCIe core on the CYW4373E uses an 8b/10b encoder/decoder scheme to provide DC balancing, synchronizing clock and data recovery, and error detection. The transmission code is specified in the ANSI X3.230-1994, clause 11 and in IEEE 802.3z, 36.2.4.

Using this scheme, 8-bit data characters are treated as 3 bits and 5 bits mapped onto a 4-bit code group and a 6-bit code group, respectively. The control bit in conjunction with the data character is used to identify when to encode one of the twelve Special Symbols included in the 8b/10b transmission code. These code groups are concatenated to form a 10-bit symbol, which is then transmitted serially. Special Symbols are used for link management, frame TLPs, and DLLPs, allowing these packets to be quickly identified and easily distinguished.

### 9.2.7 Elastic FIFO

An elastic FIFO is implemented in the receiver side to compensate for the differences between the transmit clock domain and the receive clock domain, with worst case clock frequency specified at 600 ppm tolerance. As a result, the transmit and receive clocks can shift one clock every 1666 clocks. In addition, the FIFO adaptively adjusts the elastic level based on the relative frequency difference of the write and read clock. This technique reduces the elastic FIFO size and the average receiver latency by half.

**9.2.8 Electrical Subblock**

The high-speed signals utilize the Common Mode Logic (CML) signaling interface with on-chip termination and de-emphasis for best-in-class signal integrity. A de-emphasis technique is employed to reduce the effects of Intersymbol Interference (ISI) due to the interconnect by optimizing voltage and timing margins for worst case channel loss. This results in a maximally open “eye” at the detection point, thereby allowing the receiver to receive data with acceptable Bit-Error Rate (BER).

To further minimize ISI, multiple bits of the same polarity that are output in succession are de-emphasized. Subsequent same bits are reduced by a factor of 3.5 dB in power. This amount is specified by PCIe to allow for maximum interoperability while minimizing the complexity of controlling the de-emphasis values. The high-speed interface requires AC coupling on the transmit side to eliminate the DC common mode voltage from the receiver. The range of AC capacitance allowed is 75 nF to 200 nF.

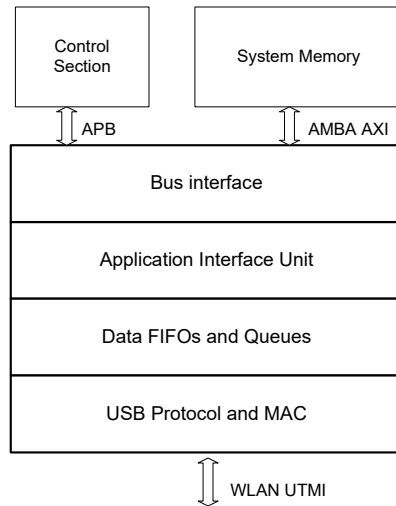
**9.2.9 Configuration Space**

The PCIe function in the CYW4373E implements the configuration space as defined in the *PCI Express Base Specification v2.0*.

**9.3 WLAN USB 2.0 Interface**

Figure 27 details the Host Interface block diagram of the shared USB 2.0 for WLAN

**Figure 27. WLAN USB 2.0 Host Interface block diagram**



The CYW4373E has an USB 2.0 protocol engine that supports the following hardware interface:

- Advanced microcontroller bus architecture (AMBA) advanced extensible interface (AXI) for an AXI interconnect
- AMBA advanced peripheral bus (APB) for device controller (BDC) certificate signing request (CSR) access.
- Interrupts
- WLAN UTMI interface connected HS Hub.

The device properties and endpoint (0 to 5) are stored inside the CYW4373 system memory, in which each endpoint consists of transfer ring and is linked to data buffers.

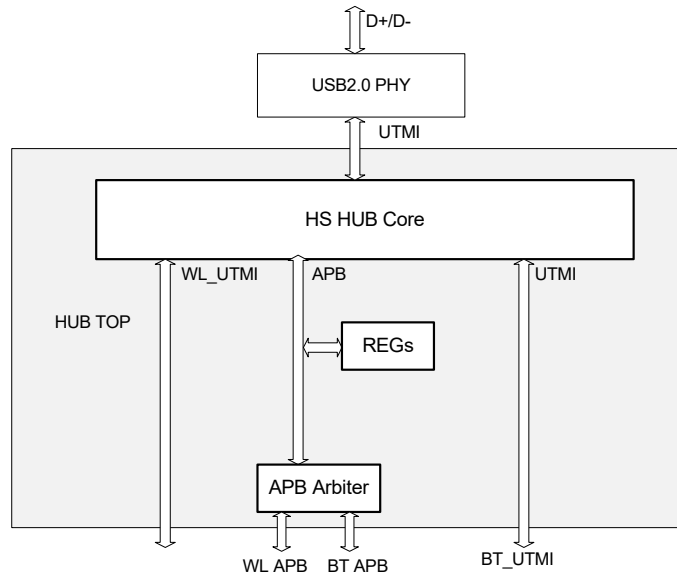


## 10. Shared Host Interfaces

### 10.1 Shared BT and WLAN USB 2.0 Interface

Figure 28 details the Host Interface block diagram of the shared USB 2.0 hub for WLAN and BT.

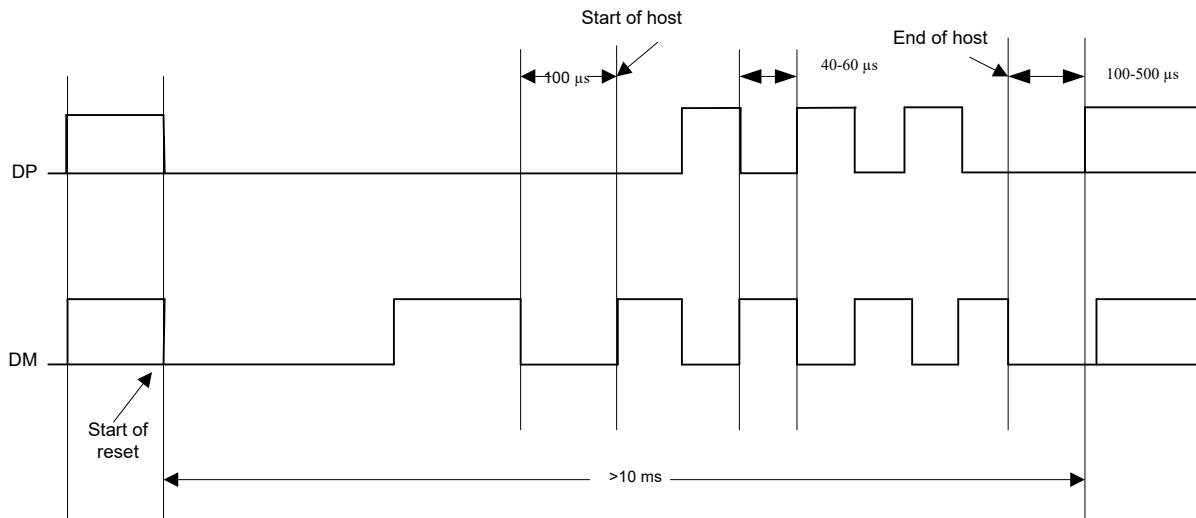
**Figure 28. WLAN/BT USB 2.0 Host Interface block diagram**



The CYW4373 has a USB2.0-PHY and HS HUB which can enable shared USB2.0 interface between WLAN and BT. The key features of this USB2.0-PHY and HS HUB are as follows:

- D+/D- as USB signaling
- HS HUB is connected to WLAN and BT via UTMI interface.
- AMBA advanced peripheral bus (APB) for reading writing APB registers of HS HUB and other registers. These registers are accessible by both WLAN and BT through an arbiter.

**Figure 29. WLAN/BT USB Timing**



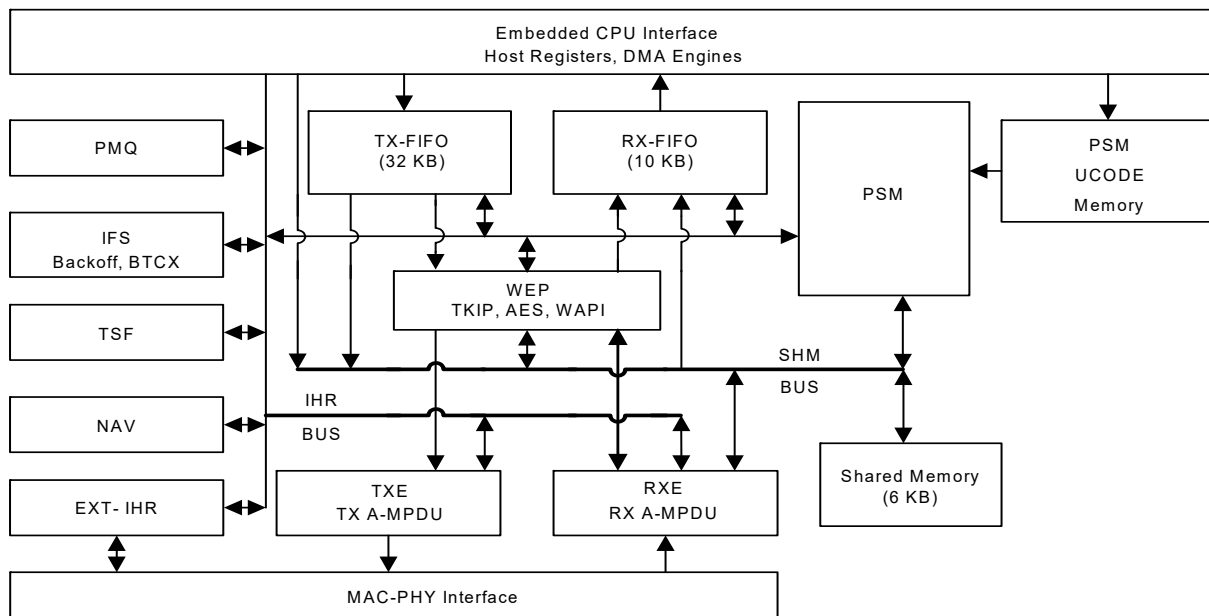
## 11. Wireless LAN MAC and PHY

### 11.1 IEEE 802.11ac MAC

The CYW4373E WLAN MAC is designed to support high-throughput operation with low-power consumption. It does so without compromising the Bluetooth coexistence policies, thereby enabling optimal performance over both networks. In addition, several power saving modes have been implemented that allow the MAC to consume very little power while maintaining network-wide timing synchronization. The architecture diagram of the MAC is shown in [Figure 30](#).

The following sections provide an overview of the important modules in the MAC.

**Figure 30. WLAN MAC Architecture**



The CYW4373E WLAN media access controller (MAC) supports features specified in the IEEE 802.11 base standard, and amended by IEEE 802.11n/ac. The key MAC features include:

- Enhanced MAC for supporting IEEE 802.11ac features
- Transmission and reception of aggregated MPDUs (A-MPDUs) for very high throughput (VHT)
- Support for power management schemes, including WMM power-save, power-save multi-poll (PSMP) and multiphase PSMP operation
- Support for immediate ACK and Block-ACK policies
- Interframe space timing support, including RIFS
- Support for RTS/CTS and CTS-to-self frame sequences for protecting frame exchanges
- Back-off counters in hardware for supporting multiple priorities as specified in the WMM specification
- Timing synchronization function (TSF), network allocation vector (NAV) maintenance, and target beacon transmission time (TBTT) generation in hardware and capturing the TSF timer on an external time synchronization pulse
- Hardware offload for AES-CCMP, legacy WPA TKIP, legacy WEP ciphers, WAPI, and support for key management
- Support for coexistence with Bluetooth and other external radios
- Programmable independent basic service set (IBSS) or infrastructure basic service set functionality
- Statistics counters for MIB support

### 11.1.1 PSM

The programmable state machine (PSM) is a microcoded engine, which provides most of the low-level control to the hardware, to implement the IEEE 802.11 specification. It is a microcontroller that is highly optimized for flow control operations, which are predominant in implementations of communication protocols. The instruction set and fundamental operations are simple and general, which allows algorithms to be optimized until very late in the design process. It also allows for changes to the algorithms to track evolving IEEE 802.11 specifications.

The PSM fetches instructions from the microcode memory. It uses the shared memory to obtain operands for instructions, as a data store, and to exchange data between both the host and the MAC data pipeline (via the SHM bus). The PSM also uses a scratchpad memory (similar to a register bank) to store frequently accessed and temporary variables.

The PSM exercises fine-grained control over the hardware engines, by programming internal hardware registers (IHR). These IHRs are co-located with the hardware functions they control, and are accessed by the PSM via the IHR bus.

The PSM fetches instructions from the microcode memory using an address determined by the program counter, instruction literal, or a program stack. For ALU operations the operands are obtained from shared memory, scratchpad, IHRs, or instruction literals, and the results are written into the shared memory, scratchpad, or IHRs.

There are two basic branch instructions: conditional branches and ALU based branches. To better support the many decision points in the IEEE 802.11 algorithms, branches can depend on either a readily available signals from the hardware modules (branch condition signals are available to the PSM without polling the IHRs), or on the results of ALU operations.

### 11.1.2 WEP

The wired equivalent privacy (WEP) engine encapsulates all the hardware accelerators to perform the encryption and decryption, and MIC computation and verification. The accelerators implement the following cipher algorithms: legacy WEP, WPA TKIP, WPA2 AES-CCMP.

The PSM determines, based on the frame type and association information, the appropriate cipher algorithm to be used. It supplies the keys to the hardware engines from an on-chip key table. The WEP interfaces with the TXE to encrypt and compute the MIC on transmit frames, and the RXE to decrypt and verify the MIC on receive frames.

### 11.1.3 TXE

The transmit engine (TXE) constitutes the transmit data path of the MAC. It coordinates the DMA engines to store the transmit frames in the TXFIFO. It interfaces with WEP module to encrypt frames, and transfers the frames across the MAC-PHY interface at the appropriate time determined by the channel access mechanisms.

The data received from the DMA engines are stored in transmit FIFOs. The MAC supports multiple logical queues to support traffic streams that have different QoS priority requirements. The PSM uses the channel access information from the IFS module to schedule a queue from which the next frame is transmitted. Once the frame is scheduled, the TXE hardware transmits the frame based on a precise timing trigger received from the IFS module.

The TXE module also contains the hardware that allows the rapid assembly of MPDUs into an A-MPDU for transmission. The hardware module aggregates the encrypted MPDUs by adding appropriate headers and pad delimiters as needed.

### 11.1.4 RXE

The receive engine (RXE) constitutes the receive data path of the MAC. It interfaces with the DMA engine to drain the received frames from the RXFIFO. It transfers bytes across the MAC-PHY interface and interfaces with the WEP module to decrypt frames. The decrypted data is stored in the RXFIFO.

The RXE module contains programmable filters that are programmed by the PSM to accept or filter frames based on several criteria such as receiver address, BSSID, and certain frame types.

The RXE module also contains the hardware required to detect A-MPDUs, parse the headers of the containers, and disaggregate them into component MPDUS.

#### 11.1.5 IFS

The IFS module contains the timers required to determine interframe space timing including RIFS timing. It also contains multiple backoff engines required to support prioritized access to the medium as specified by WMM.

The interframe spacing timers are triggered by the cessation of channel activity on the medium, as indicated by the PHY. These timers provide precise timing to the TXE to begin frame transmission. The TXE uses this information to send response frames or perform transmit frame-bursting (RIFS or SIFS separated, as within a TXOP).

The backoff engines (for each access category) monitor channel activity, in each slot duration, to determine whether to continue or pause the backoff counters. When the backoff counters reach 0, the TXE gets notified, so that it may commence frame transmission. In the event of multiple backoff counters decrementing to 0 at the same time, the hardware resolves the conflict based on policies provided by the PSM.

The IFS module also incorporates hardware that allows the MAC to enter a low-power state when operating under the IEEE power save mode. In this mode, the MAC is in a suspended state with its clock turned off. A sleep timer, whose count value is initialized by the PSM, runs on a slow clock and determines the duration over which the MAC remains in this suspended state. Once the timer expires the MAC is restored to its functional state. The PSM updates the TSF timer based on the sleep duration ensuring that the TSF is synchronized to the network.

The IFS module also contains the PTA hardware that assists the PSM in Bluetooth coexistence functions.

#### 11.1.6 TSF

The timing synchronization function (TSF) module maintains the TSF timer of the MAC. It also maintains the target beacon transmission time (TBTT). The TSF timer hardware, under the control of the PSM, is capable of adopting timestamps received from beacon and probe response frames in order to maintain synchronization with the network.

The TSF module also generates trigger signals for events that are specified as offsets from the TSF timer, such as uplink and downlink transmission times used in PSMP.

#### 11.1.7 NAV

The network allocation vector (NAV) timer module is responsible for maintaining the NAV information conveyed through the duration field of MAC frames. This ensures that the MAC complies with the protection mechanisms specified in the standard.

The hardware, under the control of the PSM, maintains the NAV timer and updates the timer appropriately based on received frames. This timing information is provided to the IFS module, which uses it as a virtual carrier-sense indication.

#### 11.1.8 MAC-PHY Interface

The MAC-PHY interface consists of a data path interface to exchange RX/TX data from/to the PHY. In addition, there is an programming interface, which can be controlled either by the host or the PSM to configure and control the PHY. This block also captures two sets of TSF and AVB timers when an external trigger is detected. The trigger can be programmed to occur on any edge of either any GPIO or the TimeSyncSlowIn, TimeSyncFastIn, or selected coexistence inputs.

## 11.2 IEEE 802.11ac PHY

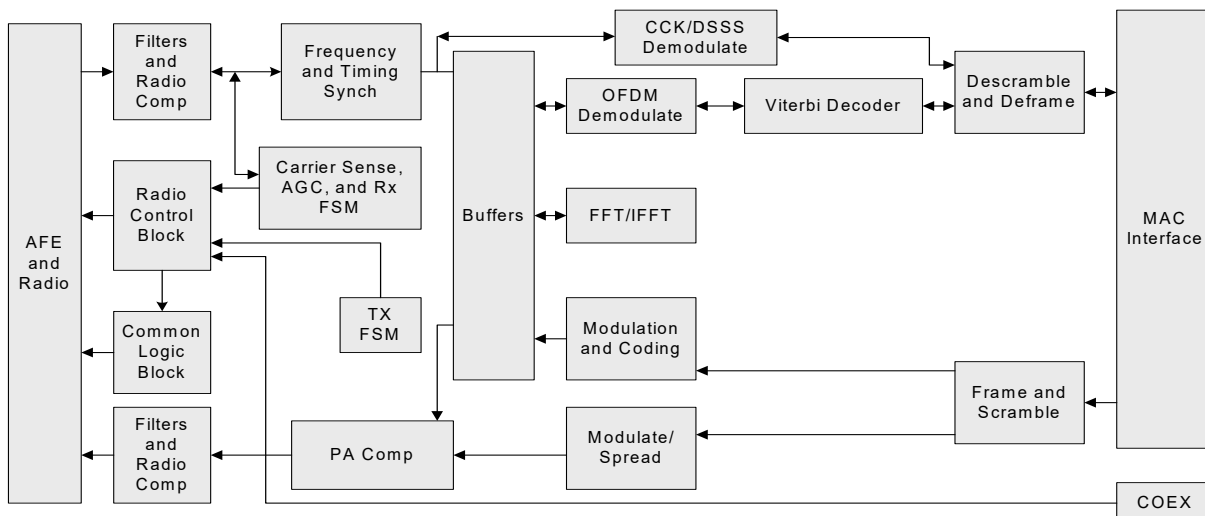
The CYW4373E WLAN Digital PHY is designed to comply with IEEE 802.11a/b/g/n/ac single-stream specifications to provide wireless LAN connectivity supporting data rates from 1 Mbps to 433.3 Mbps for low-power, high-performance handheld applications.

The PHY has been designed to work in the presence of interference, radio nonlinearity, and various other impairments. It incorporates optimized implementations of the filters, FFT, Viterbi decoder and LDPC decoder algorithms. Efficient algorithms have been designed to achieve maximum throughput and reliability, including algorithms for carrier sense/rejection, frequency/phase/timing acquisition and tracking, channel estimation and tracking. The PHY receiver also contains a robust IEEE 802.11b demodulator. The PHY carrier sense has been tuned to provide high throughput for IEEE 802.11g/11b hybrid networks with Bluetooth coexistence. It has also been designed for shared single antenna systems between WL and BT to support simultaneous RX-RX.

The key PHY features include:

- Programmable data rates from MCS0–MCS8 in 20 MHz and MCS0–MCS9 in 40/80 MHz channels, as specified in IEEE 802.11ac.
- Supports Optional Short GI and Green Field modes in TX and RX.
- TX and RX LDPC for improved range and power efficiency.
- All scrambling, encoding, forward error correction, and modulation in the transmit direction and inverse operations in the receive direction.
- Supports IEEE 802.11h/d for worldwide operation.
- Advanced algorithms for low power, enhanced sensitivity, range, and reliability.
- Algorithms to improve performance in presence of Bluetooth.
- Automatic gain control scheme for blocking and non blocking application scenario for cellular applications.
- Closed loop transmit power control.
- Digital RF chip calibration algorithms to handle CMOS RF chip non-idealities.
- On-the-fly channel frequency and transmit power selection.
- Supports per-packet RX antenna diversity.
- Available per-packet channel quality and signal strength measurements.
- Designed to meet FCC and other worldwide regulatory requirements.
- Narrow band (2.5, 5 & 10 MHz channel) WLAN mode for long range

**Figure 31. WLAN PHY Block Diagram**



## 12. WLAN Radio Subsystem

The CYW4373E includes an integrated dual-band WLAN RF transceiver that has been optimized for use in 2.4 GHz and 5 GHz Wireless LAN systems. It has been designed to provide low-power, low-cost, and robust communications for applications operating in the globally available 2.4 GHz unlicensed ISM or 5 GHz U-NII bands. The transmit and receive sections include all on-chip filtering, mixing, and gain control functions.

Ten RF control signals are available to drive external RF switches and support optional external power amplifiers and low-noise amplifiers for each band. See the reference board schematics for further details.

A block diagram of the radio subsystem is shown in [Figure 32](#). Note that integrated on-chip baluns (not shown) convert the fully differential transmit and receive paths to single-ended signal pins.

### 12.1 Receiver Path

The CYW4373E has a wide dynamic range, direct conversion receiver that employs high order on-chip channel filtering to ensure reliable operation in the noisy 2.4 GHz ISM band or the entire 5 GHz U-NII band. An on-chip low-noise amplifier (LNA) in the 2.4 GHz path is shared between the Bluetooth and WLAN receivers, while the 5 GHz receive path has a dedicated on-chip LNA. Control signals are available that can support the use of optional LNAs for each band, which can increase the receive sensitivity by several dB.

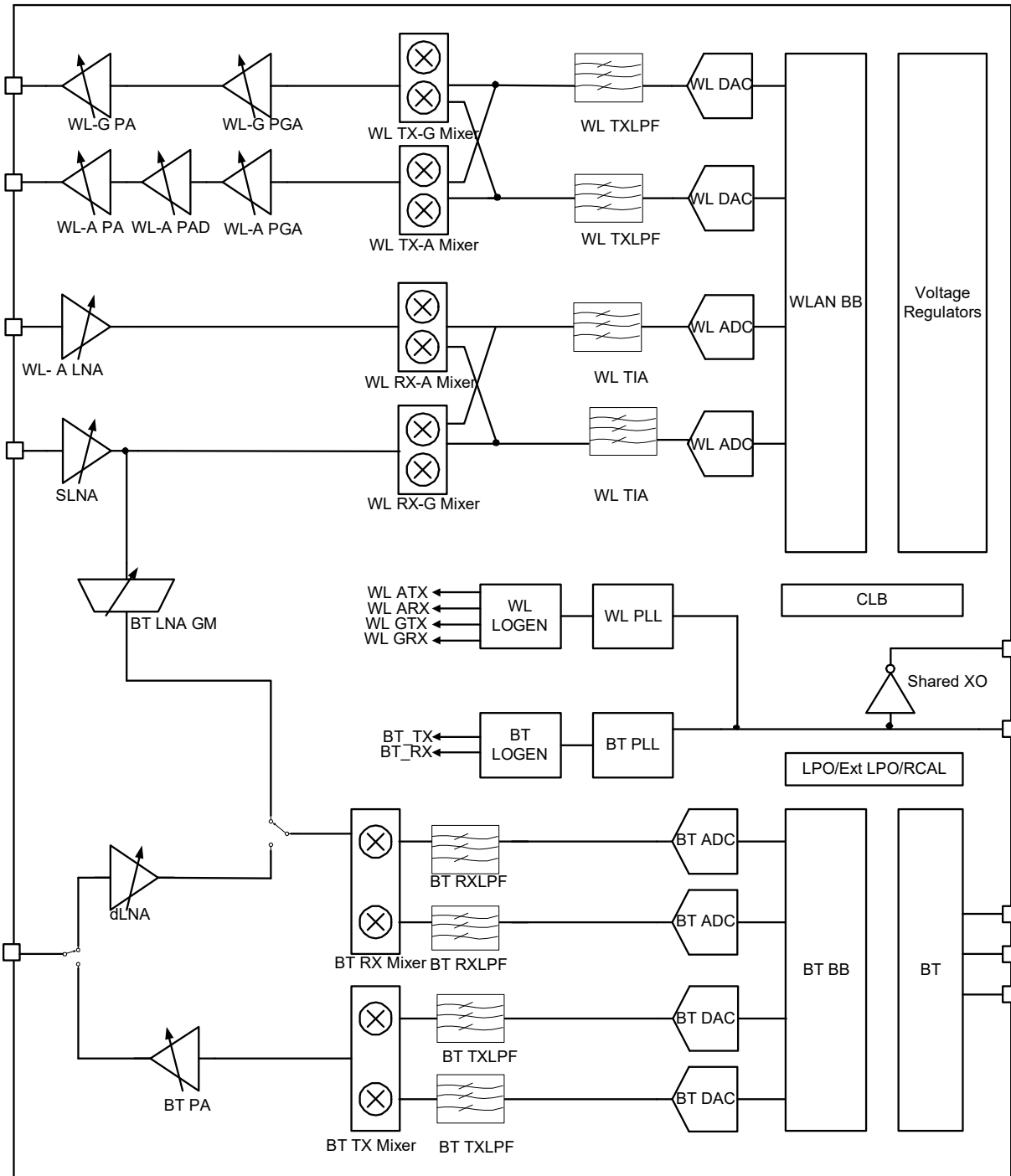
### 12.2 Transmit Path

Baseband data is modulated and upconverted to the 2.4 GHz ISM or 5-GHz U-NII bands, respectively. Linear on-chip power amplifiers are included, which are capable of delivering high output powers while meeting IEEE 802.11 a/b/g/n/ac specifications without the need for external PAs. When using the internal PAs, closed-loop output power control is completely integrated. As an option, external PAs can be used for even higher output power, in which case the closed-loop output power control is provided by means of a-band and g-band TSSI inputs from external power detectors.

### 12.3 Calibration

The CYW4373E features dynamic and automatic on-chip calibration to continually compensate for temperature and process variations across components. These calibration routines are performed periodically in the course of normal radio operation. Examples of some of the automatic calibration algorithms are baseband filter calibration for optimum transmit and receive performance, and LOFT calibration for carrier leakage reduction. In addition, I/Q Calibration, R Calibration, and VCO Calibration are performed on-chip. No per-board calibration is required in manufacturing test, which helps to minimize the test time and cost in large volume production.

**Figure 32. Radio Functional Block Diagram**



### 13. Ball Map and Pin Descriptions

#### 13.1 Ball Map

**Figure 33. CYW4373E Ball Map Package: 4.51mm x 5.43mm WLPGA 128 Balls, 0.4 mm Ball Pitch  
Package Bottom View ( Balls Facing Up)**

|   | 11                 | 10                   | 9                   | 8                        | 7                | 6               | 5                 | 4                 | 3                 | 2                 | 1               |   |
|---|--------------------|----------------------|---------------------|--------------------------|------------------|-----------------|-------------------|-------------------|-------------------|-------------------|-----------------|---|
| A |                    | TDN                  | TDP                 | RDN                      | RDP              | SDIO_CLK        | LDO_VDDBA<br>T5V  | VOUT_3P3          | LDO_VDD1<br>P5    | SR_VDDBA<br>T5V   | SR_PVSS         | A |
| B | REFCLKP            | RXTX_AVDD1<br>P2     | PCIE_CLKRE<br>Q_L   | SDIO_DAT<br>A_0          | SDIO_DATA<br>3   | SDIO_DAT<br>A_2 | VOUT_BTLD<br>O2P5 | VOUT_LNLD<br>O    | VOUT_CLD<br>O     | VOUT_HLD<br>O     | SR_VLX          | B |
| C | REFCLKN            | PLL_AVDD1P2          | PCIE_AVSS           | VDDC                     | SDIO_DATA<br>1   | SDIO_CMD        | VSSC              | VOUT_MEM<br>LPLDO | BT_REG_O<br>N     | PMU_AVSS          |                 | C |
| D |                    | RF_SW_CTRL<br>0      | RF_SW_CTR<br>L_1    | PCI_PME_<br>L            | PERST_L          | VDDIO           |                   | WL_REG_ON         | GPIO_4            | GPIO_3            | GPIO_1          | D |
| E | RF_SW_CT<br>RL_6   | AVSS_BBPLL           | AVDD_BBPL<br>L      | RF_SW_CT<br>RL_2         | RF_SW_CTR<br>L_3 |                 | JTAG_SEL          | GPIO_6            | GPIO_5            | VDDC              | GPIO_2          | E |
| F |                    | RF_SW_CTRL<br>5      | VSSC                | VDDC                     | STRAP_0          | STRAP_1         | VSSC              | VDDC_MEM          | GPIO_0            | USB2_MO<br>NPLL   | USB2_DM         | F |
| G | WRF_XTAL<br>XON    | WRF_XTAL_G<br>ND1P2  | RF_SW_CTR<br>L_4    | VDDIO_RF                 | STRAP_2          |                 |                   | BT_VDDO           | USB2_MON<br>CDR   | USB2_AV<br>S      | USB2_DP         | G |
| H | WRF_XTAL<br>_XOP   | WRF_XTAL_V<br>DD1P35 | WRF_XTAL_<br>VDD1P2 | WRF_SYN<br>TH_VDD3<br>P3 |                  |                 | VSSC              | BT_GPIO_3         |                   | USB2_AV<br>D33    | USB2_RRE<br>F   | H |
| J | WRF_PMU<br>VDD1P35 | WRF_SYNT<br>H_VDD1P2 | WRF_SYNT<br>H_GND   | WRF_VCO<br>GND           | VDDC             |                 | VDDC              | BT_VDDC           | VSSC              | LPO_IN            | BT_PCM_I<br>N   | J |
| K | WRF_RX5G<br>GND    | WRF_AFE_V<br>D1P35   | WRF_GENE<br>RAL_GND | WRF_EXT_<br>TSSIA        | VSSC             |                 | BT_GPIO_5         | BT_GPIO_2         | BT_PCM_S<br>YNC   |                   | BT_PCM_C<br>LK  | K |
| L | WRF_RFIN_<br>5G    | WRF_GENE<br>RAL_GND  | WRF_AFE_G<br>ND     | WRF_GPAI<br>O_OUT        | BT_VCOVD<br>D1P2 | BT_VCOVS<br>S   | BT_IFVSS          | CLK_REQ           | BT_PCM_O<br>UT    | BT_DEV_W<br>AKE   | BT_VDDC         | L |
| M | WRF_PAOU<br>T_5G   | WRF_PA_G<br>ND3P3    | WRF_TXMIX<br>VDD    | WRF_RX2<br>G_GND         | BT_LNAVDD<br>1P2 | BT_LNAVSS       | BT_PLLVSS         | BT_VDDC           | BT_HOST_<br>WAKE  | BT_UART_<br>CTS_N | BT_UART_<br>TXD | M |
| N | WRF_PA_V<br>DD3P3  |                      | WRF_PAOU<br>T_2G    | WRF_RFIN<br>_2G          | BT_RF            | BT_PAVDD<br>2P5 | BT_PLLVDD1<br>P2  | BT_IFVDD1P<br>2   | BT_UART_R<br>TS_N | BT_UART_<br>RXD   | VSSC            | N |
|   | 11                 | 10                   | 9                   | 8                        | 7                | 6               | 5                 | 4                 | 3                 | 2                 | 1               |   |



### 13.2 Pin List by Pin Number

Table 17 lists CYW4373E pins by pin number. For a list of CYW4373E pins by pin name, see Table 19.

**Table 17. WLBGA Pin List by Pin Number**

| Ball | Name          |
|------|---------------|
| A1   | SR_PVSS       |
| A2   | SR_VDDBAT5V   |
| A3   | LDO_VDD1P5    |
| A4   | VOUT_3P3      |
| A5   | LDO_VDDBAT5V  |
| A6   | SDIO_CLK      |
| A7   | RDP           |
| A8   | RDN           |
| A9   | TDP           |
| A10  | TDN           |
| A11  | –             |
| B1   | SR_VLX        |
| B2   | VOUT_HLDO     |
| B3   | VOUT_CLDO     |
| B4   | VOUT_LNLDO    |
| B5   | VOUT_BTLD02P5 |
| B6   | SDIO_DATA_2   |
| B7   | SDIO_DATA_3   |
| B8   | SDIO_DATA_0   |
| B9   | PCIE_CLKREQ_L |
| B10  | RXTX_AVDD1P2  |
| B11  | REFCLKP       |
| C1   | –             |
| C2   | PMU_AVSS      |
| C3   | BT_REG_ON     |
| C4   | VOUT_MEMLPLDO |
| C5   | VSSC          |
| C6   | SDIO_CMD      |
| C7   | SDIO_DATA_1   |
| C8   | VDDC          |
| C9   | PCIE_VSS      |
| C10  | PLL_AVDD1P2   |
| C11  | REFCLKN       |
| D1   | GPIO_1        |
| D2   | GPIO_3        |
| D3   | GPIO_4        |
| D4   | WL_REG_ON     |

**Table 17. WLBGA Pin List by Pin Number (Cont.)**

| Ball | Name         |
|------|--------------|
| D5   | –            |
| D6   | VDDIO        |
| D7   | PERDST_L     |
| D8   | PCI_PME_L    |
| D9   | RF_SW_CTRL_1 |
| D10  | RF_SW_CTRL_0 |
| D11  | –            |
| E1   | GPIO_2       |
| E2   | VDDC         |
| E3   | GPIO_5       |
| E4   | GPIO_6       |
| E5   | JTAG_SEL     |
| E6   | –            |
| E7   | RF_SW_CTRL_3 |
| E8   | RF_SW_CTRL_2 |
| E9   | AVDD_BBPLL   |
| E10  | AVSS_BBPLL   |
| E11  | RF_SW_CTRL_6 |
| F1   | USB2_DM      |
| F2   | USB2_MONPLL  |
| F3   | GPIO_0       |
| F4   | VDDC_MEM     |
| F5   | VSSC         |
| F6   | STRAP_1      |
| F7   | STRAP_0      |
| F8   | VDDC         |
| F9   | VSSC         |
| F10  | RF_SW_CTRL_5 |
| F11  | –            |
| G1   | USB2_DP      |
| G2   | USB2_AVSS    |
| G3   | USB2_MONCDR  |
| G4   | BT_VDDO      |
| G5   | –            |
| G6   | –            |
| G7   | STRAP_2      |
| G8   | VDDIO_RF     |
| G9   | RF_SW_CTRL_4 |

**Table 17. WLBGA Pin List by Pin Number (Cont.)**

| Ball | Name             |
|------|------------------|
| G10  | WRF_XTAL_GND1P2  |
| G11  | WRF_XTAL_XON     |
| H1   | USB2_RREF        |
| H2   | USB2_AVDD33      |
| H3   | –                |
| H4   | BT_GPIO_3        |
| H5   | VSSC             |
| H6   | –                |
| H7   | –                |
| H8   | WRF_SYNTH_VDD3P3 |
| H9   | WRF_XTAL_VDD1P2  |
| H10  | WRF_XTAL_VDD1P35 |
| H11  | WRF_XTAL_XOP     |
| J1   | BT_PCM_IN        |
| J2   | LPO_IN           |
| J3   | VSSC             |
| J4   | BT_VDDC          |
| J5   | VDDC             |
| J6   | –                |
| J7   | VDDC             |
| J8   | WRF_VCO_GND      |
| J9   | WRF_SYNTH_GND    |
| J10  | WRF_SYNTH_VDD1P2 |
| J11  | WRF_PMU_VDD1P35  |
| K1   | BT_PCM_CLK       |
| K2   | –                |
| K3   | BT_PCM_SYN       |
| K4   | BT_GPIO_2        |
| K5   | BT_GPIO_5        |
| K6   | –                |
| K7   | VSSC             |
| K8   | WRF_EXT_TSSIA    |
| K9   | WRF_GENERAL_GND  |
| K10  | WRF_AFE_VDD1P35  |
| K11  | WRF_RX5G_GND     |
| L1   | BT_VDDC          |
| L2   | BT_DEV_WAKE      |
| L3   | BT_PCM_OUT       |
| L4   | CLK_REQ          |
| L5   | BT_IFVSS         |
| L6   | BT_VCOVSS        |

**Table 17. WLBGA Pin List by Pin Number (Cont.)**

| Ball | Name             |
|------|------------------|
| L7   | BT_VCOVDD1P2     |
| L8   | WRF_GPAIO_OUT    |
| L9   | WRF_AFE_GND      |
| L10  | WRF_GENERAL2_GND |
| L11  | WRF_RFIN_5G      |
| M1   | BT_UART_TXD      |
| M2   | BT_UART_CTS_N    |
| M3   | BT_HOST_WAKE     |
| M4   | BT_VDDC          |
| M5   | BT_PLLVSS        |
| M6   | BT_LNAVSS        |
| M7   | BT_LNAVDD1P2     |
| M8   | WRF_RX2G_GND     |
| M9   | WRF_TXMIX_VDD    |
| M10  | WRF_PA_GND3P3    |
| M11  | WRF_PAOUT_5G     |
| N1   | VSSC             |
| N2   | BT_UART_RXD      |
| N3   | BT_UART_RTS_N    |
| N4   | BT_IFVDD1P2      |
| N5   | BT_PLLVDD1P2     |
| N6   | BT_PAVDD2P5      |
| N7   | BT_RF            |
| N8   | WRF_RFIN_2G      |
| N9   | WRF_PAOUT_2G     |
| N10  | –                |
| N11  | WRF_PA_VDD3P3    |

### 13.3 Pin Descriptions

The signal name, type, and description of each pin in the CYW4373E is listed in Table 18. The symbols shown under Type indicate pin directions (I/O = bidirectional, I = input, O = output) and the internal pull-up/pull-down characteristics (PU = weak internal pull-up resistor and PD = weak internal pull-down resistor), if any.

**Table 18. Signal Descriptions**

| Signal Name  | WLBGA Ball | Type   | Description  |
|--|------------|--------|--|
| <b>WLAN and Bluetooth Receive RF Signal Interface</b>  |            |        |  |
| WRF_RFIN_2G  | N8         | I      | 2.4 GHz Bluetooth and WLAN receiver shared input.  |
| WRF_RFIN_5G  | L11        | I      | 5 GHz WLAN receiver input.   |
| WRF_PACOUT_2G  | N9         | O      | 2.4 GHz WLAN PA output.  |
| WRF_PACOUT_5G  | M11        | O      | 5 GHz WLAN PA output.  |
| WRF_EXT_TSSIA  | K8         | I      | 5 GHz TSSI input from an optional external power amplifier/power detector.   |
| WRF_GPAIO_OUT  | L8         | I/O    | GPIO or 2.4 GHz TSSI input from an optional external power amplifier/power detector.   |
| <b>RF Switch Control Lines</b>   |            |        |  |
| RF_SW_CTRL_0   | D10        | O      | Programmable RF switch control lines. The control lines are programmable via the driver and NVRAM file.  |
| RF_SW_CTRL_1   | D9         | O      |  |
| RF_SW_CTRL_2   | E8         | O      |  |
| RF_SW_CTRL_3   | E7         | O      |  |
| RF_SW_CTRL_4   | G9         | O      |  |
| RF_SW_CTRL_5   | F10        | O      |  |
| RF_SW_CTRL_6   | E11        | O      |  |
| <b>WLAN PCI Express Interface</b>  |            |        |  |
| PCIE_CLKREQ_L  | B9         | OD     | PCIe clock request signal which indicates when the REFCLK to the PCIe interface can be gated. 1 = the clock can be gated. 0 = the clock is required.   |
| PERST_L  | D7         | I (PU) | PCIe System Reset. This input is the PCIe reset as defined in the <i>PCIe Base Specification Version 1.1</i> .   |
| RDN  | A8         | I      | Receiver differential pair (×1 lane).  |
| RDP  | A7         | I      |  |
| REFCLKN  | C11        | I      | PCIe differential clock inputs (negative and positive), 100 MHz differential.  |
| REFCLKP  | B11        | I      |  |
| TDN  | A10        | O      | Transmitter differential pair (×1 lane).   |
| TDP  | A9         | O      |  |
| PCI_PME_L  | D8         | OD     | PCI power management event output. Used to request a change in the device or system power state. The assertion and deassertion of this signal is asynchronous to the PCIe reference clock. This signal has an open-drain output structure, as per the <i>PCI Bus Local Bus Specification, Revision 2.3</i> . |
| <b>WLAN SDIO Bus Interface</b>   |            |        |  |
| <b>Note:</b> These signals can also have alternate functionality depending on package and host interface mode. |            |        |  |
| SDIO_CLK   | A6         | I      | SDIO clock input.  |
| SDIO_CMD   | C6         | I/O    | SDIO command line.   |
| SDIO_DATA_0  | B8         | I/O    | SDIO data line 0.  |
| SDIO_DATA_1  | C7         | I/O    | SDIO data line 1.  |
| SDIO_DATA_2  | B6         | I/O    | SDIO data line 2.  |
| SDIO_DATA_3  | B7         | I/O    | SDIO data line 3.  |

**Table 18. Signal Descriptions (Cont.)**

| Signal Name   | WLBGA Ball | Type | Description  |
|---|------------|------|--|
| <b>WLAN GPIO Interface</b>  |            |      |  |
| <b>Note:</b> The GPIO signals can be multiplexed via software and the JTAG_SEL pin to behave as various specific functions. |            |      |  |
| GPIO_0  | F3         | I/O  | Programmable GPIO pins:<br>GPIO_2 is TCK/SWCLK if JTAG_SEL = 1<br>GPIO_3 is TMS/SWDIO if JTAG_SEL = 1<br>GPIO_4 is TDIO if JTAG_SEL = 1<br>GPIO_5 is TDO if JTAG_SEL = 1<br>GPIO_6 is TRST_L if JTAG_SEL = 1   |
| GPIO_1  | D1         | I/O  |  |
| GPIO_2  | E1         | I/O  |  |
| GPIO_3  | D2         | I/O  |  |
| GPIO_4  | D3         | I/O  |  |
| GPIO_5  | E3         | I/O  |  |
| GPIO_6  | E4         | I/O  |  |
| <b>JTAG Interface</b>   |            |      |  |
| JTAG_SEL  | E5         | I/O  | JTAG select. This pin must be connected to ground if the JTAG interface is not used. It must be high to select SWD OR JTAG. When JTAG_SEL = 1: <ul style="list-style-type: none"> <li>■ GPIO_2 is TCK</li> <li>■ GPIO_3 is TMS</li> <li>■ GPIO_4 is TDIO</li> <li>■ GPIO_5 is TDO</li> <li>■ GPIO_6 is TRST_L</li> </ul> |
| <b>Clocks</b>   |            |      |  |
| WRF_XTAL_XOP  | H11        | I    | XTAL oscillator input.   |
| WRF_XTAL_XON  | G11        | O    | XTAL oscillator output.  |
| LPO_IN  | J2         | I    | External sleep clock input (32.768 kHz).   |
| CLK_REQ   | L4         | O    | Reference clock request (shared by BT and WLAN).   |
| <b>Bluetooth Transceiver</b>  |            |      |  |
| BT_RF   | N7         | O    | Bluetooth PA output and dLNA input.  |
| <b>Bluetooth PCM</b>  |            |      |  |
| BT_PCM_CLK  | K1         | I/O  | PCM or SLIMbus clock; can be master (output) or slave (input).   |
| BT_PCM_IN   | J1         | I    | PCM data input or SLIMbus transport sensing.   |
| BT_PCM_OUT  | L3         | O    | PCM data output.   |
| BT_PCM_SYNC   | K3         | I/O  | PCM sync; can be master (output) or slave (input), or SLIMbus data.  |
| <b>Bluetooth UART</b>   |            |      |  |
| BT_UART_CTS_N   | M2         | I    | UART clear-to-send. Active-low clear-to-send signal for the HCI UART interface.  |
| BT_UART_RTS_N   | N3         | O    | UART request-to-send. Active-low request-to-send signal for the HCI UART interface. BT LED control pin.  |
| BT_UART_RXD   | N2         | I    | UART serial input. Serial data input for the HCI UART interface. BT RF disable pin 2.  |
| BT_UART_TXD   | M1         | O    | UART serial output. Serial data output for the HCI UART interface.   |
| <b>Bluetooth GPIO</b>   |            |      |  |
| BT_GPIO_2   | K4         | I/O  | Bluetooth general-purpose I/O.   |
| BT_GPIO_3   | H4         | I/O  | Bluetooth general-purpose I/O.   |
| BT_GPIO_5   | K5         | I/O  | Bluetooth general-purpose I/O.   |
| <b>Shared USB 2.0 Interface</b>   |            |      |  |
| USB2_DP   | G1         | IO   | Data plus of shared USB2.0 port.   |
| USB2_DM   | F1         | IO   | Data minus of shared USB2.0 port.  |
| USB2_MONCDR   | G3         | O    | CDR monitor for debug.   |
| USB2_MONPLL   | F2         | O    | PLL monitor for debug purpose.   |

**Table 18. Signal Descriptions (Cont.)**

| Signal Name                            | WLBGA Ball         | Type | Description  |
|--|--------------------|------|--|
| USB2_RREF                              | H1                 | IO   | Bandgap reference resistor; 4.8K ohm +/-5%.  |
| <b>Miscellaneous</b>                   |                    |      |  |
| WL_REG_ON                              | D4                 | I    | Used by PMU to power-up or power down the internal CYW4373E regulators used by the WLAN section. Also, when deasserted, this pin holds the WLAN section in reset. This pin has an internal 200 kΩ pull-down resistor that is enabled by default. It can be disabled through programming.           |
| BT_REG_ON                              | C3                 | I    | Used by PMU to power-up or power down the internal CYW4373E regulators used by the Bluetooth section. Also, when deasserted, this pin holds the Bluetooth section in reset. This pin has an internal 200 kΩ pull-down resistor that is enabled by default. It can be disabled through programming. |
| BT_DEV_WAKE                            | L2                 | I/O  | Bluetooth DEV_WAKE.  |
| BT_HOST_WAKE                           | M3                 | I/O  | Bluetooth HOST_WAKE.   |
| <b>Integrated Voltage Regulators</b>   |                    |      |  |
| SR_VDDBAT5V                            | A2                 | I    | VBAT.  |
| SR_VLX                                 | B1                 | O    | CBUCK switching regulator output. Refer to <a href="#">Table 42</a> for details of the inductor and capacitor required on this output.   |
| LDO_VDD1P5                             | A3                 | I    | LNLDO input.   |
| LDO_VDDBAT5V                           | A5                 | I    | LDO VBAT.  |
| WRF_XTAL_VDD1P35                       | H10                | I    | XTAL LDO input (1.35V).  |
| WRF_XTAL_VDD1P2                        | H9                 | O    | XTAL LDO output (1.2V).  |
| VOUT_LNLDO                             | B4                 | O    | Output of LNLDO.   |
| VOUT_CLDO                              | B3                 | O    | Output of core LDO.  |
| VOUT_BTLDO2P5                          | B5                 | O    | Output of BT LDO.  |
| VOUT_3P3                               | A4                 | O    | LDO 3.3V output.   |
| <b>Bluetooth Supplies</b>              |                    |      |  |
| BT_PAVDD2P5                            | N6                 | PWR  | Bluetooth PA power supply.   |
| BT_LNAVDD1P2                           | M7                 | PWR  | Bluetooth LNA power supply.  |
| BT_IFVDD1P2                            | N4                 | PWR  | Bluetooth IF block power supply.   |
| BT_PLLVDD1P2                           | N5                 | PWR  | Bluetooth RF PLL power supply.   |
| <b>WLAN Supplies</b>                   |                    |      |  |
| WRF_SYNTH_VDD3P3                       | H8                 | PWR  | Synthesizer VDD 3.3V supply.   |
| WRF_PA_VDD3P3                          | N11                | PWR  | 2 GHz and 5 GHz PA 3.3V supply.  |
| WRF_PMU_VDD1P35                        | J11                | PWR  | PMU 1.35V supply.  |
| WRF_TXMIX_VDD                          | M9                 | PWR  | 3.3V supply for the TX Mix.  |
| WRF_SYNTH_VDD1P2                       | J10                | PWR  | 1.2V supply for the synthesizer.   |
| WRF_AFE_VDD1P35                        | K10                | PWR  | 1.35V supply for the AFE.  |
| <b>WLAN STAPs</b>                      |                    |      |  |
| GPIO_15 / STRAP_2                      | G7                 | I    | USB_DISABLE  |
| GPIO_14 / STRAP_1                      | F6                 | I    | PCIE_ENABLE  |
| GPIO_13 / STRAP_0/<br>STRAP_XTAL_SEL_1 | F7                 | I    | "SDIO_PADVDDIO sel, XTAL sel in USB mode   |
| <b>Miscellaneous Supplies</b>          |                    |      |  |
| VDDC                                   | C8, E2, F8, J5, J7 | PWR  | 1.2V core supply for the WLAN.   |
| VDDIO                                  | D6                 | PWR  | 1.8V–3.3V VDDIO supply for the WLAN. Must be directly connected to BT_VDDO on the PCB.   |

**Table 18. Signal Descriptions (Cont.)**

| Signal Name  | WLBGA Ball         | Type | Description   |
|--|--------------------|------|---|
| BT_VDDC  | M4, J4, L1         | PWR  | 1.2V core supply for the BT.  |
| BT_VDDO  | G4                 | PWR  | 1.8V–3.3V VDDIO supply for the BT. Must be directly connected to VDDIO on the PCB.  |
| VDDIO  | D6                 | PWR  | 1.8V–3.3V supply for the SDIO pads.   |
| VDDIO_RF   | G8                 | PWR  | IO supply for the RF switch control pads (3.3V).  |
| AVDD_BBPLL   | E9                 | PWR  | 1.2V supply for the baseband PLL.   |
| PLL_AVDD1P2  | C10                | PWR  | 1.2V supply for the PCIe PLL.   |
| VOUT_HLDO  | B2                 | PWR  | 1.2V supply for the PCIe.   |
| RXTX_AVDD1P2   | B10                | PWR  | 1.2V supply for the PCIe TX/RX.   |
| <b>Ground</b>  |                    |      |   |
| WRF_VCO_GND  | J8                 | GND  | VCO/LOGEN ground.   |
| WRF_AFE_GND  | L9                 | GND  | AFE ground.   |
| WRF_XTAL_GND1P2  | G10                | GND  | XTAL ground.  |
| WRF_RX2G_GND   | M8                 | GND  | RX 2 GHz ground.  |
| WRF_RX5G_GND   | K11                | GND  | RX 5 GHz ground.  |
| WRF_PA_GND3P3  | M10                | GND  | PA ground.  |
| WRF_GENERAL_GND  | K9                 | GND  | General ground.   |
| WRF_GENERAL2_GND   | L10                | GND  | General ground.   |
| WRF_SYNTH_GND  | J9                 | GND  | Ground.   |
| VSSC   | C5, F5, F9, J3, K7 | GND  | Core ground for WLAN and BT.  |
| VSSC (Previously BT_GPIO_4)  | H5                 | GND  | Must be shorted to Ground on PCB. Usage of this GPIO will lead to higher current consumption due to leakage in lower power modes. |
| SR_PVSS  | A1                 | GND  | Power ground.   |
| PMU_AVSS   | C2                 | GND  | Quiet ground.   |
| BT_LNAVSS  | M6                 | GND  | Bluetooth LNA ground.   |
| BT_IFVSS   | L5                 | GND  | Bluetooth IF block ground.  |
| BT_PLLVSS  | M5                 | GND  | Bluetooth PLL ground.   |
| AVSS_BBPLL   | E10                | GND  | Baseband PLL ground.  |
| PCI_VSS  | C9                 | GND  | PCIe ground.  |
| <b>Depopulated Pins</b>  |                    |      |   |
| A11, C1, D5, D11, E6, F11, G5, G6, H3, H6, H7, J6, K2, K6, and N10 | –                  | –    | –   |

### 13.4 WLAN GPIO Signals and Strapping Options

This section describes WLAN GPIO signals and strapping options. The pins are sampled at power-on reset (POR) to determine the various operating modes. Sampling occurs a few milliseconds after an internal POR or deassertion of the external POR. After the POR, each pin assumes the GPIO or alternative function specified in the signal descriptions table. Each strapping option pin has an internal pull-up (PU) or pull-down (PD) resistor that determines the default mode. To change the mode, connect an external PU resistor to VDDIO or a PD resistor to GND, using a 10 kΩ resistor or less.

**Note:** Refer to the reference board schematics for more information.

**Table 19. Strap Pins**

| Pad/Ball                           | Default Pull | Functionality                           |
|------------------------------------|--------------|---|
| GPIO_15 / STRAP_2                  | 1            | USB_DISABLE                             |
| GPIO_14 / STRAP_1                  | 1            | PCIe_ENABLE, USBHUB_BYPASS              |
| GPIO_13 / STRAP_0/STRAP_XTAL_SEL_1 | 1            | SDIO_PADVDDIO_sel, XTAL sel in USB MODE |

- Strapping options are defined such a way that defaults are having internal PULL UPs, so that it is easy to configure the strap value in opposite manner on board (it is simple to short to GND on board ,there is no need for a pull down resistor).
- SDIO is mode is available by default in all the below combinations. In “SDIO only” mode OTP for SDIO is available. OTP for SDIO CIS TUPLES will not be available in other modes. Need to use default CIS tuples for other modes.

**Table 20. Strapping Options**

| USB_DISABLE<br>STRAP_2<br>GPIO_15 | PCIe_ENABLE_STRAP_1<br>STRAP_1 GPIO_14 | SDIO_PADVDDIO<br>STRAP_0 GPIO_13     | Mode Selected | SDIO OTP<br>present |
|-----------------------------------|--|--------------------------------------|---------------|---------------------|
| 0                                 | 0                                      | 0                                    | USB           | 0                   |
| 1                                 | 0                                      | 0 = SDIO is 3.3V<br>1 = SDIO is 1.8V | SDIO only     | 1                   |
| 1                                 | 1                                      |                                      | PCIe          | 0                   |

### 13.5 XTAL Selection Table for WLBGA in USB mode

**Note:** In USB mode, SDIO pads would come up in 3.3V mode only. There is no option for SDIO pads to powerup with 1.8V mode. In non-USB mode (SDIO), SDIO pads supports both 1.8v and 3.3v signaling.

**Table 21. XTAL selection with WLBGA package**

| GPIO_13/STRAP_0/STRAP_XTAL_SEL0 | XTAL value (MHz) |
|---------------------------------|------------------|
| 0                               | 37.4             |

13.5.1 Multiplexed WLAN GPIO Signals

**Table 22. Multiplexed WLAN GPIO Signals**

|                     | HWDecided/<br>PowerONDefault   | SameAsPin<br>Name        | GPIO-0  | FAST_UART/<br>GPIO_1  | GCI-0      | GCI-1       | DBG_UART    | SFLASH      | SPROM | MISC-0        | MISC-1         | MISC-2           |
|---------------------|--|--------------------------|---------|-----------------------|------------|-------------|-------------|-------------|-------|---------------|----------------|------------------|
| Pin/Function<br>Sel | 0  | 1                        | 2       | 3                     | 4          | 5           | 6           | 7           | 8     | 9             | 10             | 11               |
| GPIO_0              | TRISTATE_IND   | WL_HOST_ WAKE/<br>GPIO_0 | GPIO_8  |                       | GCI_GPIO_0 | GCI_GPIO_11 |             |             |       |               | SDIO_SEP_ INT_ | SDIO_SEP_ INT_OD |
| GPIO_1              | TRISTATE_IND   | WL_DEV_ WAKE/<br>GPIO_1  | GPIO_9  |                       | GCI_GPIO_1 | GCI_GPIO_12 |             |             |       | RF_DISABLE_ L |                |                  |
| GPIO_2              | JTAG_SEL?TCK:<br>TRISTATE_IND  | GPIO_2                   | GPIO_10 | FAST_UART_RX          | GCI_GPIO_2 | GCI_GPIO_13 |             |             |       | TCK           |                |                  |
| GPIO_3              | JTAG_SEL?TMS:<br>TRISTATE_IND  | GPIO_3                   | GPIO_11 | FAST_UART_TX          | GCI_GPIO_3 | GCI_GPIO_14 |             |             |       | TMS           |                |                  |
| GPIO_4              | JTAG_SEL?TDI:T<br>RISTATE_IND  | GPIO_4                   | GPIO_12 | FAST_UART_CT<br>S_IN  | GCI_GPIO_4 | GCI_GPIO_15 | UART_DBG_RX |             |       | TDI           |                |                  |
| GPIO_5              | JTAG_SEL?TDO:<br>TRISTATE_IND  | GPIO_5                   | GPIO_13 | FAST_UART_RT<br>S_OUT | GCI_GPIO_0 | GCI_GPIO_5  | UART_DBG_TX |             |       | TDO           |                |                  |
| GPIO_6              | JTAG_SEL?TRST<br>L:TRISTATE_IN<br>D  | GPIO_6                   | GPIO_14 |                       | GCI_GPIO_1 | GCI_GPIO_6  |             |             |       | TRST_L        |                |                  |
| GPIO_13             | TRISTATE_IND   | GPIO_13                  | GPIO_5  |                       | GCI_GPIO_3 | GCI_GPIO_13 |             |             |       |               |                |                  |
| GPIO_14             | TRISTATE_IND   | GPIO_14                  | GPIO_6  |                       | GCI_GPIO_4 | GCI_GPIO_14 |             |             |       |               |                |                  |
| GPIO_15             | TRISTATE_IND   | GPIO_15                  | GPIO_7  |                       |            | GCI_GPIO_15 |             |             |       |               |                |                  |
| SDIO_CLK            | TEST_MODE?<br>TEST_SDIO_CLK<br>:<br>SDIO_EN?SDIO<br>CLK:TRISTATE_I<br>ND       | SDIO_CLK                 |         |                       |            |             |             |             |       | SDIO_AOS_ CLK |                |                  |
| SDIO_CMD            | TEST_MODE?<br>TEST_SDIO_CM<br>D:<br>SDIO_EN?SDIO<br>CMD:TRISTATE_I<br>ND       | SDIO_CMD                 | GPIO_11 |                       | GCI_GPIO_0 |             |             | SFLASH_ CS# |       | SDIO_AOS_ CMD |                |                  |
| SDIO_DATA_ 0        | TEST_MODE?<br>TEST_SDIO_DAT<br>A_0:<br>SDIO_EN?SDIO<br>DATA_0:TRISTAT<br>E_IND | SDIO_D0                  | GPIO_12 |                       | GCI_GPIO_1 |             |             | SFLASH_ CLK |       | SDIO_AOS_ D0  |                |                  |



**Table 22. Multiplexed WLAN GPIO Signals (Cont.)**

|                | HWDecided/<br>PowerONDefault  | SameAsPin<br>Name | GPIO-0  | FAST_UART/<br>GPIO_1 | GCI-0      | GCI-1       | DBG_UART    | SFLASH      | SPROM | MISC-0      | MISC-1   | MISC-2 |
|----------------|---|-------------------|---------|----------------------|------------|-------------|-------------|-------------|-------|-------------|----------|--------|
| SDIO_DATA_1    | TEST_MODE?<br>TEST_SDIO_DATA_1:<br>SDIO_EN?SDIO_DATA_1:TRISTATE_IND | SDIO_D1           | GPIO_13 |                      | GCI_GPIO_2 |             |             | SFLASH_MISO |       | SDIO_AOS_D1 |          |        |
| SDIO_DATA_2    | TEST_MODE?<br>TEST_SDIO_DATA_2:<br>SDIO_EN?SDIO_DATA_2:TRISTATE_IND | SDIO_D2           | GPIO_14 |                      | GCI_GPIO_3 |             |             |             |       | SDIO_AOS_D2 |          |        |
| SDIO_DATA_3    | TEST_MODE?<br>TEST_SDIO_DATA_3:<br>SDIO_EN?SDIO_DATA_3:TRISTATE_IND | SDIO_D3           | GPIO_15 |                      | GCI_GPIO_4 |             |             | SFLASH_MOSI |       | SDIO_AOS_D3 |          |        |
| RF_SW_CTL_RL_0 | RF_SW_CTRL_0  | RF_SW_CTL_RL_0    |         |                      |            |             |             |             |       |             |          |        |
| RF_SW_CTL_RL_1 | RF_SW_CTRL_1  | RF_SW_CTL_RL_1    |         |                      |            |             |             |             |       |             |          |        |
| RF_SW_CTL_RL_2 | RF_SW_CTRL_2  | RF_SW_CTL_RL_2    |         |                      |            |             |             |             |       |             |          |        |
| RF_SW_CTL_RL_3 | RF_SW_CTRL_3  | RF_SW_CTL_RL_3    | GPIO_8  | GPIO_0               |            | GCI_GPIO_8  |             |             |       | PALDO_PD    |          |        |
| RF_SW_CTL_RL_4 | RF_SW_CTRL_4  | RF_SW_CTL_RL_4    | GPIO_9  | GPIO_1               |            | GCI_GPIO_9  |             |             |       | PALDO_PU    |          |        |
| RF_SW_CTL_RL_5 | RF_SW_CTRL_5  | RF_SW_CTL_RL_5    | GPIO_10 | GPIO_2               |            | GCI_GPIO_10 | UART_DBG_RX |             |       |             |          |        |
| RF_SW_CTL_RL_6 | RF_SW_CTRL_6  | RF_SW_CTL_RL_6    | GPIO_11 | GPIO_3               |            | GCI_GPIO_11 | UART_DBG_TX |             |       |             | PALDO_PU |        |

**13.6 I/O States**

The following notations are used in [Table 23](#).

- I: Input signal
- O: Output signal
- I/O: Input/Output signal
- PU = Pulled up (39.58kOhm resistance<sup>[12]</sup>)
- PD = Pulled down (44.57kOhm resistance<sup>[12]</sup>)
- NoPull = Neither pulled up nor pulled down

**Table 23. I/O States**

| Name          | I/O | Keeper<br>[12] | Active Mode  | Low Power State/Sleep<br>(All Power Present)        | Power-down <sup>[13]</sup><br>(BT_REG_ON and WL_REG_ON Held Low) | Out-of-Reset;<br>Before SW Download<br>(BT_REG_ON High;<br>WL_REG_ON High) | (WL_REG_ON High and BT_REG_ON = 0) and VDDIOs Are Present | Power Rail |
|---------------|-----|----------------|--|---|--|--|---|------------|
| WL_REG_ON     | I   | N              | Input; PD (pull-down can be disabled)                | Input; PD (pull-down can be disabled)               | Input; PD (of 200K)  | Input; PD (of 200K)  | Input; PD (of 200K)                                       | –          |
| BT_REG_ON     | I   | N              | Input; PD (pull down can be disabled)                | Input; PD (pull down can be disabled)               | Input; PD (of 200K)  | Input; PD (of 200K)  | Input; PD (of 200K)                                       | –          |
| CLK_REQ       | O   | Y              | Open drain or push-pull (programmable). Active high. | Open drain or push-pull (programmable). Active high | High-Z, NoPull   | Open drain. Active high  | PD  | BT_VDDO    |
| BT_HOST_WAKE  | O   | Y              | Input/Output; PU, PD, NoPull (programmable)          | Input/Output; PU, PD, NoPull (programmable)         | High-Z, NoPull   | Input, No Pull   | High-Z, NoPull  | BT_VDDO    |
| BT_DEV_WAKE   | I   | Y              | Input/Output; PU, PD, NoPull (programmable)          | Input; PU, PD, NoPull (programmable)                | High-Z, NoPull   | Input, PD  | High-Z, NoPull  | BT_VDDO    |
| BT_GPIO_2     | I/O | Y              | Input/Output; PU, PD, NoPull (programmable)          | Input/Output; PU, PD, NoPull (programmable)         | High-Z, NoPull   | Input, PD  | High-Z, NoPull  | BT_VDDO    |
| BT_GPIO_3     | I/O | Y              | Input/Output; PU, PD, NoPull (programmable)          | Input/Output; PU, PD, NoPull (programmable)         | High-Z, NoPull   | Input, PD  | PD  | BT_VDDO    |
| BT_GPIO_5     | I/O | Y              | Input/Output; PU, PD, NoPull (programmable)          | Input/Output; PU, PD, NoPull (programmable)         | High-Z, NoPull   | Input, PU  | High-Z, No Pull   | BT_VDDO    |
| BT_UART_CTS_N | I   | Y              | Input; NoPull  | Input; NoPull                                       | High-Z, NoPull   | Input; PU  | High-Z, No Pull   | BT_VDDO    |
| BT_UART_RTS_N | O   | Y              | Output; NoPull                                       | Output; NoPull                                      | High-Z, NoPull   | Input; PU  | High-Z, No Pull   | BT_VDDO    |

**Notes**

12. Typical value from simulation data with VDDO=3.3V +/- 10%.
13. In the power-down state (xx\_REG\_ON=0): High-Z; NoPull => the pad is disabled because power is not supplied.
14. Depending on whether the PCM interface is enabled and the configuration of PCM is in master or slave mode, it can be either Output or input.
15. NoPull when in SDIO mode.

**Table 23. I/O States (Cont.)**

| Name           | I/O | Keeper [12] | Active Mode   | Low Power State/Sleep (All Power Present)                     | Power-down <sup>[13]</sup> (BT_REG_ON and WL_REG_ON Held Low) | Out-of-Reset; Before SW Download (BT_REG_ON High; WL_REG_ON High) | (WL_REG_ON High and BT_REG_ON = 0) and VDDIOs Are Present | Power Rail |
|----------------|-----|-------------|---|---|---|---|---|------------|
| BT_UART_RXD    | I   | Y           | Input; PU   | Input; NoPull   | High-Z, NoPull  | Input; PU   | High-Z, No Pull   | BT_VDDO    |
| BT_UART_TXD    | O   | Y           | Output; NoPull  | Output; NoPull  | High-Z, NoPull  | Input; PU   | High-Z, No Pull   | BT_VDDO    |
| SDIO_DATA[0:3] | I/O | N           | Input/Output; PU (SDIO Mode)                                  | Input; PU (SDIO Mode)   | High-Z, NoPull  | Input; PU (SDIO Mode)   | Input; PU (SDIO Mode)                                     | VDDIO      |
| SDIO_CMD       | I/O | N           | Input/Output; PU (SDIO Mode)                                  | Input; PU (SDIO Mode)   | High-Z, NoPull  | Input; PU (SDIO Mode)   | Input; PU (SDIO Mode)                                     | VDDIO      |
| SDIO_CLK       | I   | N           | Input; NoPull   | Input; noPull   | High-Z, NoPull  | Input; noPull   | High-Z, No Pull   | VDDIO      |
| BT_PCM_CLK     | I/O | Y           | Input; NoPull <sup>[14]</sup>                                 | Input; NoPull <sup>[14]</sup>                                 | High-Z, NoPull  | Input, PD   | High-Z, No Pull   | BT_VDDO    |
| BT_PCM_IN      | I/O | Y           | Input; NoPull <sup>[14]</sup>                                 | Input; NoPull <sup>[14]</sup>                                 | High-Z, NoPull  | Input, PD   | High-Z, No Pull   | BT_VDDO    |
| BT_PCM_OUT     | I/O | Y           | Input; NoPull <sup>[14]</sup>                                 | Input; NoPull <sup>[14]</sup>                                 | High-Z, NoPull  | Input, PD   | PD  | BT_VDDO    |
| BT_PCM_SYNC    | I/O | Y           | Input; NoPull <sup>[14]</sup>                                 | Input; NoPull <sup>[14]</sup>                                 | High-Z, NoPull  | Input, PD   | Input, PD   | BT_VDDO    |
| GPIO_0         | I/O | Y           | Input/Output; PU, PD, NoPull (programmable [Default: PD])     | Input/Output; PU, PD, NoPull (programmable [Default: PD])     | High-Z, NoPull  | Input; PD   | Input; PD   | VDDIO      |
| GPIO_1         | I/O | Y           | Input/Output; PU, PD, NoPull (programmable [Default: NoPull]) | Input/Output; PU, PD, NoPull (programmable [Default: NoPull]) | High-Z, NoPull  | Input; NoPull   | Input; NoPull   | VDDIO      |
| GPIO_2         | I/O | Y           | Input/Output; PU, PD, NoPull (programmable [Default: NoPull]) | Input/Output; PU, PD, NoPull (programmable [Default: NoPull]) | High-Z, NoPull  | Input; NoPull   | Input; NoPull   | VDDIO      |
| GPIO_3         | I/O | Y           | Input/Output; PU, PD, NoPull (programmable [Default: PD])     | Input/Output; PU, PD, NoPull (programmable [Default: PD])     | High-Z, NoPull  | Input; PD   | Input; PD   | VDDIO      |
| GPIO_4         | I/O | Y           | Input/Output; PU, PD, NoPull (programmable [Default: NoPull]) | Input/Output; PU, PD, NoPull (programmable [Default: NoPull]) | High-Z, NoPull  | Input; NoPull   | Input; NoPull   | VDDIO      |
| GPIO_5         | I/O | Y           | Input/Output; PU, PD, NoPull (programmable [Default: PD])     | Input/Output; PU, PD, NoPull (programmable [Default: PD])     | High-Z, NoPull  | Input; PD   | Input; PD   | VDDIO      |

**Notes**

12. Typical value from simulation data with VDDO=3.3V +/- 10%.

13. In the power-down state (xx\_REG\_ON=0): High-Z; NoPull => the pad is disabled because power is not supplied.

14. Depending on whether the PCM interface is enabled and the configuration of PCM is in master or slave mode, it can be either Output or input.

15. NoPull when in SDIO mode.

**Table 23. I/O States (Cont.)**

| Name            | I/O | Keeper<br>[12] | Active Mode   | Low Power<br>State/Sleep<br>(All Power Present)                                 | Power-down <sup>[13]</sup><br>(BT_REG_ON and<br>WL_REG_ON Held<br>Low) | Out-of-Reset;<br>Before SW Download<br>(BT_REG_ON High;<br>WL_REG_ON High) | (WL_REG_ON<br>BT_REG_ON<br>VDDIOs) |
|-----------------|-----|----------------|---|---|--|--|------------------------------------|
| GPIO_6          | I/O | Y              | Input/Output; PU, PD,<br>NoPull (programmable<br>[Default: NoPull])             | Input/Output; PU, PD,<br>NoPull (programmable<br>[Default: NoPull])             | High-Z, NoPull   | Input; NoPull  | Input; NoPull                      |
| STRAP_0         | I/O | Y              | Input/Output; PU, PD,<br>NoPull (programmable<br>[Default: NoPull])             | Input/Output; PU, PD,<br>NoPull (programmable<br>[Default: NoPull])             | High-Z, NoPull   | Input; NoPull  | Input; NoPull                      |
| STRAP_1         | I/O | Y              | Input/Output; PU, PD,<br>NoPull (programmable<br>[Default: PD]) <sup>[15]</sup> | Input/Output; PU, PD,<br>NoPull (programmable<br>[Default: PD]) <sup>[15]</sup> | High-Z, NoPull   | Input; PD <sup>[15]</sup>  | Input; PD <sup>[15]</sup>          |
| STRAP_2         | I/O | Y              | Input/Output; PU, PD,<br>NoPull (programmable<br>[Default: PD])                 | Input/Output; PU, PD,<br>NoPull (programmable<br>[Default: PD])                 | High-Z, NoPull   | Input; PD  | Input; PD                          |
| RF_SW_CTRL[0:6] | I/O | Y              | Output; NoPull  | Output; NoPull  | High-Z   | Output; NoPull   | Output; NoPull                     |

**Notes**

- 12. Typical value from simulation data with VDDO=3.3V +/- 10%.
- 13. In the power-down state (xx\_REG\_ON=0): High-Z; NoPull => the pad is disabled because power is not supplied.
- 14. Depending on whether the PCM interface is enabled and the configuration of PCM is in master or slave mode, it can be either Output or input.
- 15. NoPull when in SDIO mode.

## 14. DC Characteristics

**Note:** Values in this data sheet are design goals and are subject to change based on the results of device characterization.

### 14.1 Absolute Maximum Ratings

**Caution!** The absolute maximum ratings in Table 24 indicate levels where permanent damage to the device can occur, even if these limits are exceeded for only a brief duration. Functional operation is not guaranteed under these conditions. Operation at absolute maximum conditions for extended periods can adversely affect long-term reliability of the device.

**Table 24. Absolute Maximum Ratings**

| Rating   | Symbol                  | Value                        | Unit |
|--|-------------------------|------------------------------|------|
| DC supply for the VBAT supply                      | VBAT                    | -0.5 to +5.5 <sup>[16]</sup> | V    |
| DC supply voltage for digital I/O                  | VDDIO, BT_VDDO          | -0.5 to 3.9                  | V    |
| DC supply voltage for RF switch I/Os               | VDDIO_RF                | -0.5 to 3.9                  | V    |
| DC input supply voltage for CLDO and LNLDO         | –                       | -0.5 to 1.575                | V    |
| DC supply voltage for RF analog                    | VDDRF                   | -0.5 to 1.32                 | V    |
| DC supply voltage for core                         | VDDC, BT_VDDC           | -0.5 to 1.32                 | V    |
| Maximum undershoot voltage for I/O <sup>[17]</sup> | V <sub>undershoot</sub> | -0.5                         | V    |
| Maximum overshoot voltage for I/O <sup>[17]</sup>  | V <sub>overshoot</sub>  | VDDIO + 0.5                  | V    |
| Maximum junction temperature                       | T <sub>j</sub>          | 125                          | °C   |

**Notes**

16. Non-switching voltages of up to 5.5V can be tolerated for up to 10 seconds, cumulative duration over the lifetime of the device.

17. Duration not to exceed 25% of the duty cycle.

## 14.2 Environmental Ratings

The environmental ratings are shown in [Table 25](#).

**Table 25. Environmental Ratings**

| Characteristics               | Value        | Unit | Conditions/Comments  |
|-------------------------------|--------------|------|----------------------|
| Ambient Temperature ( $T_A$ ) | -40 to +85   | °C   | Functional operation |
| Storage Temperature           | -40 to +125  | °C   | –                    |
| Relative Humidity             | Less than 60 | %    | Storage              |
|                               | Less than 85 | %    | Operation            |

## 14.3 Electrostatic Discharge Specifications

Extreme caution must be exercised to prevent electrostatic discharge (ESD) damage. Proper use of wrist and heel grounding straps to discharge static electricity is required when handling these devices. Always store unused material in its antistatic packaging.

**Table 26. ESD Specifications**

| Pin Type  | Symbol       | Conditions  | Minimum ESD Rating  | Unit |
|---|--------------|---|---------------------|------|
| ESD:<br>Handling Reference: NQY00083,<br>Section 3.4, Group D9, Table B | ESD_HAND_HBM | Human body model contact discharge per<br>AEC-Q100-002 Rev-E      | 2                   | kV   |
| CDM   | ESD_HAND_CDM | Charged device model contact discharge per<br>AEC-Q100-011 Rev-C1 | 250 <sup>[18]</sup> | V    |

**Note**

18. The WRF\_PAOUT\_2G is specified to +200V/-250V.

**14.4 Recommended Operating Conditions and DC Characteristics**

**Caution!** Functional operation is not guaranteed outside of the limits shown in Table 27. Operation outside these limits for extended periods can adversely affect long-term reliability of the device.

**Note:** For DC absolute maximum rating (AMR), see Table 24.

**Table 27. Recommended Operating Conditions and DC Characteristics**

| Parameter   | Symbol           | Value                |         |                     | Unit |
|---|------------------|----------------------|---------|---------------------|------|
|   |                  | Min                  | Typ     | Max                 |      |
| DC supply voltage for VBAT                          | VBAT             | 3.13 <sup>[19]</sup> | 3.3     | 3.5 <sup>[20]</sup> | V    |
| DC supply voltage for core                          | VDDC, BT_VDDC    | 1.14                 | 1.2     | 1.26                | V    |
| DC supply voltage for RF blocks in chip             | VDDRF            | 1.14                 | 1.2     | 1.26                | V    |
| DC supply voltage for digital I/O                   | VDDIO, BT_VDDO   | 1.62                 | 1.8/3.3 | 3.63                | V    |
| DC supply voltage for RF switch I/Os                | VDDIO_RF         | 3.13                 | 3.3     | 3.46                | V    |
| External TSSI input                                 | TSSI             | 0.15                 | –       | 0.95                | V    |
| Internal POR threshold                              | Vth_POR          | 0.4                  | –       | 0.7                 | V    |
| <b>Other Digital I/O Pins</b>                       |                  |                      |         |                     |      |
| For VDDIO, BT_VDDO = 1.8V:                          |                  |                      |         |                     |      |
| Input high voltage                                  | VIH              | 0.65 × VDDIO         | –       | –                   | V    |
| Input low voltage                                   | VIL              | –                    | –       | 0.35 × VDDIO        | V    |
| Output high voltage @ 2 mA                          | VOH              | VDDIO – 0.45         | –       | –                   | V    |
| Output low voltage @ 2 mA                           | VOL              | –                    | –       | 0.45                | V    |
| For VDDIO, BT_VDDO = 3.3V:                          |                  |                      |         |                     |      |
| Input high voltage                                  | VIH              | 2.00                 | –       | –                   | V    |
| Input low voltage                                   | VIL              | –                    | –       | 0.80                | V    |
| Output high voltage @ 2 mA                          | VOH              | VDDIO – 0.4          | –       | –                   | V    |
| Output low Voltage @ 2 mA                           | VOL              | –                    | –       | 0.40                | V    |
| <b>RF Switch Control Output Pins<sup>[21]</sup></b> |                  |                      |         |                     |      |
| For VDDIO_RF = 3.3V:                                |                  |                      |         |                     |      |
| Output high voltage @ 2 mA                          | VOH              | VDDIO – 0.4          | –       | –                   | V    |
| Output low voltage @ 2 mA                           | VOL              | –                    | –       | 0.40                | V    |
| Output capacitance                                  | C <sub>OUT</sub> | –                    | –       | 5                   | pF   |

**Notes**

19. The CYW4373E is functional across this range of voltages. Optimal RF performance specified in the data sheet, however, is guaranteed only for VBAT = 3.3V +/- 5%.

20. The maximum continuous voltage is 4.8V.

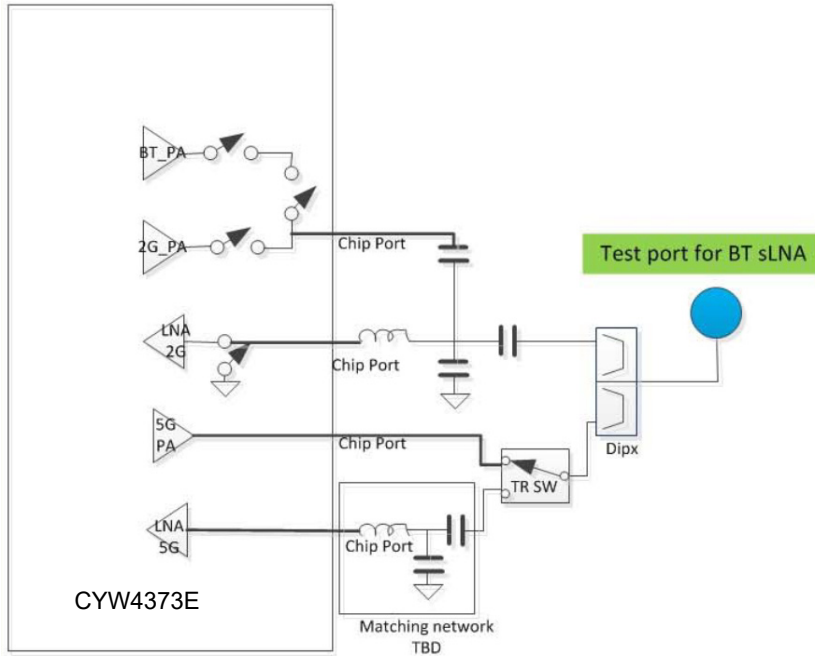
21. Programmable 2 mA to 16 mA drive strength. Default is 10 mA.

## 15. Bluetooth RF Specifications

Unless otherwise stated, limit values apply for the conditions specified in [Table 25 “Environmental Ratings”](#) and [Table 27 “Recommended Operating Conditions and DC Characteristics”](#). Typical values apply for the following conditions:

- VBAT = 3.3V
- Ambient temperature +25°C

**Figure 34. Port Locations for Bluetooth Testing**



**Note:** Unless otherwise specified, all Bluetooth RF specifications are provided at the Chip Port. Measurements are made at Test Points and referenced back to the Chip Ports.



**Table 28. Bluetooth Receiver RF Specifications**

| Parameter   | Conditions                        | Min  | Typ   | Max  | Unit |
|---|-----------------------------------|------|-------|------|------|
| <b>Note:</b> Unless otherwise specified, all Bluetooth RF specifications are provided at the Chip Port. |                                   |      |       |      |      |
| <b>General</b>  |                                   |      |       |      |      |
| Frequency range   | –                                 | 2402 | –     | 2480 | MHz  |
| RX sensitivity <sup>[22]</sup>  | GFSK, 0.1% BER, 1 Mbps            | –    | –93.0 | –    | dBm  |
|   | $\pi/4$ -DQPSK, 0.01% BER, 2 Mbps | –    | –95.0 | –    | dBm  |
|   | 8-DPSK, 0.01% BER, 3 Mbps         | –    | –89.0 | –    | dBm  |
| Input IP3   | –                                 | –16  | –     | –    | dBm  |
| Maximum input at RF port  | –                                 | –    | –     | –20  | dBm  |
| <b>RX LO Leakage</b>  |                                   |      |       |      |      |
| 2.4 GHz band  | –                                 | –    | –90   | –    | dBm  |
| <b>Interference Performance<sup>[23]</sup></b>  |                                   |      |       |      |      |
| C/I co-channel  | GFSK, 0.1% BER                    | –    | 9     | 11   | dB   |
| C/I 1 MHz adjacent channel  | GFSK, 0.1% BER                    | –    | –5.5  | 0    | dB   |
| C/I 2 MHz adjacent channel  | GFSK, 0.1% BER                    | –    | –38.0 | –30  | dB   |
| C/I $\geq$ 3 MHz adjacent channel   | GFSK, 0.1% BER                    | –    | –46.0 | –40  | dB   |
| C/I image channel   | GFSK, 0.1% BER                    | –    | –25.5 | –9   | dB   |
| C/I 1-MHz adjacent to image channel   | GFSK, 0.1% BER                    | –    | –39.0 | –20  | dB   |
| C/I co-channel  | $\pi/4$ -DQPSK, 0.1% BER          | –    | 10.5  | 13   | dB   |
| C/I 1 MHz adjacent channel  | $\pi/4$ -DQPSK, 0.1% BER          | –    | –6.0  | 0    | dB   |
| C/I 2 MHz adjacent channel  | $\pi/4$ -DQPSK, 0.1% BER          | –    | –38.5 | –30  | dB   |
| C/I $\geq$ 3 MHz adjacent channel   | $\pi/4$ -DQPSK, 0.1% BER          | –    | –47.0 | –40  | dB   |
| C/I image channel   | $\pi/4$ -DQPSK, 0.1% BER          | –    | –24.5 | –7   | dB   |
| C/I 1 MHz adjacent to image channel   | $\pi/4$ -DQPSK, 0.1% BER          | –    | –43.0 | –20  | dB   |
| C/I co-channel  | 8-DPSK, 0.1% BER                  | –    | 17.5  | 21   | dB   |
| C/I 1 MHz adjacent channel  | 8-DPSK, 0.1% BER                  | –    | –3.0  | 5    | dB   |
| C/I 2 MHz adjacent channel  | 8-DPSK, 0.1% BER                  | –    | –37.5 | –25  | dB   |
| C/I $\geq$ 3 MHz adjacent channel   | 8-DPSK, 0.1% BER                  | –    | –39.5 | –33  | dB   |
| C/I Image channel   | 8-DPSK, 0.1% BER                  | –    | –17   | 0    | dB   |
| C/I 1 MHz adjacent to image channel   | 8-DPSK, 0.1% BER                  | –    | –37.0 | –13  | dB   |
| <b>Out-of-Band Blocking Performance (CW)</b>  |                                   |      |       |      |      |
| 30–2000 MHz   | 0.1% BER                          | –    | –10   | –    | dBm  |
| 2000–2399 MHz   | 0.1% BER                          | –    | –27   | –    | dBm  |
| 2498–3000 MHz   | 0.1% BER                          | –    | –27   | –    | dBm  |
| 3000 MHz–12.75 GHz  | 0.1% BER                          | –    | –10   | –    | dBm  |
| <b>Out-of-Band Blocking Performance, Modulated Interferer</b>   |                                   |      |       |      |      |
| <b>GFSK (1 Mbps)<sup>[24]</sup></b>   |                                   |      |       |      |      |
| 698–716 MHz   | WCDMA                             | –    | 19    | –    | dBm  |
| 776–849 MHz   | WCDMA                             | –    | 20    | –    | dBm  |

**Notes**

- 22. Dirty TX is OFF.
- 23. The maximum value represents the actual Bluetooth specification required for Bluetooth qualification as defined in the version 5.0 specification.
- 24. 3dB receiver desense. Band pass filter (2400~2500MHz) is installed at BT RF front end. The insertion loss at 2440MHz is about 1.2dB.
- 25. 2560 MHz performance is used.
- 26. 2360 MHz performance is used.
- 27. 2580 MHz performance is used.
- 28. 2555 MHz performance is used.

**Table 28. Bluetooth Receiver RF Specifications (Cont.)**

| Parameter  | Conditions | Min | Typ | Max | Unit |
|--|------------|-----|-----|-----|------|
| 824–849 MHz  | GSM850     | –   | 21  | –   | dBm  |
| 824–849 MHz  | WCDMA      | –   | 19  | –   | dBm  |
| 880–915 MHz  | E-GSM      | –   | 18  | –   | dBm  |
| 880–915 MHz  | WCDMA      | –   | 17  | –   | dBm  |
| 1710–1785 MHz  | GSM1800    | –   | 5   | –   | dBm  |
| 1710–1785 MHz  | WCDMA      | –   | 5   | –   | dBm  |
| 1850–1910 MHz  | GSM1900    | –   | 3   | –   | dBm  |
| 1850–1910 MHz  | WCDMA      | –   | 3   | –   | dBm  |
| 1880–1920 MHz  | TD-SCDMA   | –   | 2   | –   | dBm  |
| 1920–1980 MHz  | WCDMA      | –   | 1   | –   | dBm  |
| 2010–2025 MHz  | TD-SCDMA   | –   | –2  | –   | dBm  |
| 2500–2570 MHz  | WCDMA      | –   | –21 | –   | dBm  |
| 2500–2570 MHz <sup>[25]</sup>                          | Band 7     | –   | –27 | –   | dBm  |
| 2300–2400 MHz <sup>[26]</sup>                          | Band 40    | –   | –30 | –   | dBm  |
| 2570–2620 MHz <sup>[27]</sup>                          | Band 38    | –   | –26 | –   | dBm  |
| 2545–2575 MHz <sup>[28]</sup>                          | XGP Band   | –   | –26 | –   | dBm  |
| <b><math>\pi/4</math>-DPSK (2 Mbps)<sup>[24]</sup></b> |            |     |     |     |      |
| 698–716 MHz  | WCDMA      | –   | 19  | –   | dBm  |
| 776–794 MHz  | WCDMA      | –   | 20  | –   | dBm  |
| 824–849 MHz  | GSM850     | –   | 21  | –   | dBm  |
| 824–849 MHz  | WCDMA      | –   | 19  | –   | dBm  |
| 880–915 MHz  | E-GSM      | –   | 19  | –   | dBm  |
| 880–915 MHz  | WCDMA      | –   | 17  | –   | dBm  |
| 1710–1785 MHz  | GSM1800    | –   | 5   | –   | dBm  |
| 1710–1785 MHz  | WCDMA      | –   | 5   | –   | dBm  |
| 1850–1910 MHz  | GSM1900    | –   | 3   | –   | dBm  |
| 1850–1910 MHz  | WCDMA      | –   | 3   | –   | dBm  |
| 1880–1920 MHz  | TD-SCDMA   | –   | 2   | –   | dBm  |
| 1920–1980 MHz  | WCDMA      | –   | 1   | –   | dBm  |
| 2010–2025 MHz  | TD-SCDMA   | –   | –2  | –   | dBm  |
| 2500–2570 MHz  | WCDMA      | –   | –21 | –   | dBm  |
| 2500–2570 MHz <sup>[25]</sup>                          | Band 7     | –   | –26 | –   | dBm  |
| 2300–2400 MHz <sup>[26]</sup>                          | Band 40    | –   | –30 | –   | dBm  |
| 2570–2620 MHz <sup>[27]</sup>                          | Band 38    | –   | –26 | –   | dBm  |
| 2545–2575 MHz <sup>[28]</sup>                          | XGP Band   | –   | –26 | –   | dBm  |
| <b>8-DPSK (3 Mbps)<sup>[24]</sup></b>                  |            |     |     |     |      |
| 698–716 MHz  | WCDMA      | –   | 19  | –   | dBm  |
| 776–794 MHz  | WCDMA      | –   | 20  | –   | dBm  |

**Notes**

22. Dirty TX is OFF.

23. The maximum value represents the actual Bluetooth specification required for Bluetooth qualification as defined in the version 5.0 specification.

24. 3dB receiver desense. Band pass filter (2400~2500MHz) is installed at BT RF front end. The insertion loss at 2440MHz is about 1.2dB.

25. 2560 MHz performance is used.

26. 2360 MHz performance is used.

27. 2580 MHz performance is used.

28. 2555 MHz performance is used.

**Table 28. Bluetooth Receiver RF Specifications (Cont.)**

| Parameter                     | Conditions | Min | Typ  | Max | Unit   |
|-------------------------------|------------|-----|------|-----|--------|
| 824-849 MHz                   | GSM850     | -   | 21   | -   | dBm    |
| 824-849 MHz                   | WCDMA      | -   | 19   | -   | dBm    |
| 880-915 MHz                   | E-GSM      | -   | 18   | -   | dBm    |
| 880-915 MHz                   | WCDMA      | -   | 17   | -   | dBm    |
| 1710-1785 MHz                 | GSM1800    | -   | 5    | -   | dBm    |
| 1710-1785 MHz                 | WCDMA      | -   | 5    | -   | dBm    |
| 1850-1910 MHz                 | GSM1900    | -   | 3    | -   | dBm    |
| 1850-1910 MHz                 | WCDMA      | -   | 2    | -   | dBm    |
| 1880-1920 MHz                 | TD-SCDMA   | -   | 0    | -   | dBm    |
| 1920-1980 MHz                 | WCDMA      | -   | 0    | -   | dBm    |
| 2010-2025 MHz                 | TD-SCDMA   | -   | -3   | -   | dBm    |
| 2500-2570 MHz                 | WCDMA      | -   | -22  | -   | dBm    |
| 2500-2570 MHz <sup>[25]</sup> | Band 7     | -   | -27  | -   | dBm    |
| 2300-2400 MHz <sup>[26]</sup> | Band 40    | -   | -30  | -   | dBm    |
| 2570-2620 MHz <sup>[27]</sup> | Band 38    | -   | -27  | -   | dBm    |
| 2545-2575 MHz <sup>[28]</sup> | XGP Band   | -   | -26  | -   | dBm    |
| <b>Spurious Emissions</b>     |            |     |      |     |        |
| 30 MHz-1 GHz                  |            | -   | -95  | -   | dBm    |
| 1-12.75 GHz                   |            | -   | -70  | -   | dBm    |
| 851-894 MHz                   |            | -   | -147 | -   | dBm/Hz |
| 925-960 MHz                   |            | -   | -147 | -   | dBm/Hz |
| 1805-1880 MHz                 |            | -   | -147 | -   | dBm/Hz |
| 1930-1990 MHz                 |            | -   | -147 | -   | dBm/Hz |
| 2110-2170 MHz                 |            | -   | -147 | -   | dBm/Hz |

**Notes**

- 22. Dirty TX is OFF.
- 23. The maximum value represents the actual Bluetooth specification required for Bluetooth qualification as defined in the version 5.0 specification.
- 24. 3dB receiver desense. Band pass filter (2400~2500MHz) is installed at BT RF front end. The insertion loss at 2440MHz is about 1.2dB.
- 25. 2560 MHz performance is used.
- 26. 2360 MHz performance is used.
- 27. 2580 MHz performance is used.
- 28. 2555 MHz performance is used.

**Table 29. Bluetooth Transmitter RF Specifications**

| Parameter   | Conditions   | Min  | Typ  | Max  | Unit   |
|---|--|------|------|------|--------|
| <b>Note:</b> Unless otherwise specified, all Bluetooth RF specifications are provided at the Chip Port. |  |      |      |      |        |
| <b>General</b>  |  |      |      |      |        |
| Frequency range   |  | 2402 | –    | 2480 | MHz    |
| sLNA Basic rate (GFSK) TX power   |  | –    | 10   | –    | dBm    |
| sLNA QPSK TX Power  |  | –    | 7    | –    | dBm    |
| sLNA 8PSK TX Power  |  | –    | 7    | –    | dBm    |
| Power control step  |  | 2    | 4    | 8    | dB     |
| <b>Note</b> Output power is with TCA and TSSI enabled.  |  |      |      |      |        |
| <b>GFSK In-Band Spurious Emissions</b>  |  |      |      |      |        |
| –20 dBc BW  | –  | –    | 0.93 | 1    | MHz    |
| <b>EDR In-Band Spurious Emissions</b>   |  |      |      |      |        |
| 1.0 MHz <  M – N  < 1.5 MHz   | M – N = the frequency range for which the spurious emission is measured relative to the transmit center frequency. | –    | –    | –26  | dBc    |
| 1.5 MHz <  M – N  < 2.5 MHz   |  | –    | –    | –20  | dBm    |
| M – N  ≥ 2.5 MHz <sup>[29]</sup>  |  | –    | –    | –40  | dBm    |
| <b>Out-of-Band Spurious Emissions</b>   |  |      |      |      |        |
| 30 MHz to 1 GHz   | –  | –    | –128 | –    | dBm/Hz |
| 1 GHz to 12.75 GHz  | –  | –    | –36  | –    | dBm/Hz |
| 1.8 GHz to 1.9 GHz  | –  | –    | –124 | –    | dBm/Hz |
| 5.15 GHz to 5.3 GHz   | –  | –    | –122 | –    | dBm/Hz |
| <b>GPS Band Spurious Emissions</b>  |  |      |      |      |        |
| Spurious emissions  | –  | –    | –133 | –    | dBm/Hz |
| <b>Out-of-Band Noise Floor</b>  |  |      |      |      |        |
| 776–794 MHz   | CDMA2000   | –    | –164 | –    | dBm/Hz |
| 869–960 MHz   | cdmaOne, GSM850  | –    | –164 | –    | dBm/Hz |
| 925–960 MHz   | E-GSM  | –    | –164 | –    | dBm/Hz |
| 1570–1580 MHz   | GPS  | –    | –158 | –    | dBm/Hz |
| 1805–1880 MHz   | GSM1800  | –    | –153 | –    | dBm/Hz |
| 1930–1990 MHz   | GSM1900, cdmaOne, WCDMA  | –    | –147 | –    | dBm/Hz |
| 2110–2170 MHz   | WCDMA  | –    | –142 | –    | dBm/Hz |
| 2500–2570 MHz   | Band 7   | –    | –132 | –    | dBm/Hz |
| 2300–2400 MHz   | Band 40  | –    | –132 | –    | dBm/Hz |
| 2570–2620 MHz   | Band 38  | –    | –135 | –    | dBm/Hz |
| 2545–2575 MHz   | XGP Band   | –    | –133 | –    | dBm/Hz |

**Note**  
29. The typical number is measured at ± 3 MHz offset.

**Table 30. Local Oscillator Performance**

| Parameter                                    | Min <sup>[30]</sup> | Typ <sup>[30]</sup> | Max <sup>[30]</sup> | Unit      |
|--|---------------------|---------------------|---------------------|-----------|
| <b>LO Performance</b>                        |                     |                     |                     |           |
| Lock time                                    | –                   | 72                  | –                   | µs        |
| Initial carrier frequency tolerance          | –                   | ±25                 | ±75                 | kHz       |
| <b>Frequency Drift</b>                       |                     |                     |                     |           |
| DH1 packet                                   | –                   | ±10                 | ±25                 | kHz       |
| DH3 packet                                   | –                   | ±10                 | ±40                 | kHz       |
| DH5 packet                                   | –                   | ±10                 | ±40                 | kHz       |
| Drift rate                                   | –                   | 8                   | 20                  | kHz/50 µs |
| <b>Frequency Deviation</b>                   |                     |                     |                     |           |
| 00001111 sequence in payload <sup>[31]</sup> | 140                 | 155                 | 175                 | kHz       |
| 10101010 sequence in payload <sup>[32]</sup> | 115                 | 135                 | –                   | kHz       |
| Channel spacing                              | –                   | 0.95                | –                   | MHz       |

**Notes**

30. Min, Typical and Max numbers are tested at 2402, 2441 and 2480MHz channels respectively.

31. This pattern represents an average deviation in payload.

32. Pattern represents the maximum deviation in payload for 99.9% of all frequency deviations.

**Table 31. BLE RF Specifications**

| Parameter                               | Conditions             | Min  | Typ  | Max  | Unit |
|---|------------------------|------|------|------|------|
| Frequency range                         | –                      | 2402 | –    | 2480 | MHz  |
| RX sense <sup>[33]</sup>                | GFSK, 0.1% BER, 1 Mbps | –    | –96  | –    | dBm  |
| TX power <sup>[34]</sup>                | –                      | –    | 10   | –    | dBm  |
| Mod Char: delta F1 average              | –                      | 225  | 255  | 275  | kHz  |
| Mod Char: delta F2 max. <sup>[35]</sup> | –                      | 185  | 220  | –    | kHz  |
| Mod Char: ratio                         | –                      | 0.8  | 0.95 | –    | –    |

**Notes**

33. Dirty TX is Off.

34. The BLE TX power cannot exceed 10 dBm EIRP specification limit. The front-end losses and antenna gain/loss must be factored in so as not to exceed the limit.

35. At least 99.9% of all delta F2 max. frequency values recorded over 10 packets must be greater than 185 kHz.

## 16. WLAN RF Specifications

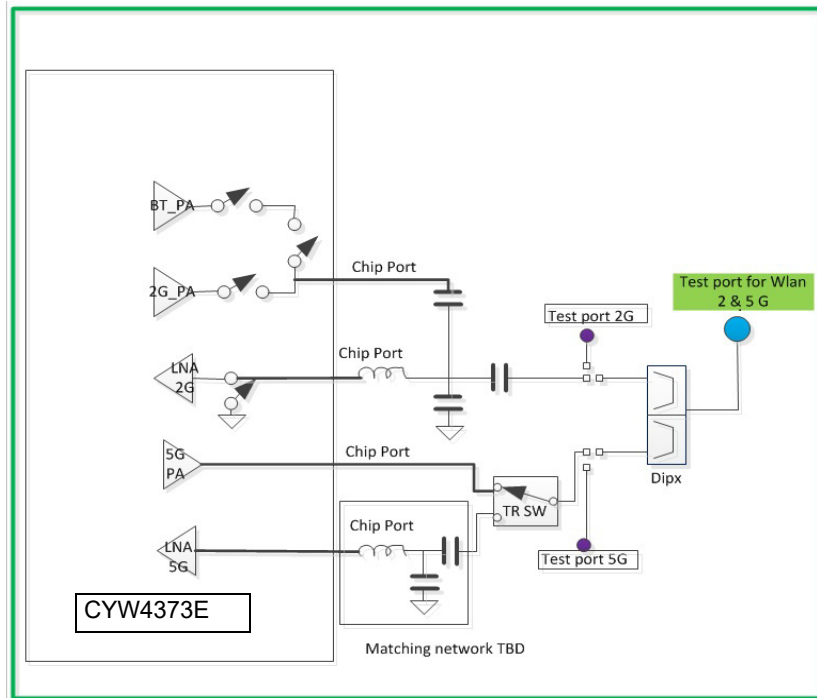
### 16.1 Introduction

The CYW4373E includes an integrated dual-band direct conversion radio that supports the 2.4 GHz and the 5 GHz bands. This section describes the RF characteristics of the 2.4 GHz and 5 GHz radio.

Unless otherwise stated, limit values apply for the conditions specified in [Table 25 “Environmental Ratings”](#) and [Table 27 “Recommended Operating Conditions and DC Characteristics”](#). Typical values apply for the following conditions:

- VBAT = 3.3V
- Ambient temperature +25°C

**Figure 35. Port Locations for WLAN Testing**



**Note:** Unless otherwise specified, all WLAN RF specifications are provided at the Chip Port. Measurements are made at Test Points and referenced back to the Chip Ports.

**16.2 WLAN 2.4 GHz Receiver Performance Specifications**

**Note:** Unless otherwise specified, all WLAN RF specifications are provided at the Chip Port.

**Table 32. WLAN 2.4 GHz Receiver Performance Specifications**

| Parameter  | Condition/Notes                                 | Min   | Typ   | Max  | Unit |
|--|---|-------|-------|------|------|
| Frequency range  | –   | 2400  | –     | 2500 | MHz  |
| RX sensitivity IEEE 802.11b<br>(8% PER for 1024 octet PSDU)  | 1 Mbps DSSS                                     | –94.2 | –98.8 | –    | dBm  |
|  | 2 Mbps DSSS                                     | –     | –96.6 | –    | dBm  |
|  | 5.5 Mbps DSSS                                   | –     | –94.5 | –    | dBm  |
|  | 11 Mbps DSSS                                    | –88.5 | –90.0 | –    | dBm  |
| RX sensitivity IEEE 802.11g<br>(10% PER for 1024 octet PSDU)   | 6 Mbps OFDM                                     | –93.1 | –94.5 | –    | dBm  |
|  | 9 Mbps OFDM                                     | –92.0 | –93.0 | –    | dBm  |
|  | 12 Mbps OFDM                                    | –     | –92.9 | –    | dBm  |
|  | 18 Mbps OFDM                                    | –89.0 | –90.1 | –    | dBm  |
|  | 24 Mbps OFDM                                    | –     | –87.2 | –    | dBm  |
|  | 36 Mbps OFDM                                    | –82.0 | –83.2 | –    | dBm  |
|  | 48 Mbps OFDM                                    | –     | –79.3 | –    | dBm  |
| RX sensitivity IEEE 802.11n 20 MHz channel<br>spacing with LDPC (10% PER for 4096 octet<br>PSDU) defined for default parameters: 800ns<br>GI, LDPC coding, and non-STBC <sup>[36]</sup>    | <b>20 MHz channel spacing for all MCS rates</b> |       |       |      |      |
|  | MCS0  | –93.2 | –94.4 | –    | dBm  |
|  | MCS1  | –     | –93.5 | –    | dBm  |
|  | MCS2  | –89.3 | –90.7 | –    | dBm  |
|  | MCS3  | –     | –88.2 | –    | dBm  |
|  | MCS4  | –83.1 | –84.0 | –    | dBm  |
|  | MCS5  | –     | –80.3 | –    | dBm  |
|  | MCS6  | –     | –79.0 | –    | dBm  |
|  | MCS7  | –75.2 | –76.6 | –    | dBm  |
| RX sensitivity IEEE 802.11n 40 MHz<br>channel spacing with LDPC (10% PER<br>for 4096 octet PSDU) defined for default<br>parameters: 800ns GI, LDPC coding,<br>and non-STBC <sup>[36]</sup> | <b>40 MHz channel spacing for all MCS rates</b> |       |       |      |      |
|  | MCS0  | –90.6 | –92.4 | –    | dBm  |
|  | MCS1  | –     | –91.1 | –    | dBm  |
|  | MCS2  | –86.1 | –88.2 | –    | dBm  |
|  | MCS3  | –     | –85.5 | –    | dBm  |
|  | MCS4  | –80.6 | –82.0 | –    | dBm  |
|  | MCS5  | –     | –77.9 | –    | dBm  |
|  | MCS6  | –     | –76.3 | –    | dBm  |
|  | MCS7  | –73.1 | –74.4 | –    | dBm  |

**Notes**

- 36. Sensitivity degradations for alternate settings in MCS modes. SGI: 2 dB drop.
- 37. The cellular standard listed for each band indicates the type of modulation used to generate the interfering signal in that band for the purpose of this test. It is not intended to indicate any specific usage of each band in any specific country..
- 38. The blocking levels are valid for channels 1 to 11. (For higher channels, the performance may be lower due to third harmonic signals (3 × 824 MHz) falling within band).
- 39. The minimum and maximum values shown have a 95% confidence level..

**Table 32. WLAN 2.4 GHz Receiver Performance Specifications (Cont.)**

| Parameter   | Condition/Notes   | Min   | Typ   | Max | Unit |
|---|---|-------|-------|-----|------|
| Blocking level for 3 dB RX sensitivity degradation (without external filtering) <sup>[37]</sup> | <b>776–794 MHz (CDMA2000):</b>  |       |       |     |      |
|   | Blocker frequency = 794 MHz   | –     | –19.2 | –   | dBm  |
|   | <b>824–849 MHz<sup>[38]</sup> (cdmaOne):</b>  |       |       |     |      |
|   | Blocker frequency = 849 MHz   | –     | –21.3 | –   | dBm  |
|   | <b>824–849 MHz (GSM850):</b>  |       |       |     |      |
|   | Blocker frequency = 849 MHz   | –     | –17.3 | –   | dBm  |
|   | <b>880–915 MHz (E-GSM):</b>   |       |       |     |      |
|   | Blocker frequency = 915 MHz   | –     | –18.5 | –   | dBm  |
|   | <b>1710–1785 MHz (GSM1800):</b>   |       |       |     |      |
|   | Blocker frequency = 1785 MHz  | –     | –21.0 | –   | dBm  |
|   | <b>1850–1910 MHz (GSM1900):</b>   |       |       |     |      |
|   | Blocker frequency = 1910 MHz  | –     | –20.7 | –   | dBm  |
|   | <b>1850–1910 MHz (cdmaOne):</b>   |       |       |     |      |
|   | Blocker frequency = 1910 MHz  | –     | –21.3 | –   | dBm  |
|   | <b>1850–1910 MHz (WCDMA):</b>   |       |       |     |      |
|   | Blocker frequency = 1910 MHz  | –     | –21.3 | –   | dBm  |
|   | <b>1920–1980 MHz (WCDMA):</b>   |       |       |     |      |
|   | Blocker frequency = 1980 MHz  | –     | –22.1 | –   | dBm  |
|   | <b>2300–2400 MHz (LTE band 40)</b>  |       |       |     |      |
|   | Blocker frequency = 2300 MHz  | –     | –27.8 | –   | dBm  |
| Blocker frequency = 2365 MHz  | –   | –26.6 | –     | dBm |      |
| <b>2500–2570 MHz (LTE band 7):</b>  |   |       |       |     |      |
| Blocker frequency = 2505 MHz  | –   | –25.4 | –     | dBm |      |
| Blocker frequency = 2565 MHz  | –   | –27.6 | –     | dBm |      |
| <b>2570–2620 MHz (LTE band 38):</b>   |   |       |       |     |      |
| Blocker frequency = 2575 MHz  | –   | –26.5 | –     | dBm |      |
| <b>2545–2575 MHz (XGP Band):</b>  |   |       |       |     |      |
| Blocker frequency = 2550 MHz  | –   | –27.1 | –     | dBm |      |
| In-band static CW jammer immunity (fc – 8 MHz < f <sub>cw</sub> < + 8 MHz)                      | RX PER < 1%, 54 Mbps OFDM, 1000 octet PSDU for: (RxSens + 23 dB < Rxlevel < max. input level) | –     | –80   | –   | dBm  |
| Input In-Band IP3   | Maximum LNA gain  | –     | –9    | –   | dBm  |
|   | Minimum LNA gain  | –     | 3     | –   | dBm  |
| Maximum Receive Level @ 2.4 GHz   | @ 1, 2 Mbps (8% PER, 1024 octets)   | –3.5  | –     | –   | dBm  |
|   | @ 5.5, 11 Mbps (8% PER, 1024 octets)  | –9.5  | –     | –   | dBm  |
|   | @ 6–54 Mbps (10% PER, 1024 octets)  | –9.5  | –     | –   | dBm  |
|   | @ MCS0–MCS7 rates (10% PER, 4096 octets)  | –9.5  | –     | –   | dBm  |

**Notes**

- 36. Sensitivity degradations for alternate settings in MCS modes. SGI: 2 dB drop.
- 37. The cellular standard listed for each band indicates the type of modulation used to generate the interfering signal in that band for the purpose of this test. It is not intended to indicate any specific usage of each band in any specific country..
- 38. The blocking levels are valid for channels 1 to 11. (For higher channels, the performance may be lower due to third harmonic signals (3 × 824 MHz) falling within band).
- 39. The minimum and maximum values shown have a 95% confidence level..



**Table 32. WLAN 2.4 GHz Receiver Performance Specifications (Cont.)**

| Parameter   | Condition/Notes                                    | Min     | Typ | Max  | Unit |    |
|---|--|---------|-----|------|------|----|
| Adjacent channel rejection-DSSS<br>(Difference between interfering and desired signal at 8% PER for 1024 octet PSDU with desired signal level as specified in Condition/Notes)                      | <b>Desired and interfering signal 30 MHz apart</b> |         |     |      |      |    |
|   | 1 Mbps DSSS  | -74 dBm | 35  | >44  | -    | dB |
|   | 2 Mbps DSSS  | -74 dBm | 35  | -    | -    | dB |
|   | <b>Desired and interfering signal 25 MHz apart</b> |         |     |      |      |    |
|   | 5.5 Mbps DSSS                                      | -70 dBm | 35  | -    | -    | dB |
|   | 11 Mbps DSSS                                       | -70 dBm | 35  | >44  | -    | dB |
| Adjacent channel rejection-OFDM<br>(Difference between interfering and desired signal (25 MHz apart) at 10% PER for 1024 octet PSDU with desired signal level as specified in Condition/Notes)      | 6 Mbps OFDM  | -79 dBm | 16  | 38.0 | -    | dB |
|   | 9 Mbps OFDM  | -78 dBm | 15  | 36.0 | -    | dB |
|   | 12 Mbps OFDM                                       | -76 dBm | 13  | -    | -    | dB |
|   | 18 Mbps OFDM                                       | -74 dBm | 11  | 32.4 | -    | dB |
|   | 24 Mbps OFDM                                       | -71 dBm | 8   | -    | -    | dB |
|   | 36 Mbps OFDM                                       | -67 dBm | 4   | 25.8 | -    | dB |
|   | 48 Mbps OFDM                                       | -63 dBm | 0   | -    | -    | dB |
|   | 54 Mbps OFDM                                       | -62 dBm | -1  | 20.4 | -    | dB |
| Adjacent channel rejection MCS0–MCS7<br>(Difference between interfering and desired signal (25 MHz apart) at 10% PER for 4096 octet PSDU with desired signal level as specified in Condition/Notes) | MCS0   | -79 dBm | 16  | 33.3 | -    | dB |
|   | MCS1   | -76 dBm | 13  | -    | -    | dB |
|   | MCS2   | -74 dBm | 11  | 27.0 | -    | dB |
|   | MCS3   | -71 dBm | 8   | -    | -    | dB |
|   | MCS4   | -67 dBm | 4   | 21.7 | -    | dB |
|   | MCS5   | -63 dBm | 0   | -    | -    | dB |
|   | MCS6   | -62 dBm | -1  | -    | -    | dB |
|   | MCS7   | -61 dBm | -2  | 13.7 | -    | dB |
| Maximum receiver gain   | -  | -       | 66  | 70   | 72   | dB |
| Gain control step   | -  | -       | -   | 3.0  | -    | dB |
| RSSI accuracy <sup>[39]</sup>   | Range -90 dBm to -30 dBm                           | -5      | -   | 5    | dB   |    |
|   | Range above -30 dBm                                | -8      | -   | 8    | dB   |    |
| Return loss   | Z <sub>o</sub> = 50Ω, across the dynamic range     | -       | 8   | -    | dB   |    |
| Receiver cascaded noise figure  | At maximum gain                                    | -       | 3.5 | -    | dB   |    |

**Notes**

36. Sensitivity degradations for alternate settings in MCS modes. SGI: 2 dB drop.

37. The cellular standard listed for each band indicates the type of modulation used to generate the interfering signal in that band for the purpose of this test. It is not intended to indicate any specific usage of each band in any specific country..

38. The blocking levels are valid for channels 1 to 11. (For higher channels, the performance may be lower due to third harmonic signals (3 × 824 MHz) falling within band).

39. The minimum and maximum values shown have a 95% confidence level..

**16.3 WLAN 2.4 GHz Transmitter Performance Specifications**

**Note:** Unless otherwise specified, all WLAN RF specifications are provided at the Chip Port.

**Table 33. WLAN 2.4 GHz Transmitter Performance Specifications**

| Parameter   | Condition/Notes  | Min    | Typ    | Max    | Unit    |     |
|---|--|--------|--------|--------|---------|-----|
| Frequency range   | –  | 2400   | –      | 2500   | MHz     |     |
| Transmitted power in cellular and bands (at +21 dBm, 100% duty cycle, 1 Mbps CCK) <sup>[40]</sup>                       | 776-794 MHz (CDMA2000)   | –      | –164   | –      | dBm/Hz  |     |
|   | 869-960 MHz (cdmaOne, GSM850)  | –      | –163   | –      | dBm/Hz  |     |
|   | 1450-1495 (DAB)  | –      | –153.6 | –      | dBm/Hz  |     |
|   | 1570-1580 MHz (GPS)  | –      | –151.2 | –      | dBm/Hz  |     |
|   | 1592-1610 MHz (GLONASS)  | –      | –147.0 | –      | dBm/Hz  |     |
|   | 1710-1800 (DSC-1800-Uplink)  | –      | –145   | –      | dBm/Hz  |     |
|   | 1805-1880 MHz (GSM 1800)   | –      | –139   | –      | dBm/Hz  |     |
|   | 1850-1910 MHz (GSM 1900)   | –      | –139   | –      | dBm/Hz  |     |
|   | 1910-1930 MHz (TDSCDMA,LTE)  | –      | –140   | –      | dBm/Hz  |     |
|   | 1930-1990 MHz (GSM1900, cdmaOne, WCDMA)  | –      | –128   | –      | dBm/Hz  |     |
|   | 2010-2075 MHz (TDSCDMA)  | –      | –131   | –      | dBm/Hz  |     |
|   | 2110-2170 MHz (WCDMA)  | –      | –125   | –      | dBm/Hz  |     |
|   | 2305-2370 (LTE band 40)  | –      | –95    | –      | dBm/Hz  |     |
|   | 2370-2400 (LTE band 40)  | –      | –77    | –      | dBm/Hz  |     |
|   | 2496-2530 (LTE band 41)  | –      | –90    | –      | dBm/Hz  |     |
|   | 2530-2560 (LTE band 41)  | –      | –109   | –      | dBm/Hz  |     |
| 2570-2690 (LTE band 41)   | –  | –112   | –      | dBm/Hz |         |     |
| 5000-5900 (WLAN 5G)   | –  | –      | –155   | –      | dBm/Hz  |     |
| <b>EVM Does Not Exceed</b>  |  |        |        |        |         |     |
| TX power at the chip port for highest power level setting at 25°C and VBAT = 3.3V with spectral mask and EVM compliance | DSSS   | –9 dB  | 20.0   | 20.0   | –       | dBm |
|   | BPSK   | –5 dB  | 18.5   | 19.5   | –       | dBm |
|   | QPSK   | –13 dB | 18.5   | 19.5   | –       | dBm |
|   | 16-QAM   | –19 dB | 18.5   | 19.5   | –       | dBm |
|   | 64-QAM   | –25 dB | 18.0   | 19.5   | –       | dBm |
|   | 64-QAM HT 20   | –27 dB | 16.5   | 19.5   | –       | dBm |
|   | 256-QAM HT 20  | –30 dB | 15.5   | 18.5   | –       | dBm |
|   | 16-QAM HT 40   | –19 dB | 15.5   | 18.0   | –       | dBm |
|   | 64-QAM HT 40   | –27 dB | 15.5   | 18.0   | –       | dBm |
| Phase noise   | 37.4 MHz crystal, integrated from 10 kHz to 10 MHz   | –      | 0.30   | –      | Degrees |     |
| TX power control dynamic range  | –  | 10     | –      | –      | dB      |     |
| Closed-loop TX power variation at highest power level setting   | Across full temperature and voltage range. Applies to 10 dBm to 20 dBm output power range. | –      | ±1.5   | ±2     | dB      |     |
| Carrier suppression   | –  | 15     | –      | –      | dBc     |     |
| Gain control step   | –  | –      | 0.25   | –      | dB      |     |
| Return loss at Chip port TX   | Z <sub>o</sub> = 50Ω   | –      | 3      | –      | dB      |     |

**Note**

40. The cellular standards listed indicate only typical usages of that band in some countries. Other standards may also be used within those bands.

**16.4 WLAN 5 GHz Receiver Performance Specifications**

**Note:** Unless otherwise specified, all WLAN RF specifications are provided at the Chip Port.

**Table 34. WLAN 5 GHz Receiver Performance Specifications**

| Parameter   | Condition/Notes                          | Min   | Typ   | Max  | Unit |
|---|--|-------|-------|------|------|
| Frequency range   | –  | 4900  | –     | 5845 | MHz  |
| RX sensitivity IEEE 802.11a<br>(10% PER for 1000 octet PSDU)  | 6 Mbps OFDM                              | –92.4 | –94.9 | –    | dBm  |
|   | 9 Mbps OFDM                              | –90.5 | –93.6 | –    | dBm  |
|   | 12 Mbps OFDM                             | –     | –92.9 | –    | dBm  |
|   | 18 Mbps OFDM                             | –87.4 | –90.4 | –    | dBm  |
|   | 24 Mbps OFDM                             | –     | –87.0 | –    | dBm  |
|   | 36 Mbps OFDM                             | –80.7 | –83.5 | –    | dBm  |
|   | 48 Mbps OFDM                             | –     | –79.1 | –    | dBm  |
|   | 54 Mbps OFDM                             | –74.9 | –77.7 | –    | dBm  |
| RX sensitivity IEEE 802.11n<br>(10% PER for 4096 octet PSDU)<br>Defined for default parameters:<br>800 ns GI, LDPC coding and<br>non-STBC | 20 MHz channel spacing for all MCS rates |       |       |      |      |
|   | MCS0                                     | –92.5 | –95.0 | –    | dBm  |
|   | MCS1                                     | –     | –93.5 | –    | dBm  |
|   | MCS2                                     | –87.9 | –91.0 | –    | dBm  |
|   | MCS3                                     | –     | –88.0 | –    | dBm  |
|   | MCS4                                     | –81.5 | –84.6 | –    | dBm  |
|   | MCS5                                     | –     | –80.2 | –    | dBm  |
|   | MCS6                                     | –     | –78.8 | –    | dBm  |
| RX sensitivity IEEE 802.11n (10% PER<br>for 4096 octet PSDU)<br>Defined for default parameters: 800 ns GI,<br>LDPC coding and non-STBC.   | 40 MHz channel spacing for all MCS rates |       |       |      |      |
|   | MCS0                                     | –90.5 | –92.6 | –    | dBm  |
|   | MCS1                                     | –     | –91.1 | –    | dBm  |
|   | MCS2                                     | –85.5 | –88.4 | –    | dBm  |
|   | MCS3                                     | –     | –85.4 | –    | dBm  |
|   | MCS4                                     | –79.3 | –82.0 | –    | dBm  |
|   | MCS5                                     | –     | –77.6 | –    | dBm  |
|   | MCS6                                     | –     | –76.1 | –    | dBm  |
| RX sensitivity IEEE 802.11ac (10% PER<br>for 4096 octet PSDU)<br>Defined for default parameters: 800 ns GI,<br>LDPC coding and non-STBC.  | 20 MHz channel spacing for all MCS rates |       |       |      |      |
|   | MCS0                                     | –92.4 | –95.0 | –    | dBm  |
|   | MCS1                                     | –     | –93.4 | –    | dBm  |
|   | MCS2                                     | –87.8 | –90.9 | –    | dBm  |
|   | MCS3                                     | –     | –88.2 | –    | dBm  |
|   | MCS4                                     | –81.4 | –84.6 | –    | dBm  |
|   | MCS5                                     | –     | –80.3 | –    | dBm  |
|   | MCS6                                     | –     | –78.8 | –    | dBm  |
|   | MCS7                                     | –74.2 | –77.0 | –    | dBm  |
| MCS8  | –70.0                                    | –73.1 | –     | dBm  |      |

**Notes**

41. For 65 Mbps, the size is 4096.

42. The minimum and maximum values shown have a 95% confidence level.

**Table 34. WLAN 5 GHz Receiver Performance Specifications (Cont.)**

| Parameter   | Condition/Notes                          | Min       | Typ   | Max  | Unit |    |
|---|--|-----------|-------|------|------|----|
| RX sensitivity IEEE 802.11ac (10% PER for 4096 octet PSDU)<br>Defined for default parameters: 800 ns GI, LDPC coding and non-STBC.  | 40 MHz channel spacing for all MCS rates |           |       |      |      |    |
|   | MCS0                                     | -90.5     | -92.7 | -    | dBm  |    |
|   | MCS1                                     | -         | -91.1 | -    | dBm  |    |
|   | MCS2                                     | -85.7     | -88.5 | -    | dBm  |    |
|   | MCS3                                     | -         | -85.6 | -    | dBm  |    |
|   | MCS4                                     | -79.3     | -82.0 | -    | dBm  |    |
|   | MCS5                                     | -         | -77.9 | -    | dBm  |    |
|   | MCS6                                     | -         | -76.3 | -    | dBm  |    |
|   | MCS7                                     | -71.3     | -74.4 | -    | dBm  |    |
|   | MCS8                                     | -67.5     | -70.5 | -    | dBm  |    |
| RX sensitivity IEEE 802.11ac (10% PER for 4096 octet PSDU)<br>Defined for default parameters: 800 ns GI, LDPC coding and non-STBC.  | 80 MHz channel spacing for all MCS rates |           |       |      |      |    |
|   | MCS0                                     | -87.3     | -89.5 | -    | dBm  |    |
|   | MCS1                                     | -         | -87.5 | -    | dBm  |    |
|   | MCS2                                     | -82.3     | -84.8 | -    | dBm  |    |
|   | MCS3                                     | -         | -82.2 | -    | dBm  |    |
|   | MCS4                                     | -76.3     | -78.6 | -    | dBm  |    |
|   | MCS5                                     | -         | -74.5 | -    | dBm  |    |
|   | MCS6                                     | -         | -73.0 | -    | dBm  |    |
|   | MCS7                                     | -69.2     | -71.3 | -    | dBm  |    |
|   | MCS8                                     | -65.2     | -67.5 | -    | dBm  |    |
| Input In-Band IP3   | Maximum LNA gain                         | -         | -11   | -    | dBm  |    |
|   | Minimum LNA gain                         | -         | 5     | -    | dBm  |    |
| Maximum receive level @ 5.24 GHz  | @ 6, 9, 12 Mbps                          | -9.5      | -     | -    | dBm  |    |
|   | @ 18, 24, 36, 48, 54 Mbps                | -14.5     | -     | -    | dBm  |    |
| Adjacent channel rejection<br>(Difference between interfering and desired signal (20 MHz apart) at 10% PER for 1000 octet PSDU with desired signal level as specified in Condition/Notes)                           | 6 Mbps OFDM                              | -79 dBm   | 16    | 31.7 | -    | dB |
|   | 9 Mbps OFDM                              | -78 dBm   | 15    | 28.1 | -    | dB |
|   | 12 Mbps OFDM                             | -76 dBm   | 13    | -    | -    | dB |
|   | 18 Mbps OFDM                             | -74 dBm   | 11    | 24.9 | -    | dB |
|   | 24 Mbps OFDM                             | -71 dBm   | 8     | -    | -    | dB |
|   | 36 Mbps OFDM                             | -67 dBm   | 4     | 18.9 | -    | dB |
|   | 48 Mbps OFDM                             | -63 dBm   | 0     | -    | -    | dB |
|   | 54 Mbps OFDM                             | -62 dBm   | -1    | 13.8 | -    | dB |
|   | 65 Mbps OFDM                             | -61 dBm   | -2    | 8.4  | -    | dB |
| Alternate adjacent channel rejection<br>(Difference between interfering and desired signal (40 MHz apart) at 10% PER for 1000 <sup>[41]</sup> octet PSDU with desired signal level as specified in Condition/Notes) | 6 Mbps OFDM                              | -78.5 dBm | 32    | 44.7 | -    | dB |
|   | 9 Mbps OFDM                              | -77.5 dBm | 31    | 43.2 | -    | dB |
|   | 12 Mbps OFDM                             | -75.5 dBm | 29    | -    | -    | dB |
|   | 18 Mbps OFDM                             | -73.5 dBm | 27    | 39.3 | -    | dB |
|   | 24 Mbps OFDM                             | -70.5 dBm | 24    | -    | -    | dB |
|   | 36 Mbps OFDM                             | -66.5 dBm | 20    | 32.7 | -    | dB |
|   | 48 Mbps OFDM                             | -62.5 dBm | 16    | -    | -    | dB |
|   | 54 Mbps OFDM                             | -61.5 dBm | 15    | 26.6 | -    | dB |
| 65 Mbps OFDM  | -60.5 dBm                                | 14        | 26.8  | -    | dB   |    |

**Notes**

41. For 65 Mbps, the size is 4096.

42. The minimum and maximum values shown have a 95% confidence level.

**Table 34. WLAN 5 GHz Receiver Performance Specifications (Cont.)**

| Parameter                      | Condition/Notes                                | Min | Typ  | Max | Unit |
|--------------------------------|--|-----|------|-----|------|
| Maximum receiver gain          | –  | –   | 70.5 | –   | dB   |
| Gain control step              | –  | –   | 3.0  | –   | dB   |
| RSSI accuracy <sup>[42]</sup>  | Range –87 dBm to –30 dBm                       | –5  | –    | 5   | dB   |
|                                | Range above –87 dBm                            | –8  | –    | 8   | dB   |
| Return loss                    | Z <sub>o</sub> = 50Ω, across the dynamic range | –   | 10   | –   | dB   |
| Receiver cascaded noise figure | At maximum gain                                | –   | 5    | –   | dB   |

**Notes**

41. For 65 Mbps, the size is 4096.

42. The minimum and maximum values shown have a 95% confidence level.

**16.5 WLAN 5 GHz Transmitter Performance Specifications**

**Note:** Unless otherwise specified, all WLAN RF specifications are provided at the Chip Port.

**Table 35. WLAN 5 GHz Transmitter Performance Specifications**

| Parameter   | Condition/Notes                         | Min    | Typ    | Max    | Unit   |     |
|---|---|--------|--------|--------|--------|-----|
| Frequency range   | –                                       | 4900   | –      | 5845   | MHz    |     |
| Transmitted power in cellular and bands (at +18.5 dBm, 100% duty cycle, 6 Mbps OFDM) <sup>[43]</sup>                    | 776–794 MHz (CDMA2000)                  | –      | –164   | –      | dBm/Hz |     |
|   | 869–960 MHz (cdmaOne, GSM850)           | –      | –166   | –      | dBm/Hz |     |
|   | 1450–1495 (DAB)                         | –      | –166   | –      | dBm/Hz |     |
|   | 1570–1580 MHz (GPS)                     | –      | –166   | –      | dBm/Hz |     |
|   | 1592–1610 MHz (GLONASS)                 | –      | –165.5 | –      | dBm/Hz |     |
|   | 1710–1800(DSC-1800-Uplink)              | –      | –135   | –      | dBm/Hz |     |
|   | 1805–1880 MHz (GSM 1800)                | –      | –165   | –      | dBm/Hz |     |
|   | 1850–1910 MHz (GSM 1900)                | –      | –165   | –      | dBm/Hz |     |
|   | 1910–1930 MHz (TDSCDMA, LTE)            | –      | –165   | –      | dBm/Hz |     |
|   | 1930–1990 MHz (GSM1900, cdmaOne, WCDMA) | –      | –165   | –      | dBm/Hz |     |
|   | 2010–2075 MHz (TDSCDMA)                 | –      | –164.5 | –      | dBm/Hz |     |
|   | 2110–2170 MHz (WCDMA)                   | –      | –164   | –      | dBm/Hz |     |
|   | 2305–2370 (LTE band 40)                 | –      | –158   | –      | dBm/Hz |     |
|   | 2370–2400 (LTE band 40)                 | –      | –162   | –      | dBm/Hz |     |
|   | 2400–2500 (WLAN 2G)                     | –      | –160   | –      | dBm/Hz |     |
|   | 2496–2530 (LTE band 41)                 | –      | –161.5 | –      | dBm/Hz |     |
| 2530–2560 (LTE band 41)   | –                                       | –161.5 | –      | dBm/Hz |        |     |
| 2570–2690 (LTE band 41)   | –                                       | –159   | –      | dBm/Hz |        |     |
| <b>EVM Does Not Exceed</b>  |   |        |        |        |        |     |
| TX power at the chip port for highest power level setting at 25°C and VBAT = 3.3V with spectral mask and EVM compliance | BPSK                                    | –5 dB  | 17.0   | 19.0   | –      | dBm |
|   | QPSK                                    | –13 dB | 17.0   | 19.0   | –      | dBm |
|   | 16-QAM                                  | –19 dB | 17.0   | 19.0   | –      | dBm |
|   | 64-QAM                                  | –25 dB | 16.0   | 19.0   | –      | dBm |
|   | 64-QAM HT20                             | –27 dB | 15.0   | 19.0   | –      | dBm |
|   | 256-QAM VHT20                           | –30 dB | 14.0   | 18.5   | –      | dBm |

**Note**

43. The cellular standards listed indicate only typical usages of that band in some countries. Other standards may also be used within those bands.

**Table 35. WLAN 5 GHz Transmitter Performance Specifications (Cont.)**

| Parameter   | Condition/Notes  | Min    | Typ  | Max  | Unit    |     |
|---|--|--------|------|------|---------|-----|
| TX power at the chip port for highest power level setting at 25°C and VBAT = 3.3V with spectral mask and EVM compliance | 256-QAM VHT40 MCS8 NSS1  | -30 dB | 14.0 | 18.0 | -       | dBm |
|   | 256-QAM VHT40 MCS9 NSS1  | -32 dB | 13.5 | 17.0 | -       | dBm |
|   | 256-QAM VHT80 MCS8 NSS1  | -30 dB | 13.5 | 17.5 | -       | dBm |
|   | 256-QAM VHT80 MCS9 NSS1  | -32 dB | 12   | 16.5 | -       | dBm |
| Phase noise   | 37.4 MHz Crystal, Integrated from 10 kHz to 10 MHz   | -      | 0.4  | -    | Degrees |     |
| TX power control dynamic range  | -  | 10     | -    | -    | dB      |     |
| Closed loop TX power variation at highest power level setting   | Across full-temperature and voltage range. Applies across 10 to 20 dBm output power range. | -      | ±1.5 | ±2.0 | dB      |     |
| Carrier suppression   | -  | 15     | -    | -    | dBc     |     |
| Gain control step   | -  | -      | 0.25 | -    | dB      |     |
| Return loss   | Z <sub>o</sub> = 50Ω   | -      | 5    | -    | dB      |     |

**Note**

43. The cellular standards listed indicate only typical usages of that band in some countries. Other standards may also be used within those bands.

**16.6 General Spurious Emissions Specifications**

This section provides the TX and RX spurious emissions specifications for both the WLAN 2.4 GHz and 5 GHz bands. The recommended spectrum analyzer settings for the spurious emissions specifications are provided in [Table 36](#).

**Table 36. Recommended Spectrum Analyzer Settings**

| Parameter             | Setting   |
|-----------------------|---|
| Resolution Bandwidth: | 1 MHz   |
| Video Bandwidth:      | 10 MHz  |
| Sweep:                | Auto  |
| Span:                 | Variable  |
| Detector:             | Maximum Peak                                      |
| Trace:                | Maximum Hold                                      |
| Modulation:           | OFDM (Orthogonal Frequency-division Multiplexing) |

**16.6.1 2.4 GHz Band Spurious Emissions**
**20 MHz Channel Spacing**
**Table 37. 2.4 GHz Band, 20 MHz Channel Spacing TX Spurious Emissions Specifications**

| Emissions Frequency Range (MHz) | Channel Power (dBm) | Spurious Emission Level(Fch= 2442 MHz)<br>Typ(dBm) |
|---------------------------------|---------------------|--|
| 1000 – 2000                     | 21                  | -44  |
| 2000 - 2400                     | 21                  | -40  |
| 2500 - 3000                     | 21                  | -40  |
| 3000 - 4000                     | 21                  | -40  |
| 4000 - 5000                     | 21                  | -16  |
| 5000 - 6000                     | 21                  | -47  |
| 6000 – 7000                     | 21                  | -48  |
| 7000 – 8000                     | 21                  | -15  |
| 8000 – 10000                    | 21                  | -43  |
| 10000 – 12000                   | 21                  | -50  |
| 12000 – 15000                   | 21                  | -49  |
| 15000 – 20000                   | 21                  | -48  |

**16.6.2 5 GHz Band Spurious Emissions**
**20 MHz Channel Spacing**
**Table 38. 5 GHz Band, 20 MHz Channel Spacing TX Spurious Emissions Specifications**

| Emissions Frequency Range (MHz) | Channel Power (dBm) | Spurious Emission Level (Typical) (dBm) |        |        |
|---------------------------------|---------------------|---|--------|--------|
|                                 |                     | CH5180                                  | CH5500 | CH5825 |
| 1000 – 2000                     | 19                  | -48                                     | -48    | -48    |
| 2000 - 3000                     | 19                  | -48                                     | -47    | -48    |
| 3000 - 4000                     | 19                  | -43                                     | -44    | -43    |
| 4000 - 5000                     | 19                  | -46                                     | -46    | -46    |
| 5000 - 6000                     | 19                  | -43                                     | -42    | -40    |
| 6000 – 7000                     | 19                  | -43                                     | -48    | -41    |
| 7000 – 8000                     | 19                  | -48                                     | -45    | -48    |
| 8000 – 10000                    | 19                  | -48                                     | -48    | -49    |
| 10000 – 12000                   | 19                  | -11                                     | -15    | -16    |
| 12000 – 15000                   | 19                  | -47                                     | -46    | -47    |
| 15000 – 20000                   | 19                  | -20                                     | -22    | -22    |

**40 MHz Channel Spacing**

**Table 39. 5 GHz Band, 40 MHz Channel Spacing TX Spurious Emissions Specifications**

| Emissions Frequency Range (MHz) | Channel Power (dBm) | Spurious Emission Level (Typical) (dBm) |         |         |
|---------------------------------|---------------------|---|---------|---------|
|                                 |                     | CH5190m                                 | CH5510m | CH5795m |
| 1000 – 2000                     | 19                  | -48                                     | -48     | -48     |
| 2000 - 3000                     | 19                  | -48                                     | -48     | -48     |
| 3000 - 4000                     | 19                  | -43                                     | -43     | -42     |
| 4000 - 5000                     | 19                  | -45                                     | -46     | -47     |
| 5000 - 6000                     | 19                  | -42                                     | -42     | -42     |
| 6000 – 7000                     | 19                  | -44                                     | -48     | -46     |
| 7000 – 8000                     | 19                  | -48                                     | -46     | -48     |
| 8000 – 10000                    | 19                  | -48                                     | -48     | -48     |
| 10000 – 12000                   | 19                  | -16                                     | -18     | -19     |
| 12000 – 15000                   | 19                  | -46                                     | -46     | -46     |
| 15000 – 20000                   | 19                  | -26                                     | -27     | -27     |

**80 MHz Channel Spacing**

**Table 40. 5 GHz Band, 80 MHz Channel Spacing TX Spurious Emissions Specifications**

| Emissions Frequency Range (MHz) | Channel Power (dBm) | Spurious Emission Level (Typical) (dBm) |         |         |
|---------------------------------|---------------------|---|---------|---------|
|                                 |                     | CH5210q                                 | CH5530q | CH5775q |
| 1000 – 2000                     | 19                  | -48                                     | -48     | -48     |
| 2000 - 3000                     | 19                  | -48                                     | -48     | -48     |
| 3000 - 4000                     | 19                  | -41                                     | -41     | -41     |
| 4000 - 5000                     | 19                  | -38                                     | -47     | -47     |
| 5000 - 6000                     | 19                  | -40                                     | -40     | -40     |
| 6000 – 7000                     | 19                  | -44                                     | -48     | -46     |
| 7000 – 8000                     | 19                  | -48                                     | -46     | -48     |
| 8000 – 10000                    | 19                  | -50                                     | -50     | -50     |
| 10000 – 12000                   | 19                  | -19                                     | -23     | -23     |
| 12000 – 15000                   | 19                  | -47                                     | -47     | -47     |
| 15000 – 20000                   | 19                  | -27                                     | -30     | -31     |



16.6.3 Receiver Spurious Emissions Specifications

**Table 41. 2G and 5G General Receiver Spurious Emissions**

| Band | Frequency Range         | Emission(Typical) | Unit |
|------|-------------------------|-------------------|------|
| 2G   | 2.4 GHz < f < 2.5 GHz   | -89               | dBm  |
|      | 3.6 GHz < f < 3.8 GHz   | -62               | dBm  |
| 5G   | 5.15 GHz < f < 5.85 GHz | -61               | dBm  |
|      | 3.45 GHz < f < 3.9 GHz  | -52               | dBm  |

## 17. Internal Regulator Electrical Specifications

### 17.1 Core Buck Switching Regulator

**Note:** Functional operation is not guaranteed outside of the specification limits provided in this section.

**Table 42. Core Buck Switching Regulator (CBUCK) Specifications**

| Specification                     | Notes  | Min                  | Typ  | Max                 | Unit |
|-----------------------------------|--|----------------------|------|---------------------|------|
| Input supply voltage (DC)         | DC voltage range inclusive of disturbances.  | 3.0                  | 3.6  | 4.8 <sup>[44]</sup> | V    |
| PWM mode switching frequency      | CCM, Load > 100 mA VBAT = 3.6V   | –                    | 4    | –                   | MHz  |
| PWM output current                | –  | –                    | –    | 600                 | mA   |
| Output current limit              | –  | –                    | 1400 | –                   | mA   |
| Output voltage range              | Programmable, 30 mV steps. Default = 1.35V   | 1.2                  | 1.35 | 1.5                 | V    |
| PWM output voltage DC accuracy    | Includes load and line regulation. Forced PWM mode.  | –4                   | –    | 4                   | %    |
| PWM ripple voltage, static        | Measure with 20 MHz bandwidth limit. Static Load. Max. Ripple based on VBAT = 3.6V, Vout = 1.35V, Fsw = 4 MHz, 2.2 μH inductor L > 1.05 μH, Cap + Board total-ESR < 20 mΩ, C <sub>out</sub> > 1.9 μF, ESL < 200 pH | –                    | 7    | 20                  | mVpp |
| PWM mode peak efficiency          | Peak Efficiency at 200 mA load with 0806 inductor (see external inductor row below)  | 78                   | 86   | –                   | %    |
|                                   | Peak Efficiency at 200 mA load with 0603 inductor (see external inductor row below)  | 78                   | 84   | –                   | %    |
| PFM mode efficiency               | 10mA load current with 0603 inductor (see external inductor row below)   | 70                   | 80   | –                   | %    |
|                                   | 10mA load current with 0806 inductor (see external inductor row below)   | 70                   | 76   | –                   | %    |
| Start-up time from power down     | VIO already ON and steady. Time from REG_ON rising edge to CLDO reaching 1.2V.   | –                    | 400  | 500                 | μs   |
| External inductor                 | 0603 size, 2.2μH, DCR=0.3Ω, ACR = 1.34Ω @ 4 MHz<br>OR<br>0806 size, 2.2 μH, DCR=0.11Ω, ACR = 1.18Ω @ 4 MHz   | –                    | 2.2  | –                   | μH   |
| External output capacitor         | Ceramic, X5R, 0402, ESR <30 mΩ at 4 MHz, 4.7 μF ±20%, 6.3V   | 2.0                  | 4.7  | 10 <sup>[45]</sup>  | μF   |
| External input capacitor          | For SR_VDDBATP5V pin, ceramic, X5R, 0603, ESR < 30 mΩ at 4 MHz, ±4.7uF ±20%, 6.3V  | 0.67 <sup>[45]</sup> | 4.7  | –                   | μF   |
| Input supply voltage ramp-up time | 0 to 4.3V  | 40                   | –    | –                   | μs   |

**Notes**

44. The maximum continuous voltage is 4.8V. Voltages up to 5.5V for up to 10 seconds, cumulative duration, over the lifetime of the device are allowed.

45. Total capacitance includes those connected at the far end of the active load.

**17.2 3.3V LDO (LDO3P3)**

**Table 43. LDO3P3 Specifications**

| Specification                    | Notes   | Min                 | Typ | Max                 | Unit    |
|----------------------------------|---|---------------------|-----|---------------------|---------|
| Input supply voltage, $V_{in}$   | Min. = $V_o + 0.2V = 3.5V$ dropout voltage requirement must be met under maximum load for performance specifications.   | 3.0                 | 3.6 | 4.8 <sup>[46]</sup> | V       |
| Output current                   | –   | 0.001               | –   | 450                 | mA      |
| Nominal output voltage, $V_o$    | –   | –                   | 3.3 | –                   | V       |
| Dropout voltage                  | At max. load.   | –                   | –   | 200                 | mV      |
| Output voltage DC accuracy       | Includes line/load regulation.  | –5                  | –   | +5                  | %       |
| Quiescent current                | No load   | –                   | –   | 100                 | $\mu A$ |
| Line regulation                  | $V_{in}$ from ( $V_o + 0.2V$ ) to 5.25V, max. load  | –                   | –   | 3.5                 | mV/V    |
| Load regulation                  | load from 1 mA to 450 mA  | –                   | –   | 0.3                 | mV/mA   |
| PSRR                             | $V_{in} \geq V_o + 0.2V$ , $V_o = 3.3V$ , $C_o = 4.7 \mu F$ ,<br>Max. load, 100 Hz to 100 kHz   | 20                  | –   | –                   | dB      |
| LDO turn-on time                 | Chip already powered up.  | –                   | 160 | 250                 | $\mu s$ |
| External output capacitor, $C_o$ | Ceramic, X5R, 0402,<br>(ESR: 5 m $\Omega$ –240 m $\Omega$ ), $\pm 10\%$ , 10V   | 1.0 <sup>[47]</sup> | 4.7 | 10                  | $\mu F$ |
| External input capacitor         | For SR_VDDBATA5V pin (shared with Bandgap) Ceramic,<br>X5R, 0402, (ESR: 30m-200 m $\Omega$ ), $\pm 10\%$ , 10V.<br>Not needed if sharing VBAT capacitor 4.7 $\mu F$ with<br>SR_VDDBATP5V. | –                   | 4.7 | –                   | $\mu F$ |

**Notes**

46. The maximum continuous voltage is 4.8V. Voltages up to 5.5V for up to 10 seconds, cumulative duration, over the lifetime of the device are allowed.

47. Minimum capacitor value refers to the residual capacitor value after taking into account the part-to-part tolerance, DC-bias, temperature, and aging.

**17.3 2.5V LDO (BTLDO2P5)**

**Table 44. BTLDO2P5 Specifications**

| Specification                             | Notes  | Min                 | Typ | Max                 | Unit  |
|---|--|---------------------|-----|---------------------|-------|
| Input supply voltage                      | Min. = 2.5V + 0.2V = 2.7V.<br>Dropout voltage requirement must be met under maximum load for performance specifications.   | 3.0                 | 3.6 | 4.8 <sup>[47]</sup> | V     |
| Nominal output voltage                    | –  | –                   | 2.8 | –                   | V     |
| Output voltage programmability            | Range  | 2.2                 | 2.5 | 2.8                 | V     |
|   | Accuracy at any step (including line/load regulation), load > 0.1 mA.  | –5                  | –   | 5                   | %     |
| Dropout voltage                           | At maximum load.   | –                   | –   | 200                 | mV    |
| Output current                            | –  | 0.1                 | –   | 70                  | mA    |
| Quiescent current                         | No load.   | –                   | 8   | 16                  | µA    |
|   | Maximum load at 70 mA.   | –                   | 660 | 700                 | µA    |
| Leakage current                           | Power-down mode.   | –                   | 1.5 | 5                   | µA    |
| Line regulation                           | V <sub>in</sub> from (V <sub>o</sub> + 0.2V) to 5.25V, maximum load.   | –                   | –   | 3.5                 | mV/V  |
| Load regulation                           | Load from 1 mA to 70 mA,<br>V <sub>in</sub> = 3.6V.  | –                   | –   | 0.3                 | mV/mA |
| PSRR                                      | V <sub>in</sub> ≥ V <sub>o</sub> + 0.2V, V <sub>o</sub> = 2.5V, C <sub>o</sub> = 2.2 µF,<br>maximum load, 100 Hz to 100 kHz.   | 20                  | –   | –                   | dB    |
| LDO turn-on time                          | Chip already powered up.   | –                   | –   | 150                 | µs    |
| In-rush current                           | V <sub>in</sub> = V <sub>o</sub> + 0.15V to 5.25V, C <sub>o</sub> = 2.2 µF, No load.   | –                   | –   | 250                 | mA    |
| External output capacitor, C <sub>o</sub> | Ceramic, X5R, 0402,<br>(ESR: 5m–240 mΩ), ±10%, 10V   | 0.7 <sup>[47]</sup> | 2.2 | 2.64                | µF    |
| External input capacitor                  | For SR_VDDBATA5V pin (shared with Bandgap) ceramic,<br>X5R, 0402,<br>(ESR: 30–200 mΩ), ±10%, 10V.<br>Not needed if sharing VBAT 4.7 µF capacitor with<br>SR_VDDBATP5V. | –                   | 4.7 | –                   | µF    |

**Notes**

- 48. The maximum continuous voltage is 4.8V. Voltages up to 5.5V for up to 10 seconds, cumulative duration, over the lifetime of the device are allowed.
- 49. Minimum capacitor value refers to the residual capacitor value after taking into account the part-to-part tolerance, DC-bias, temperature, and aging.

**17.4 CLDO**

**Table 45. CLDO Specifications**

| Specification                    | Notes  | Min                 | Typ  | Max  | Unit    |
|----------------------------------|--|---------------------|------|------|---------|
| Input supply voltage, $V_{in}$   | Min. = $1.2 + 0.15V = 1.35V$ dropout voltage requirement must be met under maximum load.         | 1.3                 | 1.35 | 1.5  | V       |
| Output current                   | –  | 0.2                 | –    | 200  | mA      |
| Output voltage, $V_o$            | Programmable in 10 mV steps. Default = 1.2V  | 0.95                | 1.2  | 1.26 | V       |
| Dropout voltage                  | At max. load   | –                   | –    | 150  | mV      |
| Output voltage DC accuracy       | Includes line/load regulation  | –4                  | –    | +4   | %       |
| Quiescent current                | No load  | –                   | 13   | –    | $\mu A$ |
|                                  | 200 mA load  | –                   | 1.24 | –    | mA      |
| Line Regulation                  | $V_{in}$ from ( $V_o + 0.15V$ ) to 1.5V, maximum load  | –                   | –    | 5    | mV/V    |
| Load Regulation                  | Load from 1 mA to 200 mA   | –                   | 0.02 | 0.05 | mV/mA   |
| Leakage Current                  | Power down   | –                   | 5    | 20   | $\mu A$ |
|                                  | Bypass mode  | –                   | 1    | 3    | $\mu A$ |
| PSRR                             | @1 kHz, $V_{in} \geq 1.35V$ , $C_o = 4.7 \mu F$  | 20                  | –    | –    | dB      |
| Start-up Time of PMU             | VIO up and steady. Time from the REG_ON rising edge to the CLDO reaching 1.2V.                   | –                   | –    | 700  | $\mu s$ |
| LDO Turn-on Time                 | LDO turn-on time when rest of the chip is up   | –                   | 140  | 180  | $\mu s$ |
| External Output Capacitor, $C_o$ | Total ESR: 5 m $\Omega$ –240 m $\Omega$  | 1.1 <sup>[50]</sup> | 2.2  | –    | $\mu F$ |
| External Input Capacitor         | Only use an external input capacitor at the VDD_LDO pin if it is not supplied from CBUCK output. | –                   | 1    | 2.2  | $\mu F$ |

**Note**

50. Minimum capacitor value refers to the residual capacitor value after taking into account the part-to-part tolerance, DC-bias, temperature, and aging.

**17.5 LNLDO**
**Table 46. LNLDO Specifications**

| Specification                    | Notes  | Min                 | Typ  | Max      | Unit                 |
|----------------------------------|--|---------------------|------|----------|----------------------|
| Input supply voltage, $V_{in}$   | Min. $V_{IN} = V_O + 0.15V = 1.35V$ (where $V_O = 1.2V$ ) dropout voltage requirement must be met under maximum load.  | 1.3                 | 1.35 | 1.5      | V                    |
| Output Current                   | –  | 0.1                 | –    | 150      | mA                   |
| Output Voltage, $V_o$            | Programmable in 25 mV steps. Default = 1.2V  | 1.1                 | 1.2  | 1.275    | V                    |
| Dropout Voltage                  | At maximum load  | –                   | –    | 150      | mV                   |
| Output Voltage DC Accuracy       | Includes line/load regulation  | –4                  | –    | +4       | %                    |
| Quiescent current                | No-load  | –                   | 40   | 100      | $\mu A$              |
|                                  | 55mA load  | –                   | 613  | 1000     | $\mu A$              |
| Line Regulation                  | $V_{in}$ from ( $V_o + 0.1V$ ) to 1.5V, 150 mA load  | –                   | –    | 5        | mV/V                 |
| Load Regulation                  | Load from 1 mA to 150 mA   | –                   | 0.02 | 0.05     | mV/mA                |
| Leakage Current                  | Power-down   | –                   | –    | 10       | $\mu A$              |
| Output Noise                     | @30 kHz, 60–150 mA load $C_o = 2.2 \mu F$<br>@100 kHz, 60–150 mA load $C_o = 2.2 \mu F$  | –                   | –    | 60<br>35 | nV/rt Hz<br>nV/rt Hz |
| PSRR                             | @ 1kHz, Input > 1.35V, $C_o = 2.2 \mu F$ , $V_o = 1.2V$  | 20                  | –    | –        | dB                   |
| LDO Turn-on Time                 | LDO turn-on time when rest of chip is up   | –                   | 140  | 180      | $\mu s$              |
| External Output Capacitor, $C_o$ | Total ESR (trace/capacitor): 5 m $\Omega$ –240 m $\Omega$  | 0.5 <sup>[51]</sup> | 2.2  | 4.7      | $\mu F$              |
| External Input Capacitor         | Only use an external input capacitor at the VDD_LDO pin if it is not supplied from CBUCK output.<br>Total ESR (trace/capacitor): 30 m $\Omega$ –200 m $\Omega$ | –                   | 1    | 2.2      | $\mu F$              |

**Note**

51. Minimum capacitor value refers to the residual capacitor value after taking into account the part-to-part tolerance, DC-bias, temperature, and aging.

**17.6 HLDO**

**Table 47. HLDO Specifications**

| Parameter                        | Conditions   | Min  | Typ   | Max   | Unit    |
|----------------------------------|--|------|-------|-------|---------|
| Input Supply Voltage, $V_{in}$   | Min $V_{in}=V_o+0.15V = 1.35V$ (for $V_o=1.2V$ )                                       | 1.3  | 1.35  | 1.5   | V       |
|                                  | dropout voltage requirement must be met under max load                                 |      |       |       |         |
| Output Current                   | Peak load=55mA, average=35mA   | 0.1  | –     | 55    | mA      |
| Output Voltage Programmability   | Range  | 1.1  | 1.2   | 1.275 | V       |
|                                  | Step Size  | –    | 25    | –     | mV      |
|                                  | Accuracy at any Step (including line/load regulation)                                  | -4   | –     | 4     | %       |
| Dropout Voltage                  | at max load  | –    | –     | 150   | mV      |
| Output Current                   | Peak load=55mA, average=35mA   | 0.1  | –     | 55    | mA      |
| Quiescent Current                | No-load  | –    | 10    | –     | $\mu A$ |
|                                  | 55mA load  | –    | 560   | –     | $\mu A$ |
| Line Regulation                  | $V_{in}$ from $(V_o+0.15V)$ to 1.5V; 55mA load   | –    | 5     | –     | mV/V    |
| Load Regulation                  | load from 1mA to 55mA; $V_{in} \geq (V_o+0.15V)$                                       | –    | 0.045 | 0.05  | mV/mA   |
| Leakage Current                  | Power-down. Junction Temp 85C  | –    | 1     | 6     | $\mu A$ |
|                                  | Bypass mode  | –    | 0.4   | 1.7   | $\mu A$ |
| PSRR                             | @1kHz, $V_{in} \geq V_o+0.15V$ , $C_o=0.47\mu F$                                       | 20   | –     | –     | dB      |
| Start-up Time of PMU             | VIO up & steady. Time from REG_ON rise edge to LDO reaching 99% of $V_o$ .             | –    | 530   | 700   | $\mu s$ |
| LDO Turn-on Time                 | LDO turn-on time when rest of chip is up   | –    | 140   | 180   | $\mu s$ |
| External Output Capacitor, $C_o$ | 0201 size cap  | 0.27 | 1     | –     | $\mu F$ |
|                                  | $C = 0.47\mu F$ , Tol = 20%, Voltage Rating = 6.3, Temp Rating = X5R                   |      |       |       |         |
| External Input Capacitor         | Only use an external input cap at VDD_LDO pin if it is not supplied from CBUCK output. | –    | 1     | –     | $\mu F$ |

## 18. System Power Consumption

**Note:** Unless otherwise stated, these values apply for the conditions specified in Table 27 “Recommended Operating Conditions and DC Characteristics”.

### 18.1 WLAN Current Consumption

The tables in this subsection show the typical, total current consumed by the CYW4373E. All values shown are with the Bluetooth core in reset mode with Bluetooth off.

#### 18.1.1 2.4 GHz Mode

**Table 48. 2.4 GHz Mode WLAN Power Consumption**

| Mode  | $V_{BAT} = 3.3V, V_{DDIO} = 1.8V, T_A = 25^\circ C$ |                        |
|---|---|------------------------|
|   | $V_{BAT}, mA$                                       | $V_{IO}, \mu A^{[52]}$ |
| <b>Sleep Modes (SDIO Interface)</b>                     |   |                        |
| Off <sup>[53]</sup>                                     | 0.003   | 0.15                   |
| Sleep <sup>[54]</sup>                                   | 0.03  | 200                    |
| IEEE Power Save: DTIM = 1, single RX <sup>[55]</sup>    | 1.6   | 200                    |
| IEEE Power Save: DTIM = 3, single RX                    | 0.55  | 230                    |
| <b>Sleep Modes (PCIe Interface)</b>                     |   |                        |
| Radio off <sup>[53]</sup>                               | 0.006   | 5                      |
| Sleep <sup>[54]</sup>                                   | 0.06  | 200                    |
| IEEE Power Save: DTIM = 1, single RX <sup>[55]</sup>    | 1.40  | 200                    |
| IEEE Power Save: DTIM = 3, single RX                    | 0.55  | 200                    |
| <b>Sleep Modes (USB Interface)</b>                      |   |                        |
| OFF <sup>[53]</sup>                                     | 0.003   | 0.057                  |
| Sleep <sup>[54]</sup>                                   | 0.49  | 230                    |
| IEEE Power Save: DTIM = 1, single RX <sup>[55]</sup>    | 2.354   | 230                    |
| IEEE Power Save: DTIM = 3, single RX                    | 1.31  | 230                    |
| <b>Active RX Modes</b>                                  |   |                        |
| Continuous RX mode: MCS7, HT20, 1SS <sup>[56, 57]</sup> | 56  | 60                     |
| Continuous RX mode: MCS7, HT40, 1SS <sup>[56, 57]</sup> | 70  | 60                     |
| CRS: HT20 <sup>[58]</sup>                               | 51  | 60                     |
| CRS: HT40 <sup>[58]</sup>                               | 61  | 60                     |
| <b>Active TX Modes – Internal PA</b>                    |   |                        |
| Continuous TX mode: 1 Mbps @ 20 dBm <sup>[59]</sup>     | 320   | 60                     |

**Notes**

- 52. VIO is specified with all pins idle (not switching) and not driving any loads. And with SDIO\_CLK OFF during sleep modes.
- 53. WL\_REG\_ON and BT\_REG\_ON are both low. All supplies are present.
- 54. Idle, not associated, or inter-beacon.
- 55. Beacon Interval = 102.4 ms. Beacon duration = 1 ms @ 1 Mbps. Average current over 3× DTIM intervals.
- 56. Duty cycle is 100%. Carrier sense (CS) detect/packet receive.
- 57. Measured using packet engine test mode.
- 58. Carrier sense (CCA) when no carrier present.
- 59. Duty cycle is 100%.



Table 48. 2.4 GHz Mode WLAN Power Consumption (Cont.)

| Mode   | $V_{BAT} = 3.3V, V_{DDIO} = 1.8V, T_A = 25^{\circ}C$ |                                 |
|--|--|---------------------------------|
|  | $V_{BAT}, mA$  | $V_{IO}, \mu A$ <sup>[52]</sup> |
| Continuous TX mode: MCS7, HT20, 1SS, 1 TX @ 17.5 dBm <sup>[59]</sup> | 300  | 60                              |
| Continuous TX mode: MCS7, HT40, 1SS, 1 TX @ 15.5 dBm <sup>[59]</sup> | 310  | 60                              |
| <b>Peak PHY Calibration Current</b>                                  |  |                                 |
| Unassociated   | 768  | 510                             |
| Associated   | 748  | 560                             |

Notes

- 52. VIO is specified with all pins idle (not switching) and not driving any loads. And with SDIO\_CLK OFF during sleep modes.
- 53. WL\_REG\_ON and BT\_REG\_ON are both low. All supplies are present.
- 54. Idle, not associated, or inter-beacon.
- 55. Beacon Interval = 102.4 ms. Beacon duration = 1 ms @ 1 Mbps. Average current over 3× DTIM intervals.
- 56. Duty cycle is 100%. Carrier sense (CS) detect/packet receive.
- 57. Measured using packet engine test mode.
- 58. Carrier sense (CCA) when no carrier present.
- 59. Duty cycle is 100%.

18.1.2 5 GHz Mode

Table 49. 5 GHz Mode WLAN Power Consumption

| Mode   | $V_{BAT} = 3.3V, V_{DDIO} = 1.8V, T_A = 25^{\circ}C$ |                                 |
|--|--|---------------------------------|
|  | $V_{BAT}, mA$  | $V_{IO}, \mu A$ <sup>[60]</sup> |
| <b>Sleep Modes (SDIO Interface)</b>                  |  |                                 |
| Off <sup>[61]</sup>                                  | 0.003  | 0.15                            |
| Sleep <sup>[62]</sup>                                | 0.03   | 200                             |
| IEEE Power Save: DTIM = 1, single RX <sup>[63]</sup> | 1.1  | 200                             |
| IEEE Power Save: DTIM = 3, single RX <sup>[63]</sup> | 0.4  | 200                             |
| <b>Sleep Modes (PCIe Interface)</b>                  |  |                                 |
| Radio off <sup>[61]</sup>                            | 0.006  | 5                               |
| Sleep <sup>[62]</sup>                                | 0.085  | 200                             |
| IEEE Power Save: DTIM = 1, single RX <sup>[63]</sup> | 1.1  | 200                             |
| IEEE Power Save: DTIM = 3, single RX <sup>[63]</sup> | 0.43   | 200                             |
| <b>Sleep Modes (USB Interface)</b>                   |  |                                 |
| OFF <sup>[61]</sup>                                  | 0.003  | 0.057                           |
| Sleep <sup>[62]</sup>                                | 0.49   | 230                             |
| IEEE Power Save: DTIM = 1, single RX <sup>[63]</sup> | 1.746  | 230                             |

Notes

- 60. VIO is specified with all pins idle (not switching) and not driving any loads. And with SDIO\_CLK OFF during sleep modes.
- 61. WL\_REG\_ON and BT\_REG\_ON are both low. All supplies are present.
- 62. Idle, not associated, or inter-beacon.
- 63. Beacon Interval = 102.4 ms. Beacon duration = 1 ms @ 1 Mbps. Average current over 3× DTIM intervals.
- 64. Duty cycle is 100%. Carrier sense (CS) detect/packet receive.
- 65. Measured using packet engine test mode.
- 66. Carrier sense (CCA) when no carrier present.
- 67. Duty cycle is 100%.

**Table 49. 5 GHz Mode WLAN Power Consumption (Cont.)**

| Mode  | $V_{BAT} = 3.3V, V_{DDIO} = 1.8V, T_A = 25^{\circ}C$ |                        |
|---|--|------------------------|
|   | $V_{BAT}, mA$  | $V_{IO}, \mu A^{[60]}$ |
| IEEE Power Save: DTIM = 3, single RX <sup>[63]</sup>                  | 1.17   | 230                    |
| <b>Active RX Modes</b>  |  |                        |
| Continuous RX mode: MCS7, HT20, 1SS <sup>[64, 65]</sup>               | 75   | 60                     |
| Continuous RX mode: MCS8, VHT20, 1SS <sup>[64, 65]</sup>              | 76   | 60                     |
| Continuous RX mode: MCS9, VHT40, 1SS <sup>[64, 65]</sup>              | 89   | 60                     |
| Continuous RX mode: MCS9, VHT80, 1SS <sup>[64, 65]</sup>              | 126  | 60                     |
| CRS: HT20 <sup>[66]</sup>   | 68   | 60                     |
| CRS: HT40 <sup>[66]</sup>   | 78   | 60                     |
| CRS: HT80 <sup>[66]</sup>   | 100  | 60                     |
| <b>Active TX Modes – Internal PA</b>                                  |  |                        |
| Continuous TX mode: MCS7, HT20, 1SS, 1 TX @ 17 dBm <sup>[67]</sup>    | 340  | 60                     |
| Continuous TX mode: MCS8, VHT20, 1SS, 1 TX @ 16 dBm <sup>[67]</sup>   | 330  | 60                     |
| Continuous TX mode: MCS9, VHT40, 1SS, 1 TX @ 15 dBm <sup>[67]</sup>   | 327  | 60                     |
| Continuous TX mode: MCS9, VHT80, 1SS, 1 TX @ 14.5 dBm <sup>[67]</sup> | 353  | 60                     |
| <b>Peak PHY Calibration Current</b>                                   |  |                        |
| Unassociated  | 666  | 410                    |
| Associated  | 664  | 390                    |

**Notes**

- 60. VIO is specified with all pins idle (not switching) and not driving any loads. And with SDIO\_CLK OFF during sleep modes.
- 61. WL\_REG\_ON and BT\_REG\_ON are both low. All supplies are present.
- 62. Idle, not associated, or inter-beacon.
- 63. Beacon Interval = 102.4 ms. Beacon duration = 1 ms @ 1 Mbps. Average current over 3× DTIM intervals.
- 64. Duty cycle is 100%. Carrier sense (CS) detect/packet receive.
- 65. Measured using packet engine test mode.
- 66. Carrier sense (CCA) when no carrier present.
- 67. Duty cycle is 100%.

## 18.2 Bluetooth Current Consumption

The Bluetooth and BLE current consumption measurements are shown in [Table 50](#).

**Note:** The WLAN core is in reset (WLAN\_REG\_ON = low) for all measurements provided in [Table 50](#).

**Note:** The BT current consumption numbers are measured based on GFSK TX output power = 10 dBm.

**Table 50. Bluetooth and BLE Current Consumption**

| Operating Mode                     | VBAT                | VDDIO | Unit |
|------------------------------------|---------------------|-------|------|
| Sleep                              | 3.9 <sup>[68]</sup> | 300   | μA   |
| Standard 1.28s Inquiry Scan        | 169.9               | 300   | μA   |
| 500 ms Sniff Master                | 153                 | 300   | μA   |
| DM1/DH1 Master TX RX               | 28.68               | 0.094 | mA   |
| DM3/DH3 Master TX RX               | 35.43               | 0.122 | mA   |
| DM5/DH5 Master TX RX               | 36.24               | 0.129 | mA   |
| 3DH5 RX 3DH1 TX Master             | 30.21               | 0.272 | mA   |
| HV3 Master                         | 10.198              | 0.064 | mA   |
| Passive Scan 1.28s <sup>[69]</sup> | 172.2               | 300   | μA   |
| Adv—Unconnectable 1.00 sec         | 94.9                | 300   | μA   |
| Connected 1.00 sec interval Master | 82.2                | 300   | μA   |

**Note**

68. This sleep current consumption number and other average current consumption numbers in this table assume the UART interface for BT. Sleep current when using the USB interface is ~800μA. Average current consumption numbers are therefore also expected to be higher when using the USB interface for BT.

69. No devices present. 1.28 second interval with a scan window of 11.25 ms

## 19. Interface Timing and AC Characteristics

### 19.1 SDIO Timing

#### 19.1.1 SDIO Default Mode Timing

SDIO default mode timing is shown by the combination of Figure 36 and Table 51.

Figure 36. SDIO Bus Timing (Default Mode)

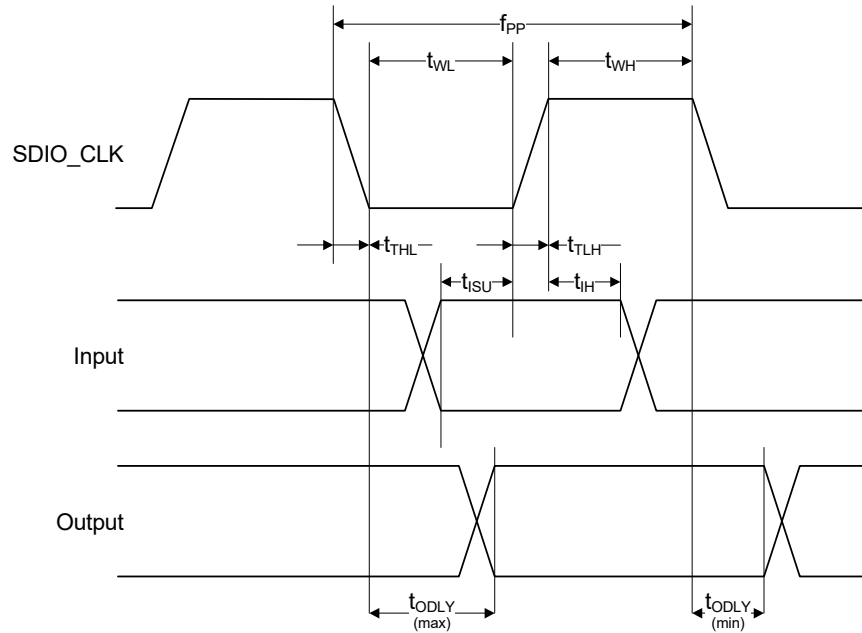


Table 51. SDIO Bus Timing<sup>[70]</sup> Parameters (Default Mode)

| Parameter   | Symbol     | Min | Typ | Max | Unit |
|---|------------|-----|-----|-----|------|
| <b>SDIO CLK (All values are referred to minimum VIH and maximum VIL<sup>[71]</sup>)</b> |            |     |     |     |      |
| Frequency – Data Transfer mode  | $f_{PP}$   | 0   | –   | 25  | MHz  |
| Frequency – Identification mode   | $f_{OD}$   | 0   | –   | 400 | kHz  |
| Clock low time  | $t_{WL}$   | 10  | –   | –   | ns   |
| Clock high time   | $t_{WH}$   | 10  | –   | –   | ns   |
| Clock rise time   | $t_{TLH}$  | –   | –   | 10  | ns   |
| Clock low time  | $t_{THL}$  | –   | –   | 10  | ns   |
| <b>Inputs: CMD, DAT (referenced to CLK)</b>   |            |     |     |     |      |
| Input setup time  | $t_{ISU}$  | 5   | –   | –   | ns   |
| Input hold time   | $t_{IH}$   | 5   | –   | –   | ns   |
| <b>Outputs: CMD, DAT (referenced to CLK)</b>  |            |     |     |     |      |
| Output delay time – Data Transfer mode  | $t_{ODLY}$ | 0   | –   | 14  | ns   |
| Output delay time – Identification mode   | $t_{ODLY}$ | 0   | –   | 50  | ns   |

**Notes**

70. Timing is based on  $CL \leq 40$  pF load on CMD and Data.  
 71. Min ( $V_{ih}$ ) =  $0.65 \times V_{DDIO}$  and max ( $V_{il}$ ) =  $0.35 \times V_{DDIO}$ .

19.1.2 SDIO High-Speed Mode Timing

SDIO high-speed mode timing is shown by the combination of Figure 37 and Table 52.

Figure 37. SDIO Bus Timing (High-Speed Mode)

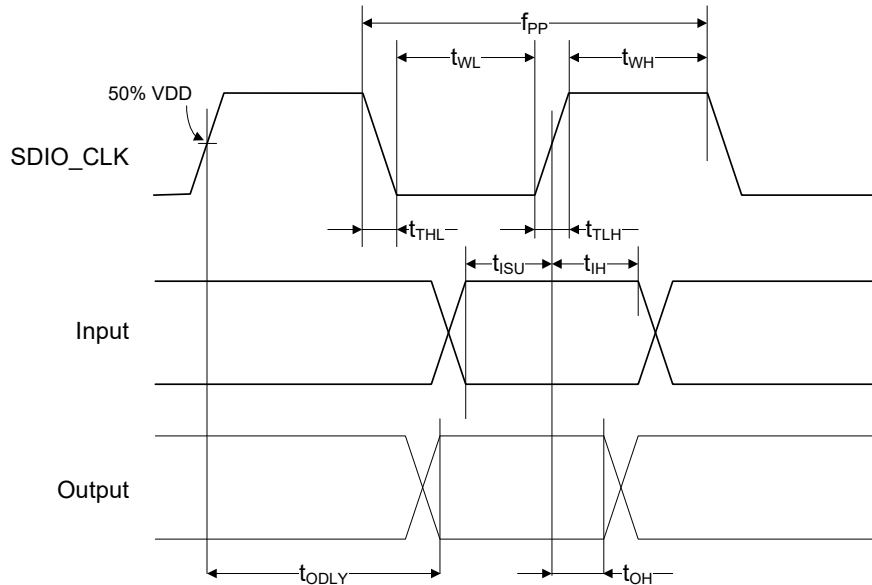


Table 52. SDIO Bus Timing<sup>[72]</sup> Parameters (High-Speed Mode)

| Parameter   | Symbol            | Min | Typ | Max | Unit |
|---|-------------------|-----|-----|-----|------|
| <b>SDIO CLK (all values are referred to minimum VIH and maximum VIL<sup>[73]</sup>)</b> |                   |     |     |     |      |
| Frequency – Data Transfer Mode  | f <sub>PP</sub>   | 0   | –   | 50  | MHz  |
| Frequency – Identification Mode   | f <sub>OD</sub>   | 0   | –   | 400 | kHz  |
| Clock low time  | t <sub>WL</sub>   | 7   | –   | –   | ns   |
| Clock high time   | t <sub>WH</sub>   | 7   | –   | –   | ns   |
| Clock rise time   | t <sub>TLH</sub>  | –   | –   | 3   | ns   |
| Clock low time  | t <sub>THL</sub>  | –   | –   | 3   | ns   |
| <b>Inputs: CMD, DAT (referenced to CLK)</b>   |                   |     |     |     |      |
| Input setup Time  | t <sub>ISU</sub>  | 6   | –   | –   | ns   |
| Input hold Time   | t <sub>IH</sub>   | 2   | –   | –   | ns   |
| <b>Outputs: CMD, DAT (referenced to CLK)</b>  |                   |     |     |     |      |
| Output delay time – Data Transfer Mode  | t <sub>ODLY</sub> | –   | –   | 14  | ns   |
| Output hold time  | t <sub>OH</sub>   | 2.5 | –   | –   | ns   |
| Total system capacitance (each line)  | CL                | –   | –   | 40  | pF   |

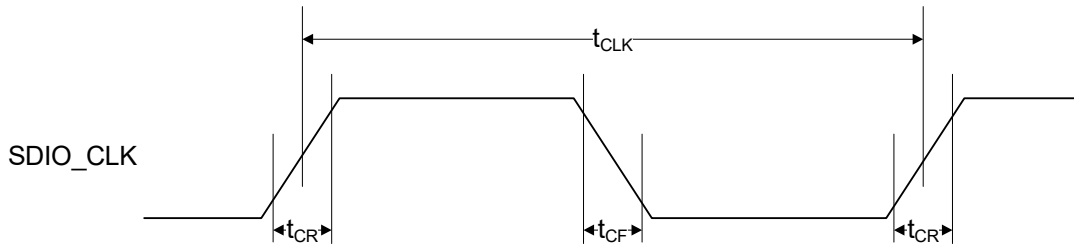
Notes

72. Timing is based on CL ≤ 40 pF load on CMD and Data.  
 73. Min (V<sub>Ih</sub>) = 0.65 × V<sub>DDIO</sub> and max (V<sub>Il</sub>) = 0.35 × V<sub>DDIO</sub>.

19.1.3 SDIO Bus Timing Specifications in SDR Modes

**Clock Timing**

**Figure 38. SDIO Clock Timing (SDR Modes)**

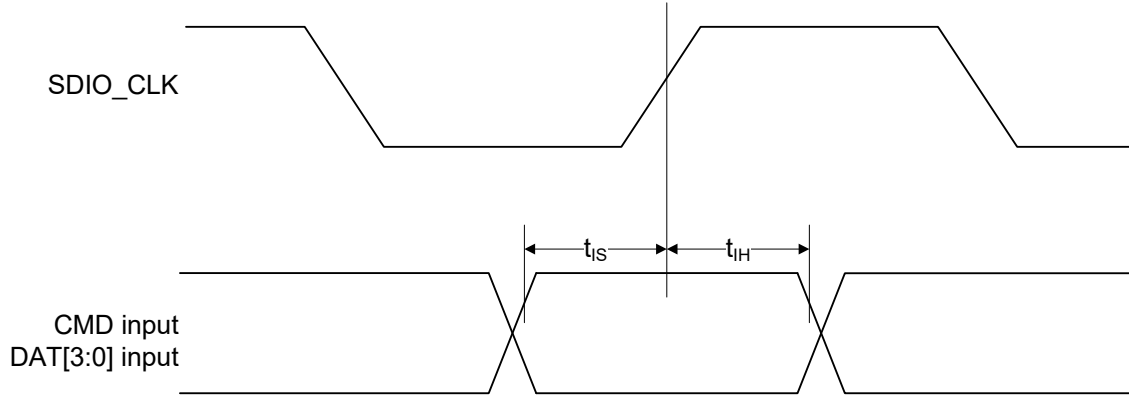


**Table 53. SDIO Bus Clock Timing Parameters (SDR Modes)**

| Parameter        | Symbol           | Min | Max                  | Unit | Comments   |
|------------------|------------------|-----|----------------------|------|--|
| –                | $t_{CLK}$        | 40  | –                    | ns   | SDR12 mode   |
|                  |                  | 20  | –                    | ns   | SDR25 mode   |
|                  |                  | 10  | –                    | ns   | SDR50 mode   |
|                  |                  | 4.8 | –                    | ns   | SDR104 mode  |
| –                | $t_{CR}, t_{CF}$ | –   | $0.2 \times t_{CLK}$ | ns   | $t_{CR}, t_{CF} < 2.00$ ns (max) @ 100 MHz, $C_{CARD} = 10$ pF<br>$t_{CR}, t_{CF} < 0.96$ ns (max) @ 208 MHz, $C_{CARD} = 10$ pF |
| Clock duty cycle | –                | 30  | 70                   | %    | –  |

**Card Input Timing**

**Figure 39. SDIO Bus Input Timing (SDR Modes)**

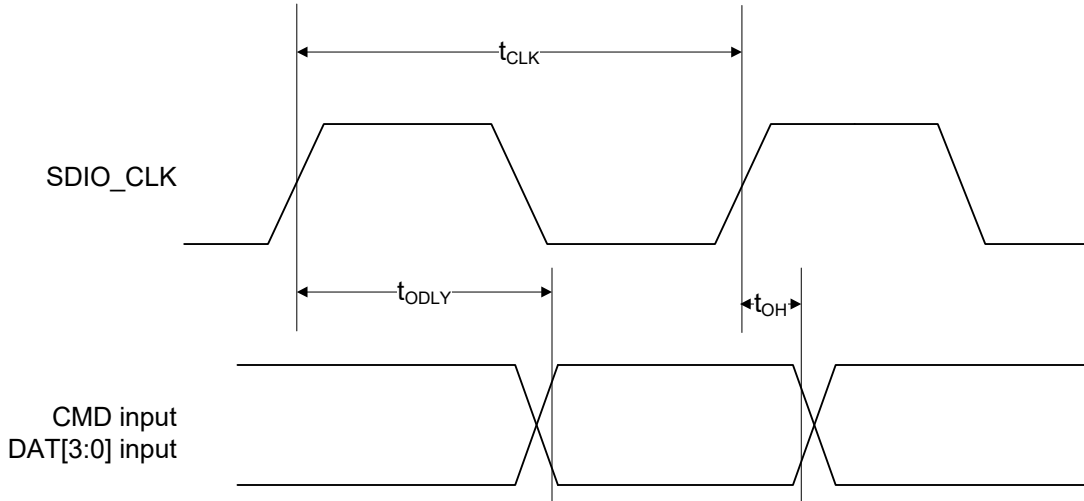


**Table 54. SDIO Bus Input Timing Parameters (SDR Modes)**

| Symbol             | Min  | Max | Unit | Comments  |
|--------------------|------|-----|------|---|
| <b>SDR104 Mode</b> |      |     |      |   |
| $t_{IS}$           | 1.4  | –   | ns   | $C_{CARD} = 10 \text{ pF}$ , $V_{CT} = 0.975\text{V}$ |
| $t_{IH}$           | 0.8  | –   | ns   | $C_{CARD} = 5 \text{ pF}$ , $V_{CT} = 0.975\text{V}$  |
| <b>SDR50 Mode</b>  |      |     |      |   |
| $t_{IS}$           | 3.00 | –   | ns   | $C_{CARD} = 10 \text{ pF}$ , $V_{CT} = 0.975\text{V}$ |
| $t_{IH}$           | 0.8  | –   | ns   | $C_{CARD} = 5 \text{ pF}$ , $V_{CT} = 0.975\text{V}$  |

**Card Output Timing**

**Figure 40. SDIO Bus Output Timing (SDR Modes up to 100 MHz)**



**Table 55. SDIO Bus Output Timing Parameters (SDR Modes up to 100 MHz)**

| Symbol     | Min | Max  | Unit | Comments   |
|------------|-----|------|------|--|
| $t_{ODLY}$ | –   | 7.5  | ns   | $t_{CLK} \geq 10$ ns $C_L = 30$ pF using driver type B for SDR50 |
| $t_{ODLY}$ | –   | 14.0 | ns   | $t_{CLK} \geq 20$ ns $C_L = 40$ pF using for SDR12, SDR25        |
| $t_{OH}$   | 1.5 | –    | ns   | Hold time at the $t_{ODLY}$ (min) $C_L = 15$ pF                  |



Figure 41. SDIO Bus Output Timing (SDR Modes 100 MHz to 208 MHz)

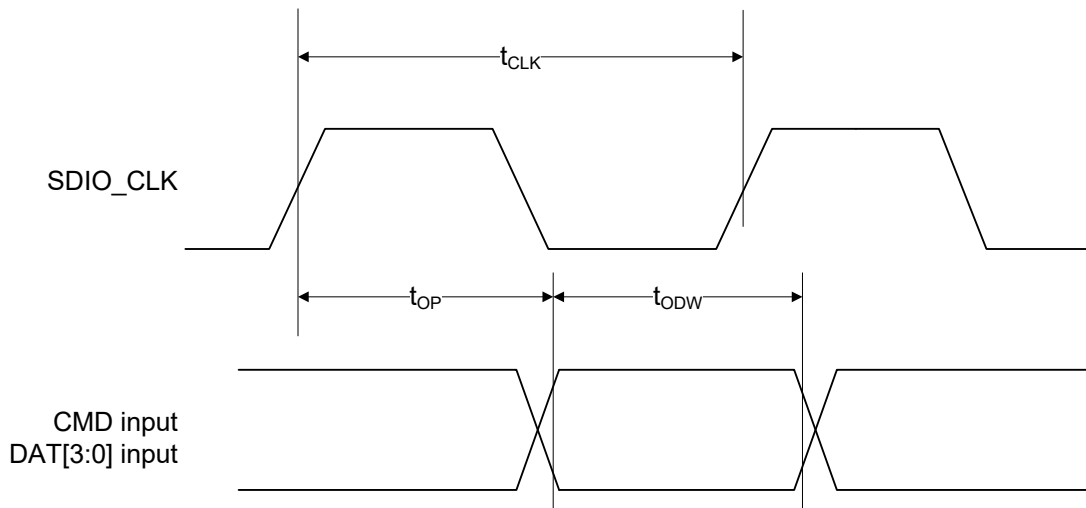
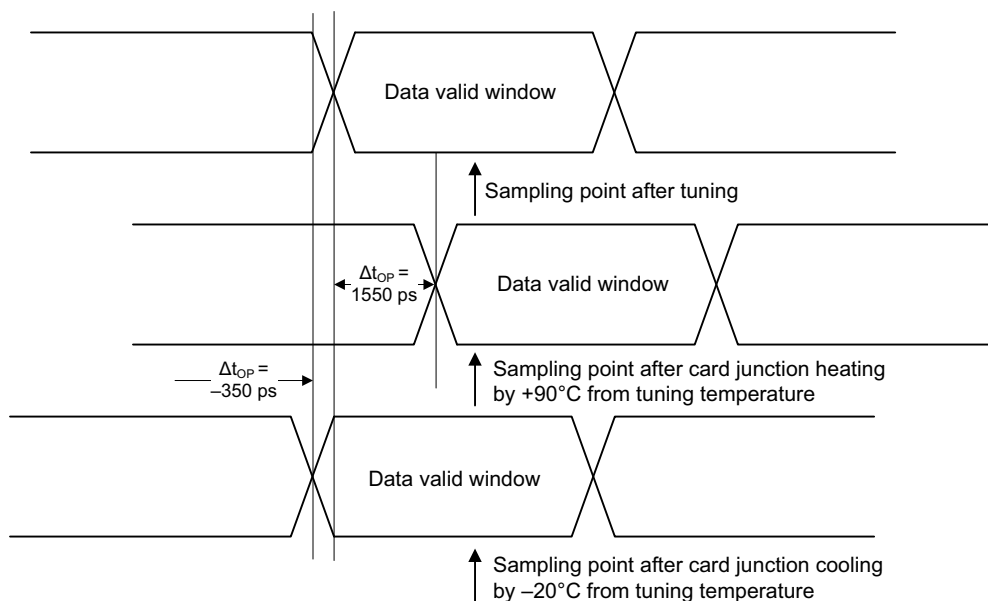


Table 56. SDIO Bus Output Timing Parameters (SDR Modes 100 MHz to 208 MHz)

| Symbol          | Min  | Max   | Unit | Comments  |
|-----------------|------|-------|------|---|
| $t_{OP}$        | 0    | 2     | UI   | Card output phase                               |
| $\Delta t_{OP}$ | -350 | +1550 | ps   | Delay variation due to temp change after tuning |
| $t_{ODW}$       | 0.60 | -     | UI   | $t_{ODW} = 2.88 \text{ ns @ 208 MHz}$           |

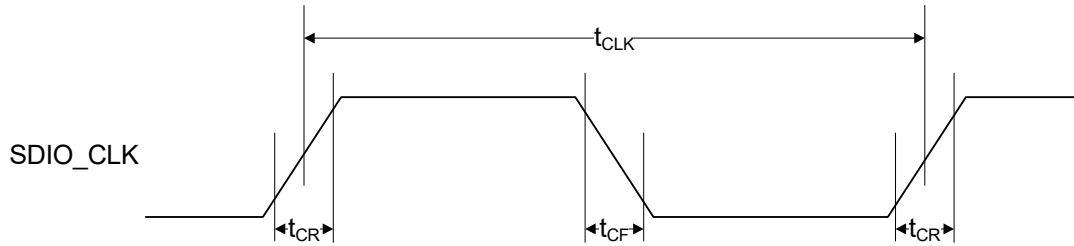
- $\Delta t_{OP} = +1550 \text{ ps}$  for junction temperature of  $\Delta t_{OP} = 90^\circ\text{C}$  during operation.
- $\Delta t_{OP} = -350 \text{ ps}$  for junction temperature of  $\Delta t_{OP} = -20^\circ\text{C}$  during operation.
- $\Delta t_{OP} = +2600 \text{ ps}$  for junction temperature of  $\Delta t_{OP} = -20^\circ\text{C}$  to  $+125^\circ\text{C}$  during operation.

Figure 42.  $\Delta t_{OP}$  Consideration for Variable Data Window (SDR 104 Mode)



19.1.4 SDIO Bus Timing Specifications in DDR50 Mode

**Figure 43. SDIO Clock Timing (DDR50 Mode)**



**Table 57. SDIO Bus Clock Timing Parameters (DDR50 Mode)**

| Parameter        | Symbol           | Min | Max                  | Unit | Comments   |
|------------------|------------------|-----|----------------------|------|--|
| –                | $t_{CLK}$        | 20  | –                    | ns   | DDR50 mode   |
| –                | $t_{CR}, t_{CF}$ | –   | $0.2 \times t_{CLK}$ | ns   | $t_{CR}, t_{CF} < 4.00$ ns (max) @50 MHz, $C_{CARD} = 10$ pF |
| Clock duty cycle | –                | 45  | 55                   | %    | –  |

Data Timing

Figure 44. SDIO Data Timing (DDR50 Mode)

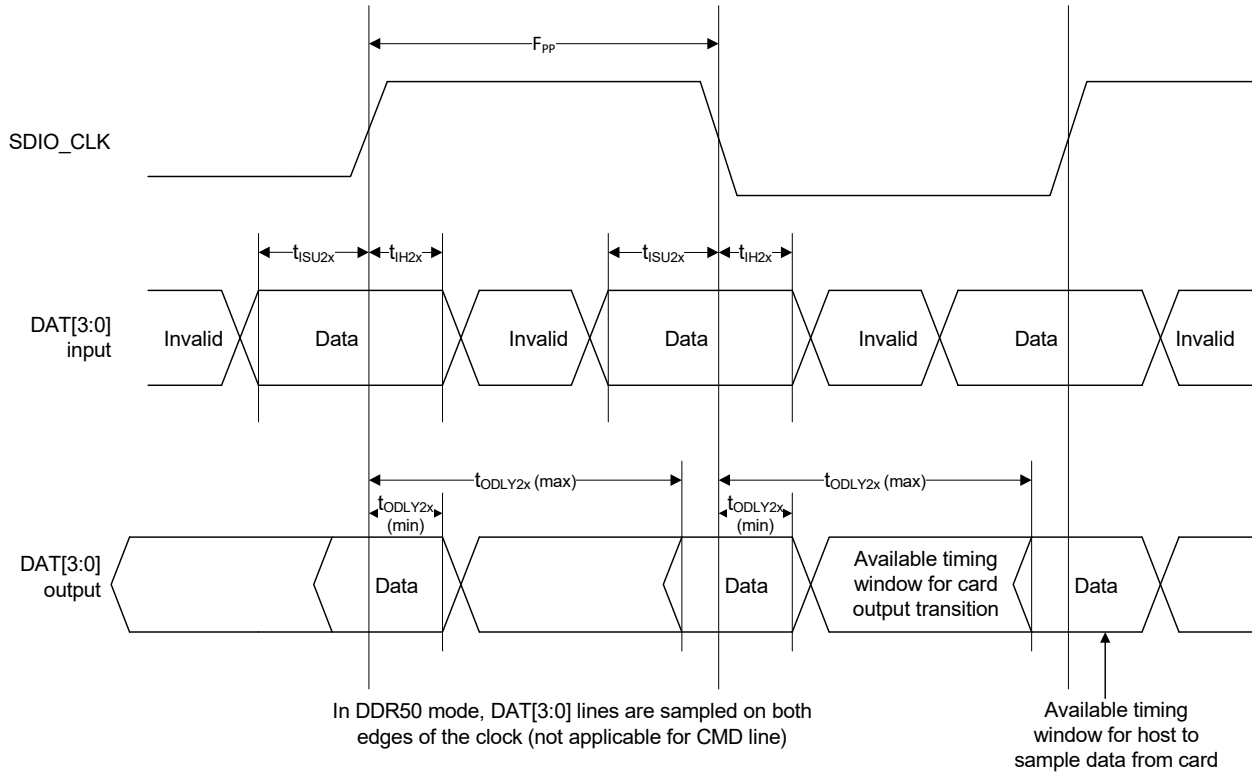


Table 58. SDIO Bus Timing Parameters (DDR50 Mode)

| Parameter         | Symbol       | Min | Max  | Unit | Comments                            |
|-------------------|--------------|-----|------|------|-------------------------------------|
| <b>Input CMD</b>  |              |     |      |      |                                     |
| Input setup time  | $t_{ISU}$    | 6   | –    | ns   | $C_{CARD} < 10 \text{ pF}$ (1 Card) |
| Input hold time   | $t_{IH}$     | 0.8 | –    | ns   | $C_{CARD} < 10 \text{ pF}$ (1 Card) |
| <b>Output CMD</b> |              |     |      |      |                                     |
| Output delay time | $t_{ODLY}$   | –   | 13.7 | ns   | $C_{CARD} < 30 \text{ pF}$ (1 Card) |
| Output hold time  | $t_{OH}$     | 1.5 | –    | ns   | $C_{CARD} < 15 \text{ pF}$ (1 Card) |
| <b>Input DAT</b>  |              |     |      |      |                                     |
| Input setup time  | $t_{ISU2x}$  | 3   | –    | ns   | $C_{CARD} < 10 \text{ pF}$ (1 Card) |
| Input hold time   | $t_{IH2x}$   | 0.8 | –    | ns   | $C_{CARD} < 10 \text{ pF}$ (1 Card) |
| <b>Output DAT</b> |              |     |      |      |                                     |
| Output delay time | $t_{ODLY2x}$ | –   | 7.5  | ns   | $C_{CARD} < 25 \text{ pF}$ (1 Card) |
| Output hold time  | $t_{ODLY2x}$ | 1.5 | –    | ns   | $C_{CARD} < 15 \text{ pF}$ (1 Card) |

### 19.2 JTAG Timing

Table 59. JTAG Timing Characteristics

| Signal Name | Period | Output Maximum | Output Minimum | Setup | Hold |
|-------------|--------|----------------|----------------|-------|------|
| TCK         | 125 ns | –              | –              | –     | –    |
| TDI         | –      | –              | –              | 20 ns | 0 ns |
| TMS         | –      | –              | –              | 20 ns | 0 ns |
| TDO         | –      | 100 ns         | 0 ns           | –     | –    |
| JTAG_TRST   | 250 ns | –              | –              | –     | –    |

### 19.3 SWD Timing

The probe outputs data to SWDIO on the falling edge of SWDCLK and captures data from SWDIO on the rising edge of SWDCLK. The target outputs data to SWDIO on the rising edge of SWDCLK and captures data from SWDIO on the rising edge of SWDCLK. SWD timing is defined through the combination of Figure 45 and Table 60.

Figure 45. SWD Read and Write Timing

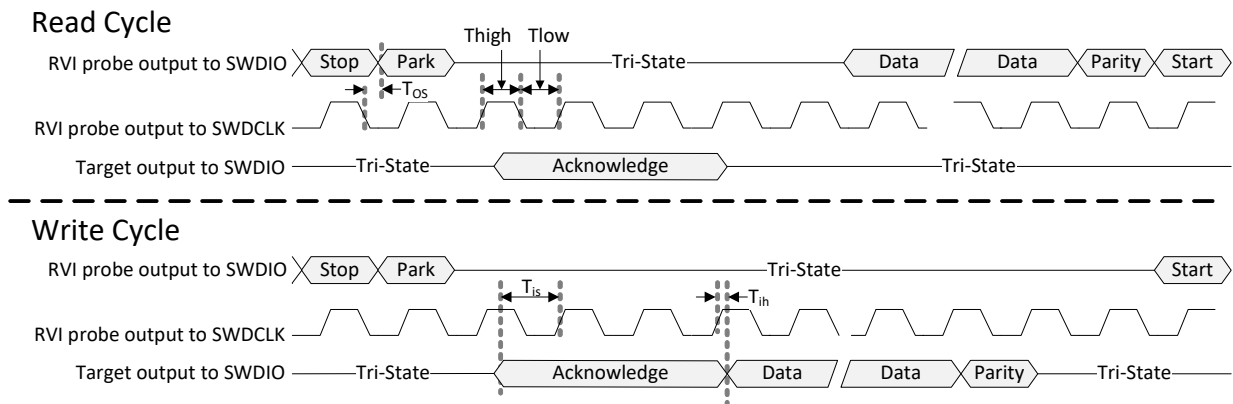


Table 60. SWD Read and Write Timing Parameters

| Parameter  | Description  | Min | Max | Unit |
|------------|--|-----|-----|------|
| $T_{cyc}$  | SWDCLK cycle time  | 125 | –   | ns   |
| $T_{high}$ | SWDCLK high period   | 50  | –   | ns   |
| $T_{low}$  | SWDCLK low period  | 50  | –   | ns   |
| $T_{os}$   | SWDIO output skew to the falling edge of SWDCLK              | –5  | 5   | ns   |
| $T_{is}$   | Input setup time between SWDIO and the rising edge of SWDCLK | 20  | –   | ns   |
| $T_{ih}$   | Input hold time between SWDIO and the rising edge of SWDCLK  | 0   | 100 | ns   |

## 20. Power-Up Sequence and Timing

### 20.1 Sequencing of Reset and Regulator Control Signals

The CYW4373E has two signals that allow the host to control power consumption by enabling or disabling the Bluetooth, WLAN, and internal regulator blocks. These signals are described below. Additionally, diagrams are provided to indicate proper sequencing of the signals for various operational states (see [Figure 46](#), [Figure 47](#), [Figure 48](#), and [Figure 49](#)). The timing values indicated are minimum required values; longer delays are also acceptable.

#### 20.1.1 Description of Control Signals

- **WL\_REG\_ON**: Used by the PMU to power-up the WLAN section. It is also OR-gated with the BT\_REG\_ON input to control the internal CYW4373E regulators. When this pin is high, the regulators are enabled and the WLAN section is out of reset. When this pin is low the WLAN section is in reset. If both the BT\_REG\_ON and WL\_REG\_ON pins are low, the regulators are disabled.
- **BT\_REG\_ON**: Used by the PMU (OR-gated with WL\_REG\_ON) to power-up the internal CYW4373E regulators. If both the BT\_REG\_ON and WL\_REG\_ON pins are low, the regulators are disabled. When this pin is low and WL\_REG\_ON is high, the BT section is in reset.

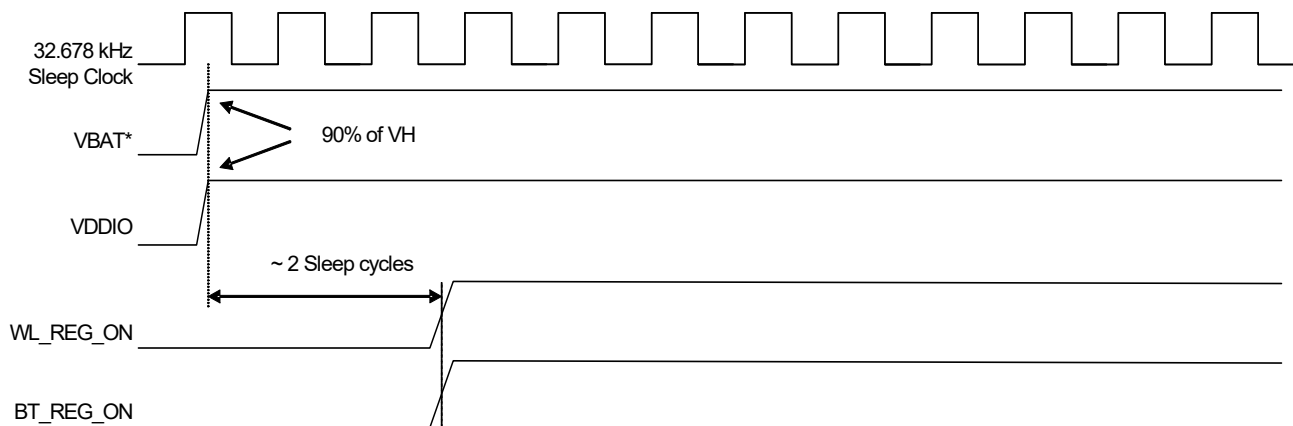
**Note:** For both the WL\_REG\_ON and BT\_REG\_ON pins, there should be at least a 10 ms time delay between consecutive toggles (where both signals have been driven low). This is to allow time for the CBUCK regulator to discharge. If this delay is not followed, then there may be a VDDIO in-rush current on the order of 36 mA during the next PMU cold start.

**Note:** The CYW4373E has an internal power-on reset (POR) circuit. The device will be held in reset for a maximum of 110 ms after VDDC and VDDIO have both passed the POR threshold. Wait at least 150 ms after VDDC and VDDIO are available before initiating SDIO accesses.

**Note:** VBAT should not rise 10%–90% faster than 40 microseconds. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

#### 20.1.2 Control Signal Timing Diagrams

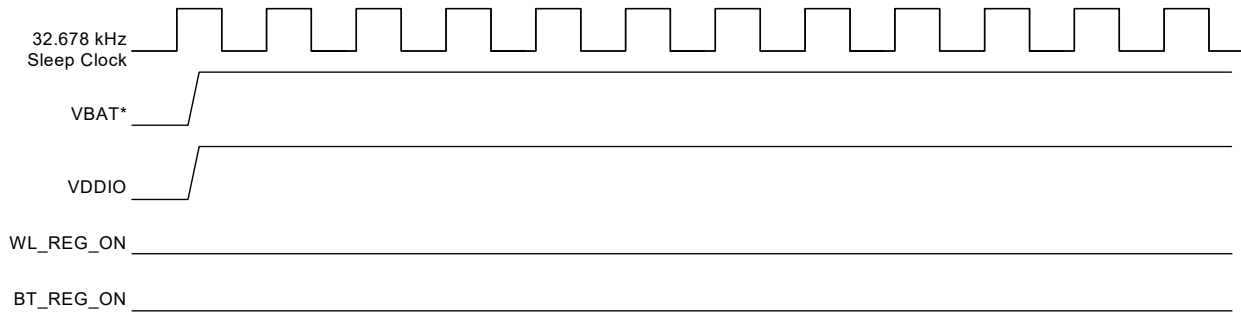
Figure 46. WLAN = ON, Bluetooth = ON



**\*Notes:**

1. VBAT should not rise 10%–90% faster than 40 microseconds.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

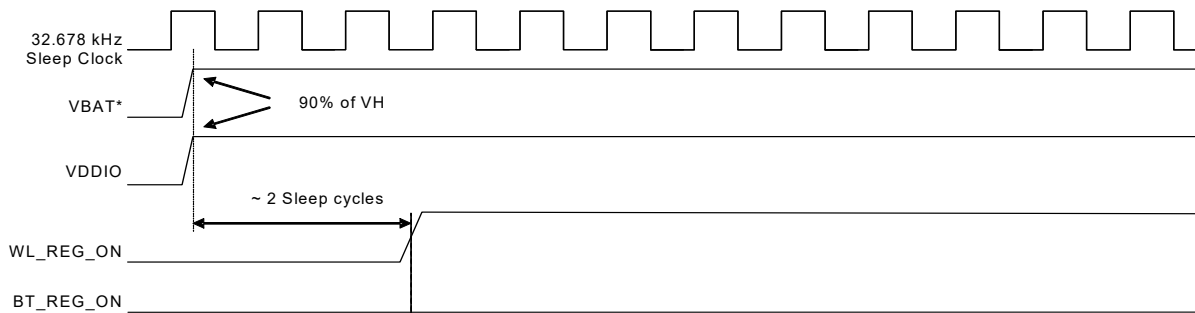
**Figure 47. WLAN = OFF, Bluetooth = OFF**



**\*Notes:**

1. VBAT should not rise 10%–90% faster than 40 microseconds.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

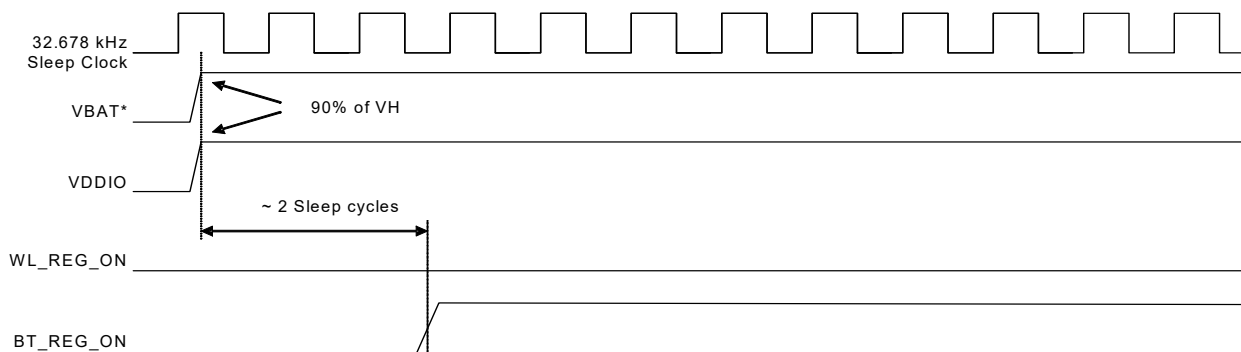
**Figure 48. WLAN = ON, Bluetooth = OFF**



**\*Notes:**

1. VBAT should not rise 10%–90% faster than 40 microseconds.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

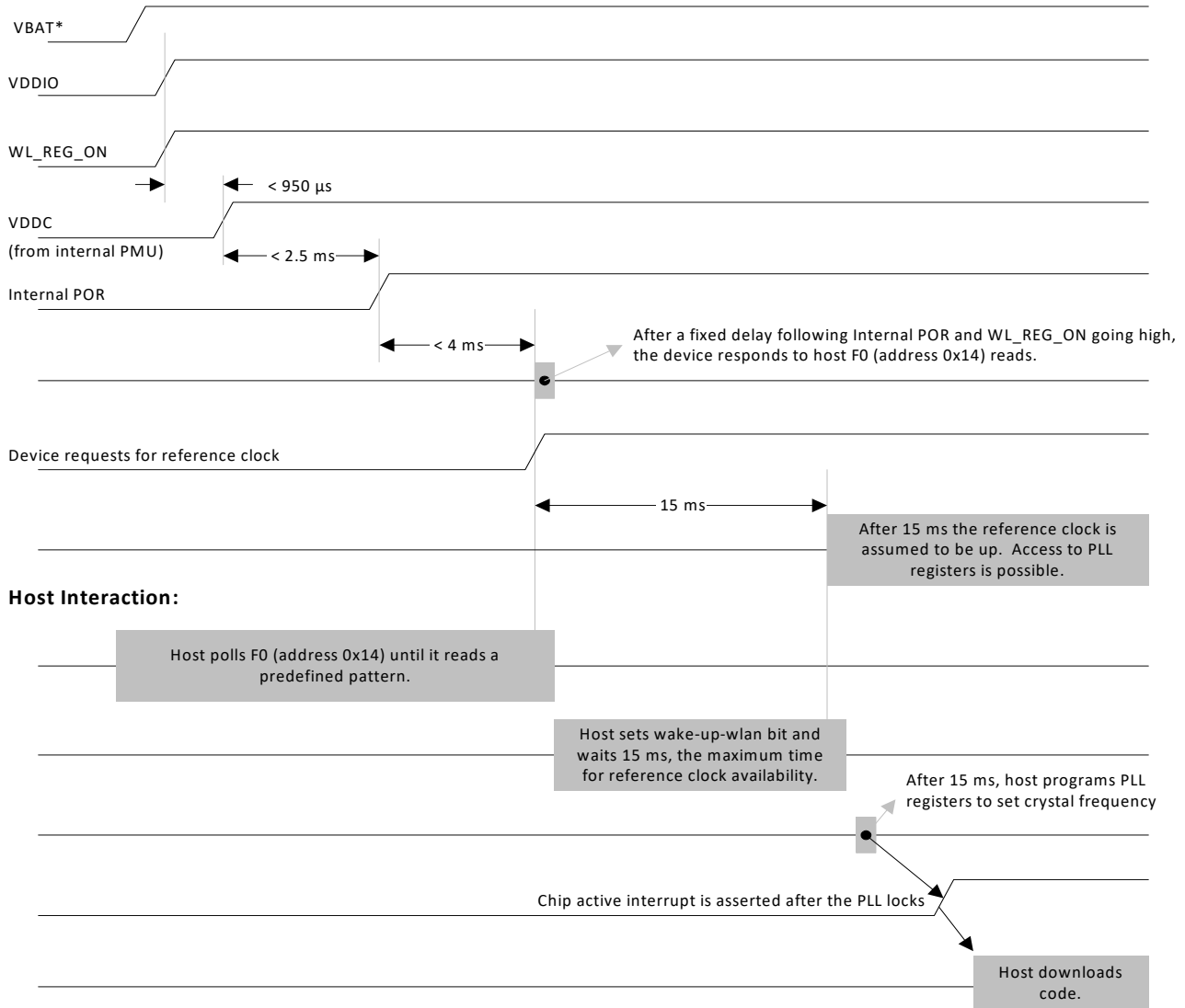
**Figure 49. WLAN = OFF, Bluetooth = ON**



**\*Notes:**

1. VBAT should not rise 10%–90% faster than 40 microseconds.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

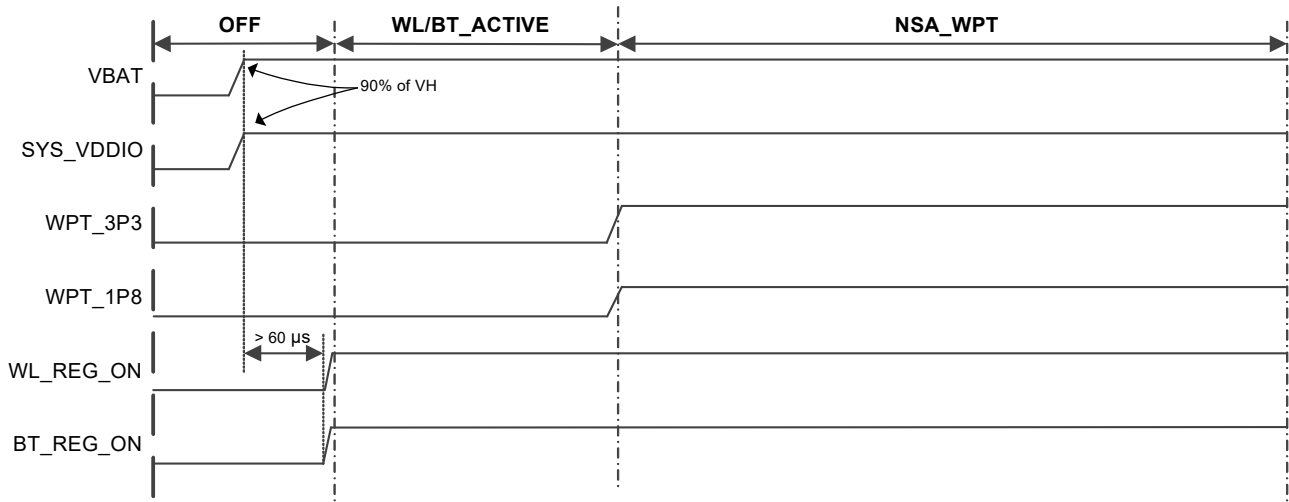
**Figure 50. WLAN Boot-Up Sequence for SDIO Host**



**\*Notes:**

1. VBAT and VDDIO should not rise 10%–90% faster than 40 microseconds.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

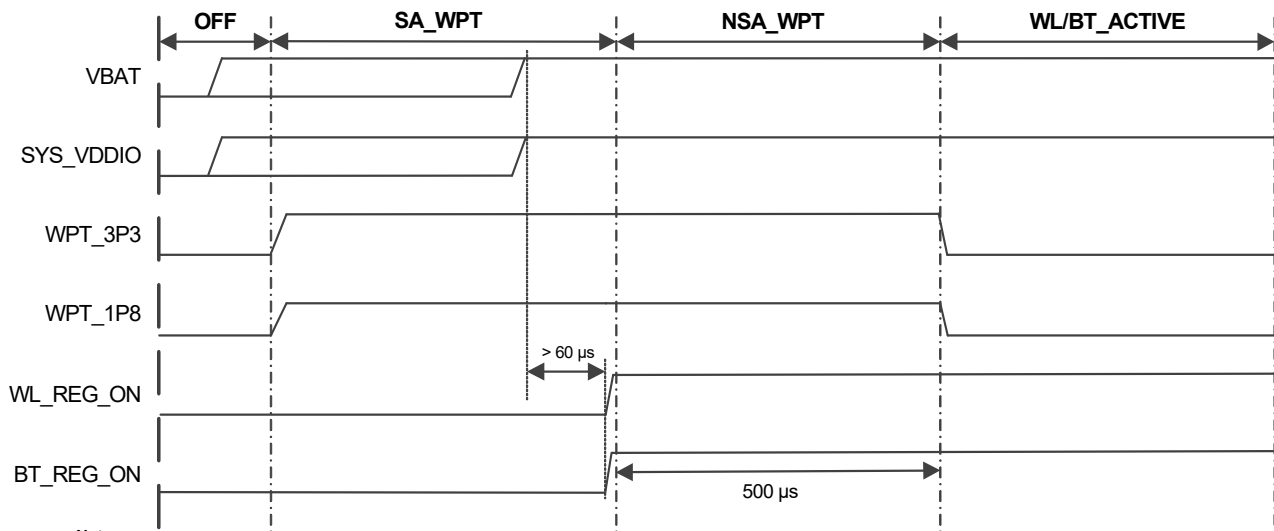
Figure 51. VBAT to WPT



Notes:

1. VBAT, SYS\_VDDIO, WPT\_1P8, and WPT\_3P3 should not rise 10%–90% faster than 40  $\mu$ s.

Figure 52. WPT to VBAT



Notes:

1. VBAT, SYS\_VDDIO, WPT\_1P8, and WPT\_3P3 should not rise 10%–90% faster than 40  $\mu$ s.
2. Maintain 500  $\mu$ s of NSA transition mode if PMU is needed from SA mode to Active mode.
3. WL\_REG\_ON should be asserted only when VBAT is stable.



## 21. Package Information

This document provides simulated thermal data in JEDEC tests for CYW4373E in 128-WLBGA 4.51x5.43 package.

### 21.1 Package Thermal Characteristics

The information in [Table 61](#) is based on the following conditions:

- No external heat sink,  $T_A = 85^\circ\text{C}$ . This is an estimate, based on a 6-layer PCB designed specifically for 4343E (CYW4343E WLSPD). Power is 1.05 watts.
- Absolute junction temperature limits are maintained through active thermal monitoring or turning off one of the TX chains, or both.

**Table 61. WLBGA Package Thermal Characteristics**

| Characteristic   | WLBGA |
|--|-------|
| $\theta_{JA}$ ( $^\circ\text{C}/\text{W}$ ) (value in still air) | 37.75 |
| $\theta_{JB}$ ( $^\circ\text{C}/\text{W}$ )                      | 5.90  |
| $\theta_{JC}$ ( $^\circ\text{C}/\text{W}$ )                      | 4.48  |
| $\Psi_{JT}$ ( $^\circ\text{C}/\text{W}$ )                        | 11.50 |
| $\Psi_{JB}$ ( $^\circ\text{C}/\text{W}$ )                        | 22.50 |
| Maximum Junction Temperature $T_j$ ( $^\circ\text{C}$ )          | 139.3 |
| Maximum Power Dissipation (W)                                    | 1.84  |

### 21.2 Junction Temperature Estimation and $\Psi_{JT}$ Versus $\theta_{JC}$

Package thermal characterization parameter  $\Psi_{JT}$  yields a better estimation of actual junction temperature ( $T_j$ ) versus using the junction-to-case thermal resistance parameter  $\theta_{JC}$ . The reason for this is that  $\theta_{JC}$  assumes that all the power is dissipated through the top surface of the package case. In actual applications, some of the power is dissipated through the bottom and sides of the package.  $\Psi_{JT}$  takes into account power dissipated through the top, bottom, and sides of the package. The equation for calculating the device junction temperature is:

$$T_j = T_T + P \times \Psi_{JT}$$

Where:

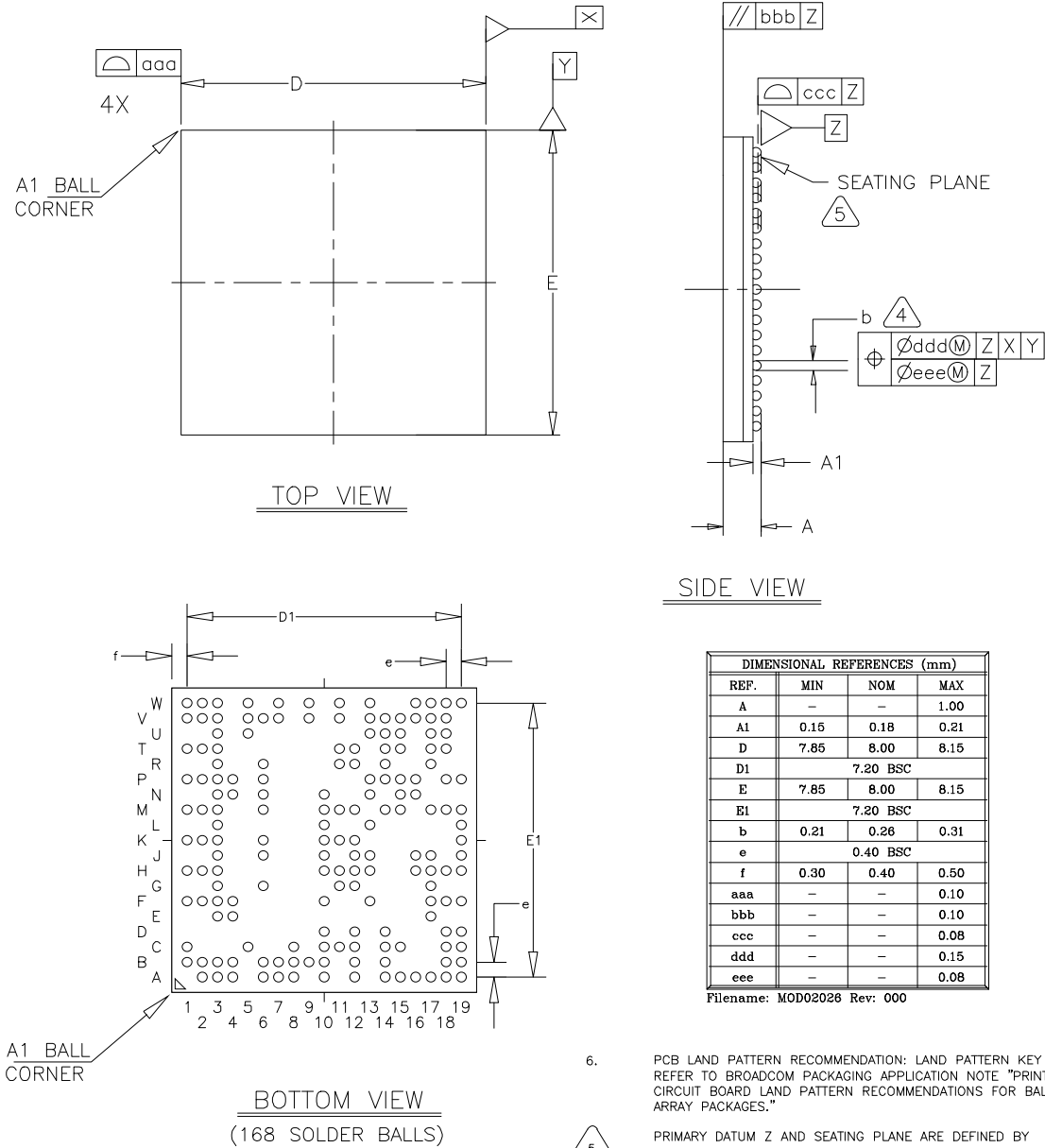
- $T_j$  = Junction temperature at steady-state condition ( $^\circ\text{C}$ )
- $T_T$  = Package case top center temperature at steady-state condition ( $^\circ\text{C}$ )
- $P$  = Device power dissipation (Watts)
- $\Psi_{JT}$  = Package thermal characteristics; no airflow ( $^\circ\text{C}/\text{W}$ )

### 21.3 Environmental Characteristics

For environmental characteristics data, see [Table 25 "Environmental Ratings"](#).

**22. Mechanical Information**

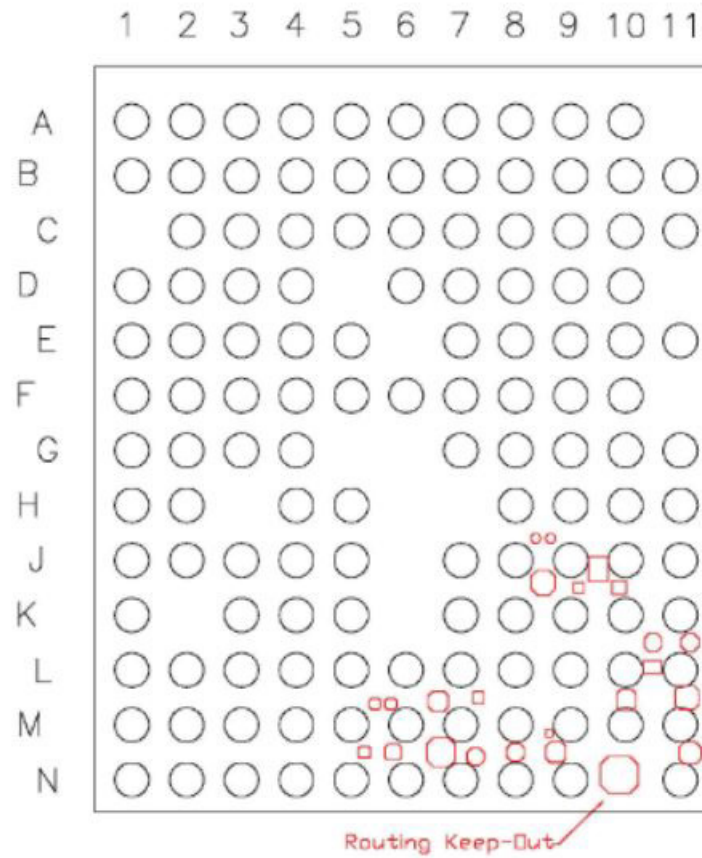
**Figure 53. 128-Ball WLBGA Package Mechanical Information**



6. PCB LAND PATTERN RECOMMENDATION: LAND PATTERN KEY A REFER TO BROADCOM PACKAGING APPLICATION NOTE "PRINTED CIRCUIT BOARD LAND PATTERN RECOMMENDATIONS FOR BALL GRID ARRAY PACKAGES."
5. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
3. THE BASIC SOLDER BALL GRID PITCH IS 0.40mm
  2. THIS PACKAGE CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034.
  1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

**Figure 54. 128-Balls WLBGA Keep-out Areas for PCB Layout—Top View with Balls Facing Down**

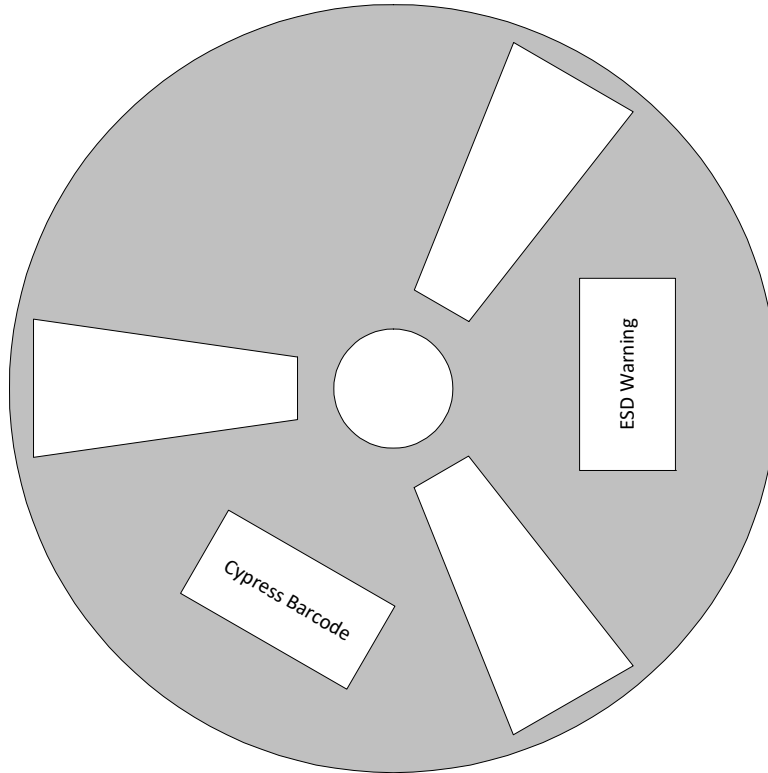


**Note:** No top-layer metal is allowed in keep-out areas.

**Note:** A DXF file for the WLBGA keep-out area is available for importation into a layout program. Contact your Cypress FAE for more information.

**22.1 Tape, Reel, and Packing Specification**

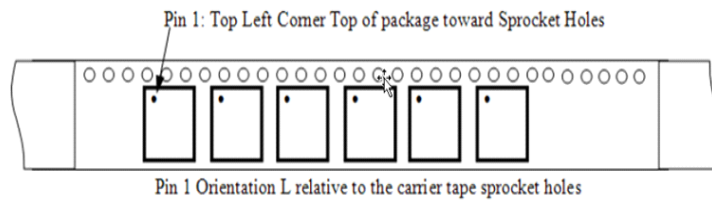
**Figure 55. Reel, Labeling and Packaging**



**Reel Diameter: 330 +/- 2.0 mm**

**Device Orientation/Mix Lot Number**

Each reel may contain up to three lot numbers, independent of the date code. Individual lots must be labeled on the box, moisture barrier bag, and the reel.



## 23. Ordering Information

**Table 62. Part Ordering Information**

| Part Number  | Package  | Description  | Operating Ambient Temperature |
|--------------|--|--|-------------------------------|
| CYW4373EUBGT | 128-ball WLBGA<br>(4.51 mm x 5.43mm x 0.4mm pitch) | Dual-band 2.4GHz and 5GHz WLAN and Bluetooth 5.0. Industrial quality level | -40°C to +85°C                |

## 24. Additional Information

### 24.1 Acronyms and Abbreviations

In most cases, acronyms and abbreviations are defined upon first use. For a more complete list of acronyms and other terms used in Cypress documents, go to: <http://www.cypress.com/glossary>.

### 24.2 References

The references in this section may be used in conjunction with this document.

**Note:** Cypress provides customer access to technical documentation and software through its Customer Support Portal (CSP) and Downloads & Support site (see [IoT Resources](#)).

| Document (or Item) Name  | Number | Source                          |
|--|--------|---------------------------------|
| [1] Bluetooth MWS Coexistence 2-wire Transport Interface Specification | –      | <a href="#">Wiced-bluetooth</a> |

### 24.3 IoT Resources

Cypress provides a wealth of data at <http://www.cypress.com/internet-things-iot> to help you to select the right IoT device for your design, and quickly and effectively integrate the device into your design. Cypress provides customer access to a wide range of information, including technical documentation, schematic diagrams, product bill of materials, PCB layout information, and software updates. Customers can acquire technical documentation and software from the Cypress Support Community website (<https://community.cypress.com/>).

**Document History**

| Document Title: CYW4373E Single-Chip Dual Band WiFi IEEE 802.11ac a/b/g/n MAC/Baseband/Radio with Bluetooth 5.0 for Industrial Applications |         |                 |   |
|---|---------|-----------------|---|
| Document Number: 002-30330  |         |                 |   |
| Revision  | ECN     | Submission Date | Description of Change   |
| **  | 6900667 | 07/09/2020      | Initial release   |
| *A  | 6999222 | 10/21/2020      | Updated <a href="#">External 32.768 kHz Low-Power Oscillator</a> section.<br>Updated <a href="#">Table 33</a> and <a href="#">Table 35</a> (Decreased 1dB at TX PWR(only Min. Power) over 2GHz/5GHz except DSSS modulation at 2GHz).<br>Updated the footnote in <a href="#">Table 51</a> and <a href="#">Table 52</a> . |

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